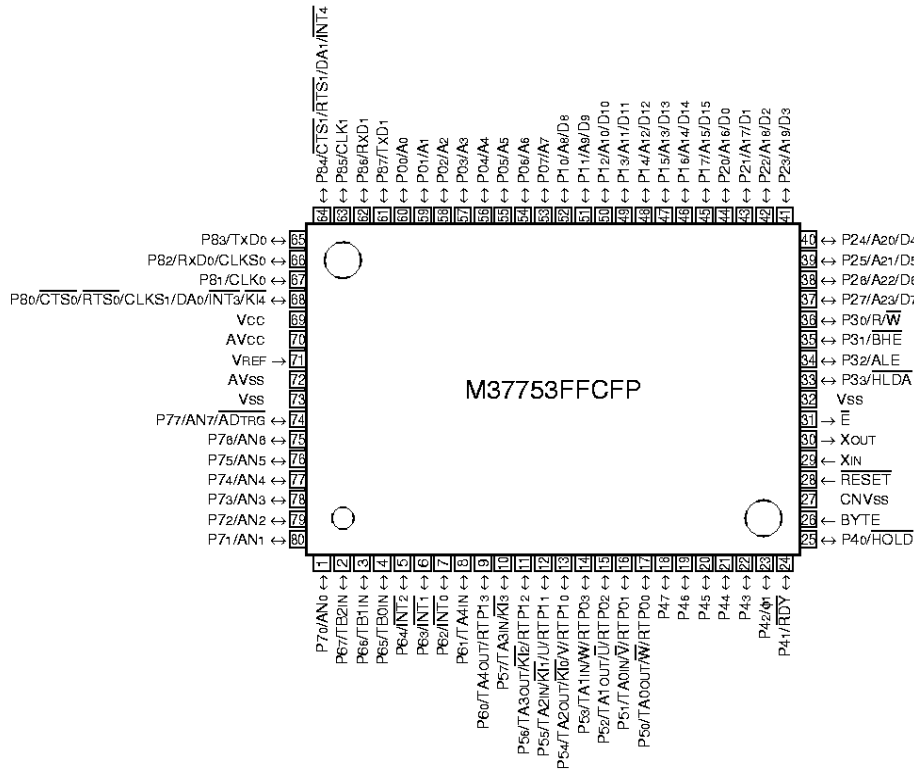


PRELIMINARY
 Notice: This is not a final specification.
 Some parametric limits are subject to change.

M37753FFCFP
M37753FFCHP

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

M37753FFCFP PIN CONFIGURATION (TOP VIEW)



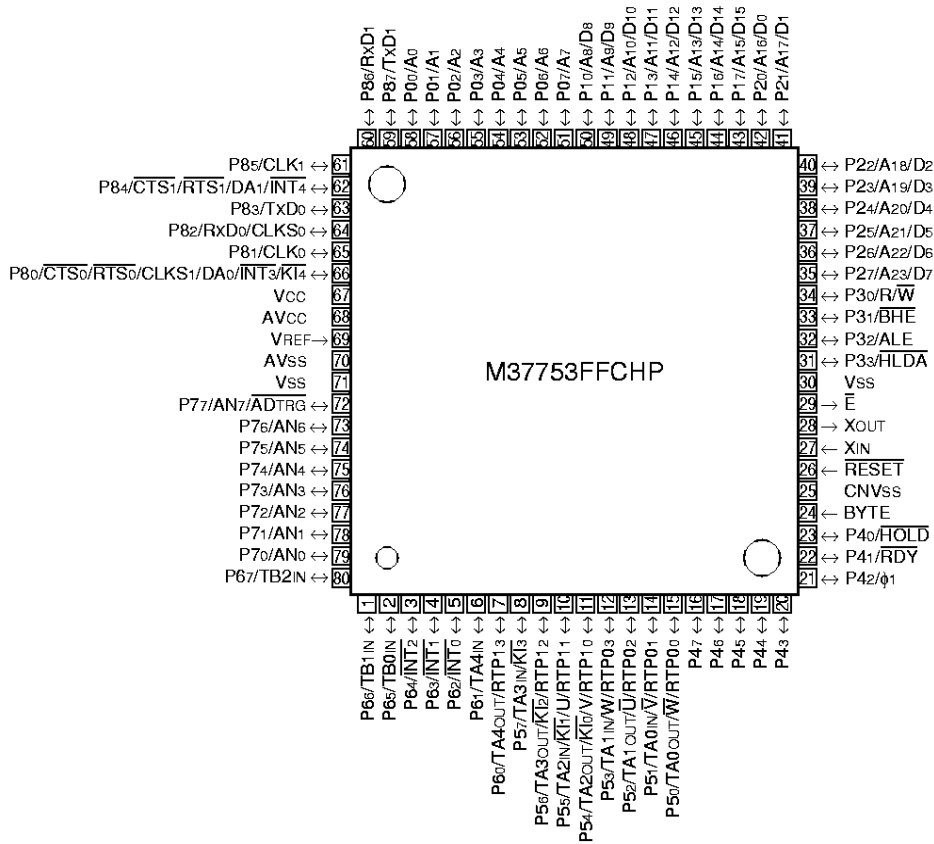
Outline 80P6N-A

PRELIMINARY
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M37753FFCFP
M37753FFCHP

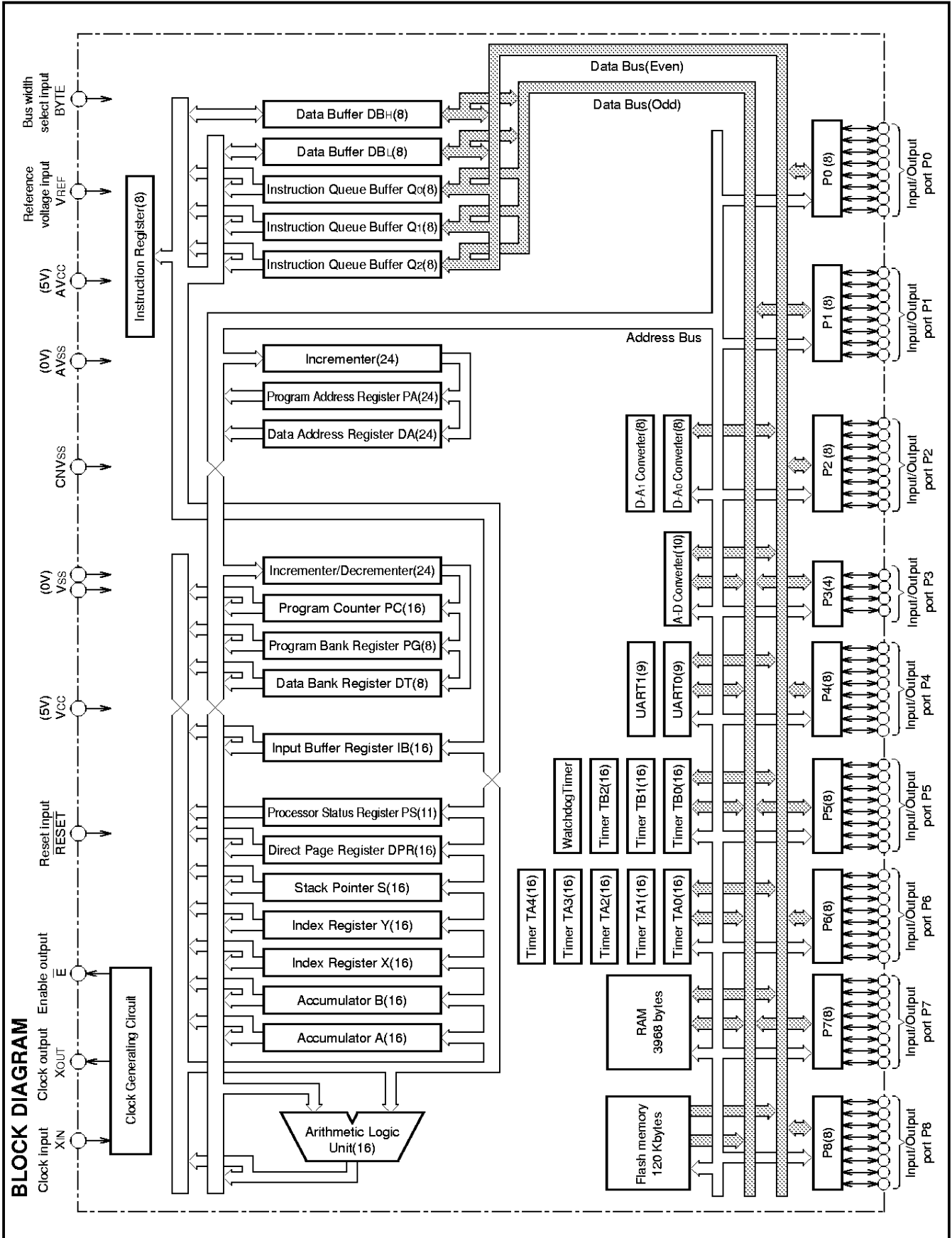
SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

M37753FFCHP PIN CONFIGURATION (TOP VIEW)



Outline 80P6Q-A

PRELIMINARY
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SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

FUNCTIONS (Microcomputer mode)

Parameter		Functions
Number of basic machine instructions		109 (103 basic instructions of 7700 Family + 6 special instructions)
Instruction execution time		100 ns (the fastest instruction at external clock 40 MHz frequency)
Memory size	Flash memory	120 Kbytes
	RAM	3968 bytes
Input/Output ports	P0–P2, P4–P8	8-bit × 8
	P3	4-bit × 1
Multiple-function timers	TA0, TA1, TA2, TA3, TA4	16-bit × 5
	TB0, TB1, TB2	16-bit × 3
Serial I/O		(UART or clock synchronous serial I/O) × 2
A-D converter		10-bit × 1(8 channels)
D-A converter		8-bit × 2
Watchdog timer		12-bit × 1
Dead-time timer		8-bit × 3
Interrupts		5 external types, 16 internal types (Each interrupt can be set to priority levels 0 – 7.)
Clock generating circuit		Built-in (externally connected to a ceramic resonator or quartz crystal resonator)
Supply voltage		5 V ± 10 %
Power dissipation		125 mW (at external clock 40 MHz frequency)
Input/Output characteristic	Input/Output withstand voltage	5 V
	Output current	5 mA
Memory expansion		Maximum 16 Mbytes
Operating temperature range		–20 to 85 °C
Device structure		CMOS high-performance silicon gate process
Package		80-pin plastic molded QFP

FUNCTIONS (Flash memory mode)

Parameter		Functions
Supply voltage		5 V ± 10 %
Program/Erase voltage		12 V ± 5 %
Flash memory mode		3 modes (parallel I/O, serial I/O, CPU reprogramming)
Programming method	Parallel I/O mode	Programming in unit of byte/120 Kbytes
	Serial I/O mode	Programming in unit of byte/120 Kbytes
	CPU reprogramming mode	Programming in unit of byte/112 Kbytes
Erasing method	Parallel I/O mode	Batch erasing/120 Kbytes
	Serial I/O mode	Batch erasing/120 Kbytes
	CPU reprogramming mode	Batch erasing/112 Kbytes or 2-division-block erasing 2-division-block erasing: 56-Kbyte area to be erased is selectable.
Program/Erase control method		Program/Erase control by software command
Command number	Parallel I/O mode	7 commands
	Serial IO mode	7 commands
	CPU reprogramming mode	7 commands
Number of times for Program/Erase		100

PRELIMINARY
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SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

PIN DESCRIPTION (MICROCOMPUTER MODE)

Pin	Name	Input/Output	Functions
VCC, VSS	Power supply		Supply 5 V±10 % to VCC and 0 V to VSS.
CNVSS	CNVSS input	Input	This pin controls the processor mode. Connect to VSS for single-chip mode or memory expansion mode. Connect to VCC for microprocessor mode.
RESET	Reset input	Input	This is reset input pin. The microcomputer is reset when supplying "L" level to this pin.
XIN	Clock input	Input	These are I/O pins of internal clock generating circuit. Connect a ceramic or quartz-crystal resonator between XIN and XOUT. When an external clock is used, the clock source should be connected to the XIN pin and the XOUT pin should be left open.
XOUT	Clock output	Output	
\bar{E}	Enable output	Output	Data or instruction read, data write are performed when output from this pin is "L".
BYTE (Note)	Bus width select input	Input	This pin determines whether the external data bus is 8-bit width or 16-bit width for memory expansion mode or microprocessor mode. The width is 16 bits when "L" signal inputs and 8 bits when "H" signal inputs.
AVCC, AVSS	Analog supply input		Power supply for the A-D converter and the D-A converter. Connect AVCC to VCC and AVSS to VSS externally.
VREF	Reference voltage input	Input	This is reference voltage input pin for the A-D converter and the D-A converter.
P00–P07	I/O port P0	I/O	In single-chip mode, port P0 is an 8-bit I/O port. This port has an I/O direction register and each pin can be programmed for input or output. These ports are in the input mode when reset. Address (A0–A7) is output in memory expansion mode or microprocessor mode.
P10–P17	I/O port P1	I/O	In single-chip mode, these pins have the same functions as port P0. When the BYTE pin is set to "L" in memory expansion mode or microprocessor mode and external data bus is 16-bit width, high-order data (D8–D15) is input or output if \bar{E} output is "L" and an address (A8–A15) is output if \bar{E} output is "H". When the BYTE pin is set to "H" and an external data bus is 8-bit width, only address (A8–A15) is output.
P20–P27	I/O port P2	I/O	In single-chip mode, these pins have the same functions as port P0. In memory expansion mode or microprocessor mode, low-order data (D0–D7) is input or output when \bar{E} output is "L" and an address (A16–A23) is output when \bar{E} output is "H".
P30–P33	I/O port P3	I/O	In single-chip mode, these pins have the same functions as port P0. In memory expansion mode or microprocessor mode, R/W, BHE, ALE, and HLDA signals are output.
P40–P47	I/O port P4	I/O	In single-chip mode, these pins have the same functions as port P0. In memory expansion mode or microprocessor mode, P40, P41, and P42 become HOLD and RDY input pins, and clock ϕ_1 output pin respectively. Functions of other pins are the same as in single-chip mode. In memory expansion mode, P42 can be programmed as I/O port.
P50–P57	I/O port P5	I/O	In addition to having the same functions as port P0 in single-chip mode, these pins also function as I/O pins for timer A0, timer A1, timer A2, timer A3, output pins for motor drive waveform, and input pins for key input interrupt.
P60–P67	I/O port P6	I/O	In addition to having the same functions as port P0 in single-chip mode, these pins also function as the I/O pin for timer A4, input pins for external interrupt input INT0, INT1, and INT2, and input pins for timer B0, timer B1, and timer B2, and output pin for motor drive waveform.
P70–P77	I/O port P7	I/O	In addition to having the same functions as port P0 in single-chip mode, these pins also function as input pins for A-D converter.
P80–P87	I/O port P8	I/O	In addition to having the same functions as port P0 in single-chip mode, these pins also function as I/O pins for UART0, UART1, output pins for D-A converter, and input pins for INT3, INT4.

Note: It is impossible to change the input level of the BYTE pin in each bus cycle. In other words, bus width cannot be switched dynamically. Fix the input level of the BYTE pin to "H" or "L" according to the bus width used.

PRELIMINARY
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SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

PIN DESCRIPTION (FLASH MEMORY PARALLEL I/O MODE)

Pin	Name	Input /Output	Functions
VCC, VSS	Power supply	—	Supply 5 V ± 10 % to VCC and 0 V to VSS.
CNVSS	VPP input	Input	Connect to 5 V ± 10 % in read-only mode, connect to 12 V ± 5 % in read/write mode.
BYTE	Bus width select input	Input	Connect to VSS.
RESET	Reset input	Input	Connect to VSS.
XIN	Clock input	Input	Connect a ceramic resonator between XIN and XOUT.
XOUT	Clock output	Output	
\bar{E}	Enable output	Output	Keep it open.
AVCC, AVSS	Analog supply input	—	Connect AVCC to VCC and AVSS to VSS.
VREF	Reference voltage input	Input	Connect to VSS.
P00–P07	Address input (A0–A7)	Input	Port P0 functions as 8-bit address input (A0–A7).
P10–P17	Address input (A8–A15)	Input	Port P1 functions as 8-bit address input (A8–A15).
P20–P27	Data I/O (D0–D7)	I/O	Function as 8-bit data's I/O pins (D0–D7).
P30–P33	Input port P3	Input	Connect to VSS.
P40–P47	Input port P4	Input	Keep P42 open. Connect P40, P41, P43–P47 to VSS.
P50–P57	Control signal input	Input	P50, P51 and P52 function as the WE, OE and CE input pins respectively. P54 functions as the A16 input pin. Connect P53 to VCC. Connect P55, P56 and P57 to VSS.
P60–P67	Input port P6	Input	Connect to VSS.
P70–P77	Input port P7	Input	Connect to VSS.
P80–P87	Input port P8	Input	Connect to VSS.

PRELIMINARY
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PIN DESCRIPTION (FLASH MEMORY SERIAL I/O MODE)

Pin	Name	Input /Output	Functions
VCC, VSS	Power supply	—	Supply 5 V ± 10 % to VCC and 0 V to VSS.
CNVSS	VPP input	Input	Connect to 12 V ± 5 %.
BYTE	Bus width select input	Input	Connect to VSS or VCC.
RESET	Reset input	Input	Connect to VSS.
XIN	Clock input	Input	Connect a ceramic resonator between XIN and XOUT.
XOUT	Clock output	Output	
\bar{E}	Enable output	Output	"H" is output.
AVCC, AVSS	Analog supply input	—	Connect AVCC to VCC and AVSS to VSS.
VREF	Reference voltage input	Input	Input an arbitrary level between the range of VSS and VCC.
P00–P07	Input port P0	Input	Input "H" or "L", or keep them open.
P10–P17	Input port P1	Input	Input "H" or "L", or keep them open.
P20–P27	Input port P2	Input	Input "H" or "L", or keep them open.
P30–P33	Input port P3	Input	Input "H" or "L", or keep them open.
P40–P43, P47	Input port P4	Input	Input "H" or "L" to P40, P41, P43, P47, or keep them open. Keep P42 open.
P44	BUSY output	Output	This pin is for BUSY signal output.
P45	SDA I/O	I/O	This pin is for serial data I/O.
P46	SCLK input	Input	This pin is for serial clock input.
P50, P52–P57	Input port P5	Input	Input "H" or "L", or keep them open.
P51	Control signal input	Input	\bar{OE} input pin
P60–P67	Input port P6	Input	Input "H" or "L", or keep them open.
P70–P77	Input port P7	Input	Input "H" or "L", or keep them open.
P80–P87	Input port P8	Input	Input "H" or "L", or keep them open.

BASIC FUNCTION BLOCKS

The M37753FFCFP and the M37753FFCHP have the same functions as the M37753M8C-XXXGP and the M37753M8C-XXXHP except for the following.

Therefore, refer to the section on the M37753M8C-XXXGP and the M37753M8C-XXXHP.

- (1) Flash memory is included instead of ROM.
- (2) The memory size is different.
- (3) The memory area modification function is different.
- (4) Part of the peripheral devices control registers is different.

(Flash memory control register, flash command register, and bits 3, 4 of particular function select register 0 are added.)

MEMORY

The memory map is shown in Figure 1.

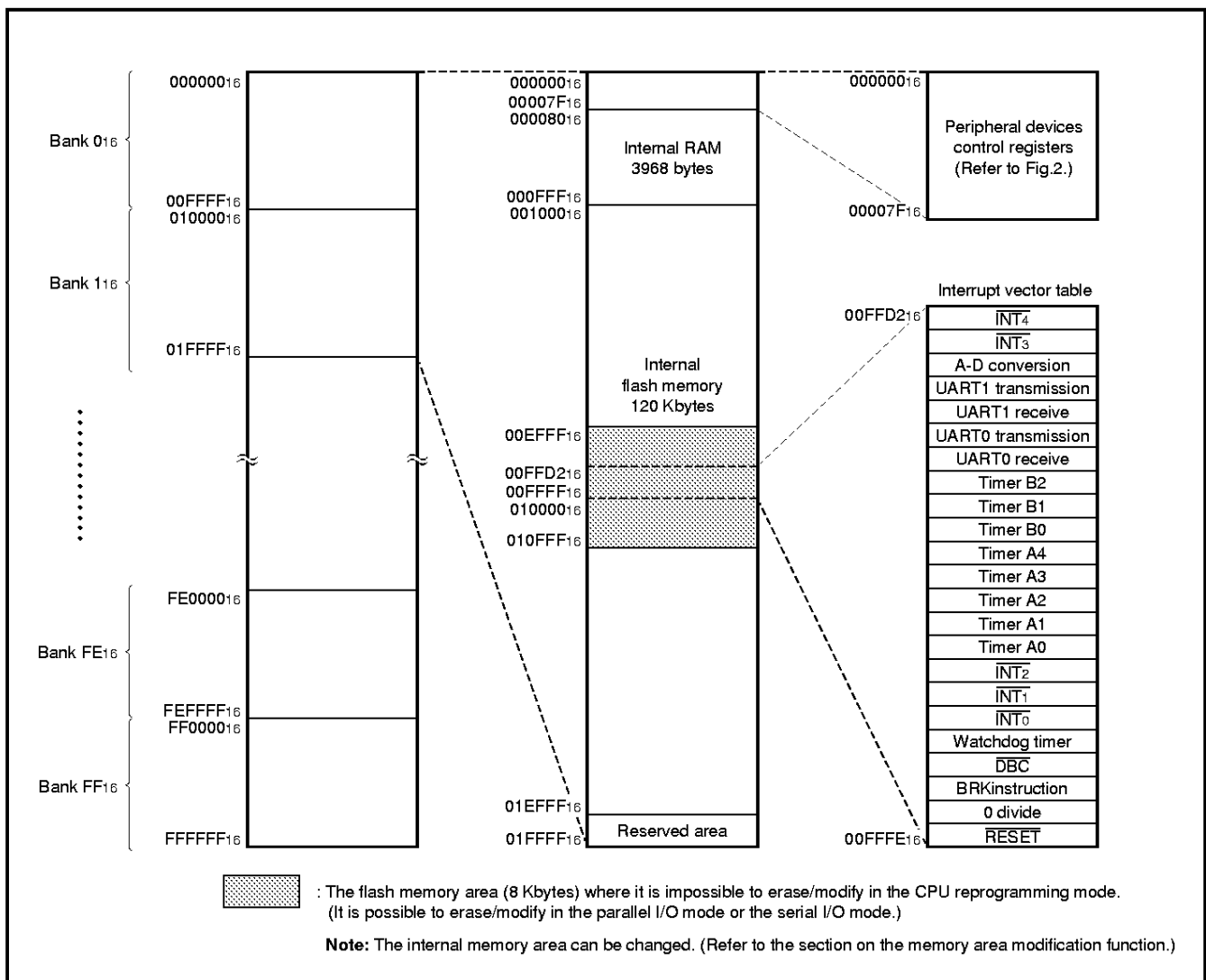


Fig. 1 Memory map

PRELIMINARY
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SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

Address (Hexadecimal notation)		Address (Hexadecimal notation)	
000000		000040	Count start register
000001		000041	
000002	Port P0 register	000042	One-shot start register
000003	Port P1 register	000043	
000004	Port P0 direction register	000044	Up-down register
000005	Port P1 direction register	000045	Timer A write flag
000006	Port P2 register	000046	Timer A0 register
000007	Port P3 register	000047	
000008	Port P2 direction register	000048	Timer A1 register
000009	Port P3 direction register	000049	
00000A	Port P4 register	00004A	Timer A2 register
00000B	Port P5 register	00004B	
00000C	Port P4 direction register	00004C	Timer A3 register
00000D	Port P5 direction register	00004D	
00000E	Port P6 register	00004E	Timer A4 register
00000F	Port P7 register	00004F	
000010	Port P6 direction register	000050	Timer B0 register
000011	Port P7 direction register	000051	
000012	Port P8 register	000052	Timer B1 register
000013		000053	
000014	Port P8 direction register	000054	Timer B2 register
000015		000055	
000016		000056	Timer A0 mode register
000017		000057	Timer A1 mode register
000018		000058	Timer A2 mode register
000019		000059	Timer A3 mode register
00001A	Waveform output mode register	00005A	Timer A4 mode register
00001B	Dead-time timer	00005B	Timer B0 mode register
00001C	Pulse output data register 1	00005C	Timer B1 mode register
00001D	Pulse output data register 0	00005D	Timer B2 mode register
00001E	A-D control register 0	00005E	Processor mode register 0
00001F	A-D control register 1	00005F	Processor mode register 1
000020		000060	Watchdog timer register
000021		000061	Watchdog timer frequency select register
000022	A-D register 1	000062	
000023		000063	
000024	A-D register 2	000064	Comparator function select register
000025		000065	Flash command register
000026	A-D register 3	000066	Comparator result register
000027		000067	Flash memory control register
000028	A-D register 4	000068	D-A register 0
000029		000069	
00002A	A-D register 5	00006A	D-A register 1
00002B		00006B	
00002C	A-D register 6	00006C	Particular function select register 0
00002D		00006D	Particular function select register 1
00002E	A-D register 7	00006E	INT ₄ interrupt control register
00002F		00006F	INT ₃ interrupt control register
000030	UART0 transmit/receive mode register	000070	A-D interrupt control register
000031	UART0 baud rate register	000071	UART0 transmit interrupt control register
000032		000072	UART0 receive interrupt control register
000033	UART0 transmit buffer register	000073	UART1 transmit interrupt control register
000034	UART0 transmit/receive control register 0	000074	UART1 receive interrupt control register
000035	UART0 transmit/receive control register 1	000075	Timer A0 interrupt control register
000036		000076	Timer A1 interrupt control register
000037	UART0 receive buffer register	000077	Timer A2 interrupt control register
000038		000078	Timer A3 interrupt control register
000039	UART1 transmit/receive mode register	000079	Timer A4 interrupt control register
00003A	UART1 baud rate register	00007A	Timer B0 interrupt control register
00003B	UART1 transmit buffer register	00007B	Timer B1 interrupt control register
00003C	UART1 transmit/receive control register 0	00007C	Timer B2 interrupt control register
00003D	UART1 transmit/receive control register 1	00007D	INT ₀ interrupt control register
00003E		00007E	INT ₁ interrupt control register
00003F	UART1 receive buffer register	00007F	INT ₂ interrupt control register

Fig. 2 Location of peripheral devices and interrupt control registers

Register Name	Address	Value	Register Name	Address	Value
Port P0 direction register	(04 ₁₆)...	00 ₁₆	Watchdog timer	(60 ₁₆)...	FFF ₁₆
Port P1 direction register	(05 ₁₆)...	00 ₁₆	Watchdog timer frequency select register	(61 ₁₆)...	XXXXXXXXXX00
Port P2 direction register	(08 ₁₆)...	0XXXXX0000	Comparator function select register	(64 ₁₆)...	00 ₁₆
Port P3 direction register	(09 ₁₆)...	XXXXXX0000	Comparator result register	(66 ₁₆)...	00 ₁₆
Port P4 direction register	(0C ₁₆)...	00 ₁₆	Flash memory control register	(67 ₁₆)...	X0000000
Port P5 direction register	(0D ₁₆)...	00 ₁₆	D-A register 0	(68 ₁₆)...	00 ₁₆
Port P6 direction register	(10 ₁₆)...	00 ₁₆	D-A register 1	(6A ₁₆)...	00 ₁₆
Port P7 direction register	(11 ₁₆)...	00 ₁₆	Particular function select register 0	(6C ₁₆)...	00 ₁₆
Port P8 direction register	(14 ₁₆)...	00 ₁₆	Particular function select register 1	(6D ₁₆)...	00 ₁₆
Waveform output mode register	(1A ₁₆)...	00 ₁₆	INT4 interrupt control register	(6E ₁₆)...	XXXX0000
Pulse output data register 1	(1C ₁₆)...	00 ₁₆	INT3 interrupt control register	(6F ₁₆)...	00000000
Pulse output data register 0	(1D ₁₆)...	000X0000	A-D interrupt control register	(70 ₁₆)...	XXXXX?0000
A-D control register 0	(1E ₁₆)...	000000???	UART 0 transmit interrupt control register	(71 ₁₆)...	XXXXX00000
A-D control register 1	(1F ₁₆)...	000000011	UART 0 receive interrupt control register	(72 ₁₆)...	XXXXX00000
UART 0 transmit/receive mode register	(30 ₁₆)...	00 ₁₆	UART 1 transmit interrupt control register	(73 ₁₆)...	XXXXX00000
UART 1 transmit/receive mode register	(38 ₁₆)...	00 ₁₆	UART 1 receive interrupt control register	(74 ₁₆)...	XXXXX00000
UART 0 transmit/receive control register 0	(34 ₁₆)...	0XXXX01000	Timer A0 interrupt control register	(75 ₁₆)...	XXXXX00000
UART 1 transmit/receive control register 0	(3C ₁₆)...	0XXXX01000	Timer A1 interrupt control register	(76 ₁₆)...	XXXXX00000
UART 0 transmit/receive control register 1	(35 ₁₆)...	000000010	Timer A2 interrupt control register	(77 ₁₆)...	XXXXX00000
UART 1 transmit/receive control register 1	(3D ₁₆)...	000000010	Timer A3 interrupt control register	(78 ₁₆)...	XXXXX00000
Count start register	(40 ₁₆)...	00 ₁₆	Timer A4 interrupt control register	(79 ₁₆)...	XXXXX00000
One-shot start register	(42 ₁₆)...	XXXXX00000	Timer B0 interrupt control register	(7A ₁₆)...	XXXXX00000
Up-down register	(44 ₁₆)...	000000000	Timer B1 interrupt control register	(7B ₁₆)...	XXXXX00000
Timer A write flag	(45 ₁₆)...	XXXXXX0000	Timer B2 interrupt control register	(7C ₁₆)...	XXXXX00000
Timer A0 mode register	(56 ₁₆)...	00 ₁₆	INT0 interrupt control register	(7D ₁₆)...	XX00000000
Timer A1 mode register	(57 ₁₆)...	00 ₁₆	INT1 interrupt control register	(7E ₁₆)...	XX00000000
Timer A2 mode register	(58 ₁₆)...	00 ₁₆	INT2 interrupt control register	(7F ₁₆)...	XX00000000
Timer A3 mode register	(59 ₁₆)...	00 ₁₆	Processor status register PS		000??00001??
Timer A4 mode register	(5A ₁₆)...	00 ₁₆	Program bank register PG		00 ₁₆
Timer B0 mode register	(5B ₁₆)...	001X00000	Program counter PCH		Contents of FFFF ₁₆
Timer B1 mode register	(5C ₁₆)...	001X00000	Program counter PCL		Contents of FFFE ₁₆
Timer B2 mode register	(5D ₁₆)...	001X00000	Direct page register DPR		0000 ₁₆
Processor mode register 0	(5E ₁₆)...	000000010	Data bank register DT		00 ₁₆
Processor mode register 1	(5F ₁₆)...	00 ₁₆			

Contents of other registers and RAM are not initialized and must be initialized by software.

Fig. 3 Microcomputer internal registers status after reset

MEMORY AREA MODIFICATION FUNCTION

For the M37753FFCFP and the M37753FFCHP, the internal memory's size and address area can be changed by setting bits 2, 3, 4 (memory allocation select bits) of the particular function select register 0 (see figure 5). Figure 4 shows the memory map when changing the internal memory area.

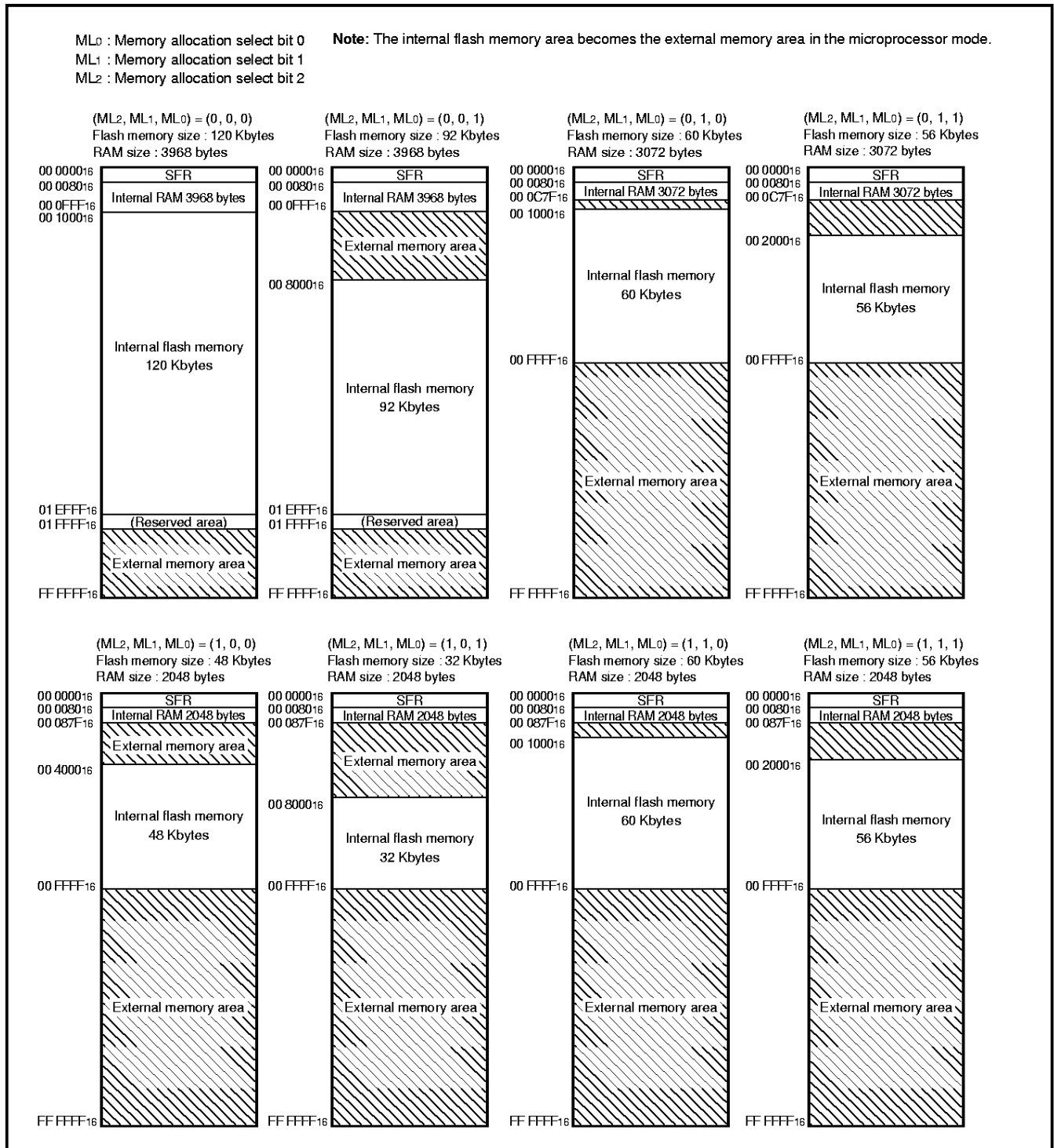


Fig. 4 Memory allocation (Internal memory area modification by memory allocation select bits)

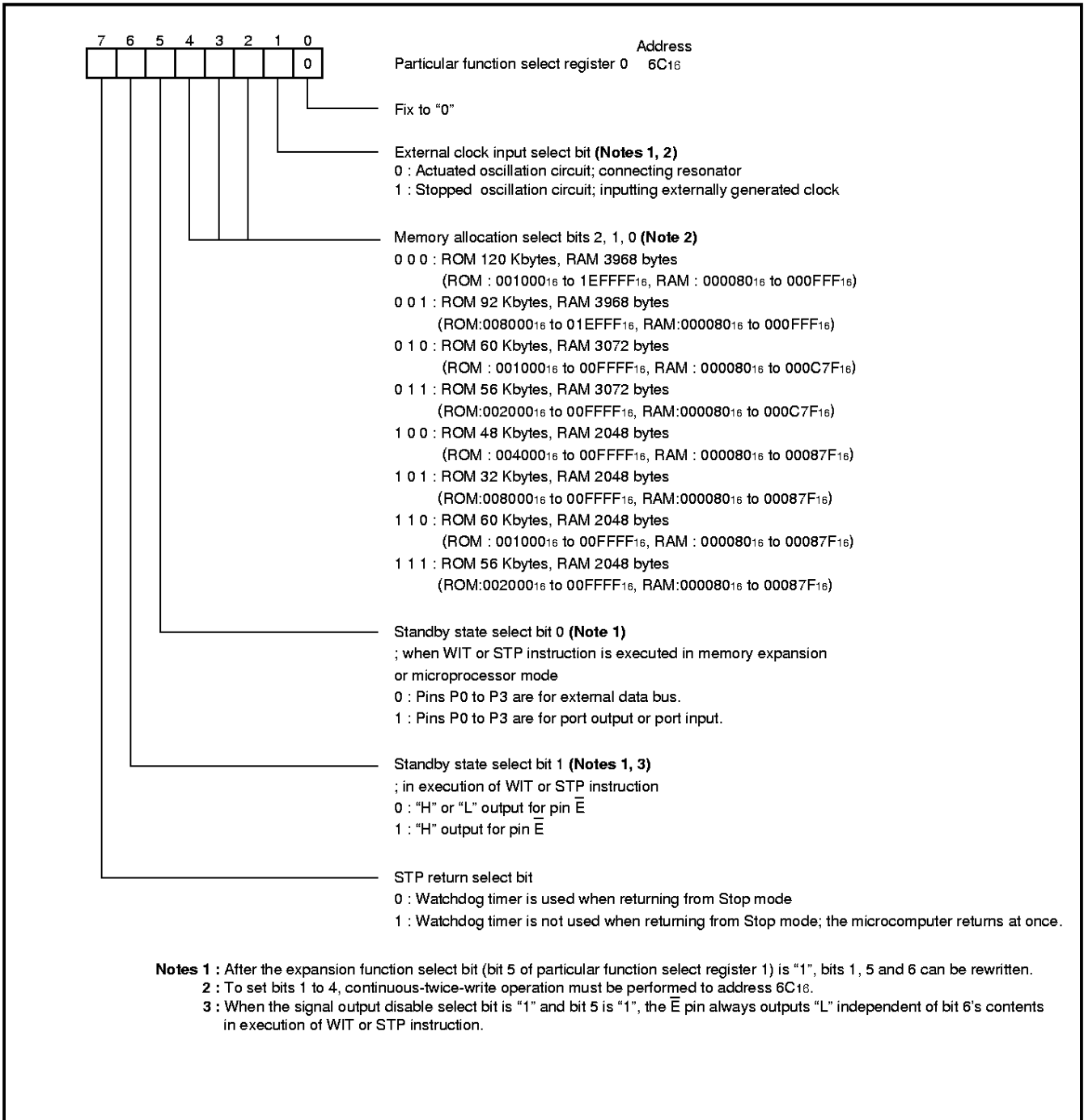


Fig. 5 Particular function select register 0 bit configuration

PRELIMINARY
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FLASH MEMORY MODE

The M37753FFCFP and the M37753FFCHP have the flash memory mode in addition to the normal operation mode (microcomputer mode). The user can use this mode to perform read, program, and erase operations for the internal flash memory.

The M37753FFCFP and the M37753FFCHP have three modes the user can choose: the parallel input/output and serial input/output mode, where the flash memory is handled by using the external programmer, and the CPU reprogramming mode, where the flash memory is handled by the central processing unit (CPU). The following explains these modes.

Flash memory mode 1 (parallel I/O mode)

The parallel I/O mode can be selected by connecting wires as shown in Figures 6, 7 and supplying power to the VCC and VPP pins. In this mode, the M37753FFCFP and the M37753FFCHP operate as an equivalent of MITSUBISHI's CMOS flash memory M5M28F101. However, because the M37753FFCFP and the M37753FFCHP's internal memory has a capacity of 120 Kbytes, programming is available for addresses 01000₁₆ to 1EFFF₁₆, and make sure that the data in addresses 00000₁₆ to 00FFF₁₆ and addresses 1F000₁₆ to 1FFFF₁₆ are FF₁₆. Note also that the M37753FFCFP and the M37753FFCHP do not contain a facility to read out a device identification code by applying a high voltage to address input (A9). Be careful not to erratically set program conditions when using a general-purpose PROM programmer.

Table 1 shows the pin assignments when operating in the parallel input/output mode.

Table 1. Pin assignments of M37753FFCFP and M37753FFCHP when operating in the parallel input/output mode

	M37753FFCFP/CHP	M5M28F101
VCC	VCC	VCC
VPP	CNVSS	VPP
VSS	VSS	VSS
Address input	Ports P0, P1, P54	A0-A16
Data I/O	Port P2	D0-D7
\overline{CE}	P52	\overline{CE}
\overline{OE}	P51	\overline{OE}
\overline{WE}	P50	\overline{WE}

Table 2. Assignment sates of control input and each state

		Pin	\overline{CE}	\overline{OE}	\overline{WE}	VPP	Data I/O
Mode	State						
Read-only	Read		VIL	VIL	VIH	VPPL	Output
	Output disable		VIL	VIH	VIH	VPPL	Floating
	Standby		VIH	×	×	VPPL	Floating
Read/Write	Read		VIL	VIL	VIH	VPPH	Output
	Output disable		VIL	VIH	VIH	VPPH	Floating
	Standby		VIH	×	×	VPPH	Floating
	Write		VIL	VIH	VIL	VPPH	Input

Note: x can be VIL or VIH.

Functional outline (Parallel input/output mode)

In the parallel input/output mode, the M37753FFCFP and the M37753FFCHP allow the user to choose an operation mode between the read-only mode and the read/write mode (software command control mode) depending on the voltage applied to the VPP pin. When VPP = VPPL, the read-only mode is selected, and the user can choose one of three states (e.g., read, output disable, or standby) depending on inputs to the \overline{CE} , \overline{OE} , and \overline{WE} pins. When VPP = VPPH, the read/write mode is selected, and the user can choose one of four states (e.g., read, output disable, standby, or write) depending on inputs to the \overline{CE} , \overline{OE} , and \overline{WE} pins. Table 2 shows assignment states of control input and each state.

Read

The microcomputer enters the read state by driving the \overline{CE} , and \overline{OE} pins low and the \overline{WE} pin high; and the contents of memory corresponding to the address to be input to address input pins (A0-A16) are output to the data input/output pins (D0-D7).

Output disable

The microcomputer enters the output disable state by driving the \overline{CE} pin low and the \overline{WE} and \overline{OE} pins high; and the data input/output pins enter the floating state.

Standby

The microcomputer enters the standby state by driving the \overline{CE} pin high. The M37753FFCFP and the M37753FFCHP are placed in a power-down state consuming only a minimal supply current. At this time, the data input/output pins enter the floating state.

Write

The microcomputer enters the write state by driving the VPP pin high (VPP = VPPH) and then the \overline{WE} pin low when the \overline{CE} pin is low and the \overline{OE} pin is high. In this state, software commands can be input from the data input/output pins, and the user can choose program or erase operation depending on the contents of this software command.

PRELIMINARY
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M37753FFCFP
M37753FFCHP

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

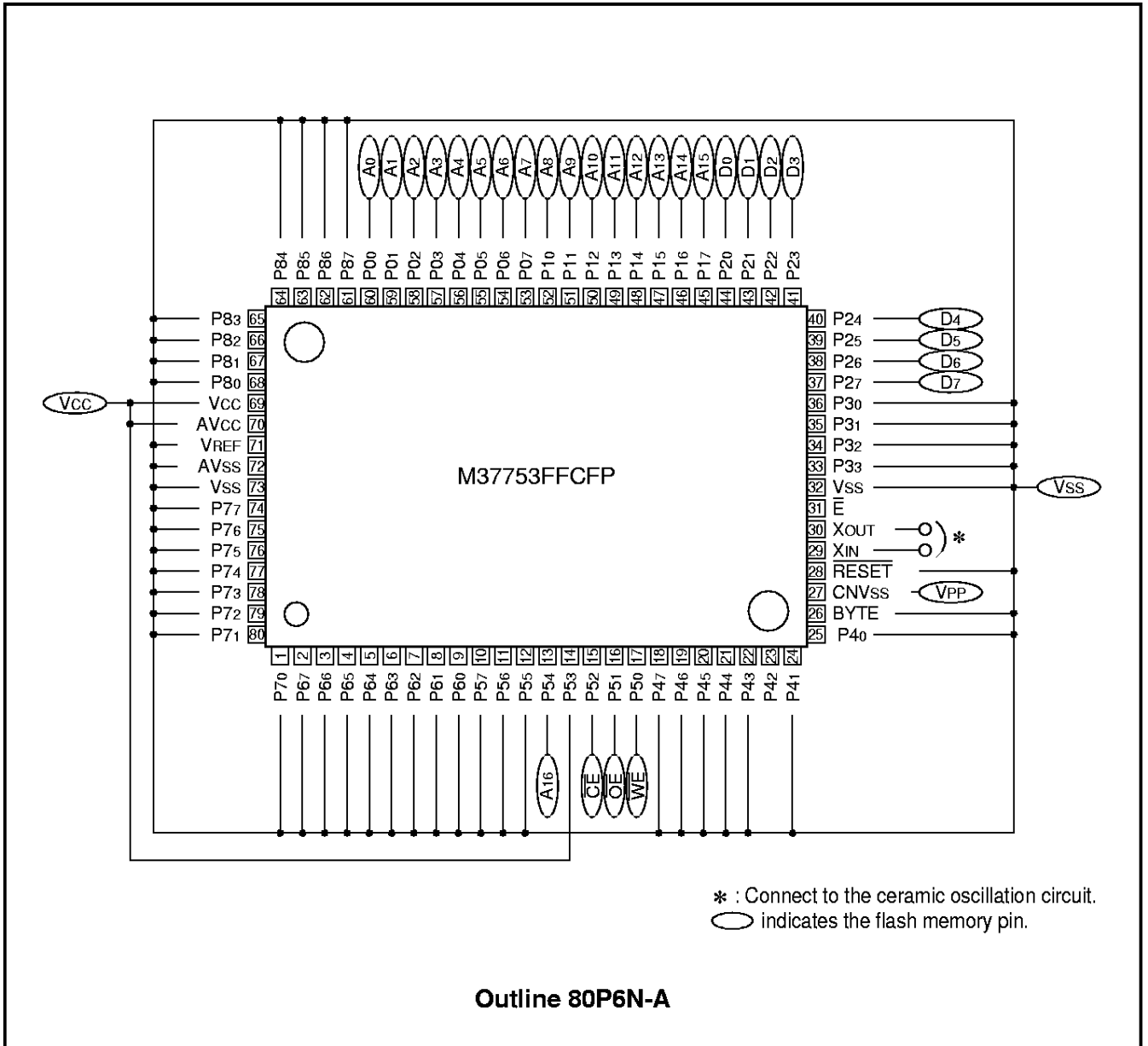


Fig. 6 Pin connection of M37753FFCFP when operating in parallel input/output mode

PRELIMINARY
 Notice: This is not a final specification.
 Some parametric limits are subject to change.

M37753FFCFP
M37753FFCHP

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

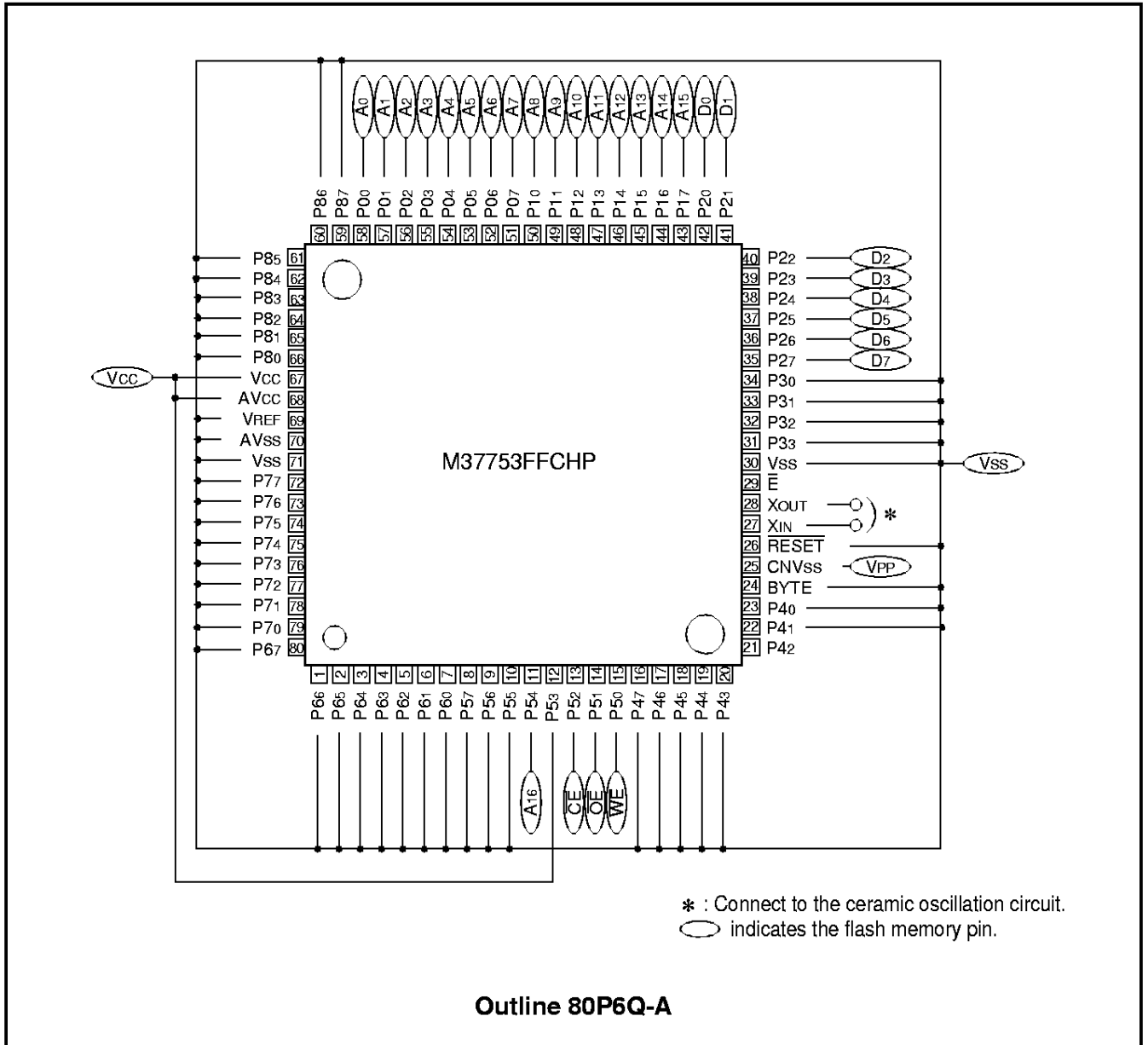


Fig. 7 Pin connection of M37753FFCHP when operating in parallel input/output mode

Read-only mode

The microcomputer enters the read-only mode by applying V_{PP}L to the VPP pin. In this mode, the user can input the address of a memory location to be read and the control signals at the timing

shown in Figure 8, and the M37753FFCFP and the M37753FFCHP will output the contents of the user's specified address from data I/O pin to the external. In this mode, the user cannot perform any operation other than read.

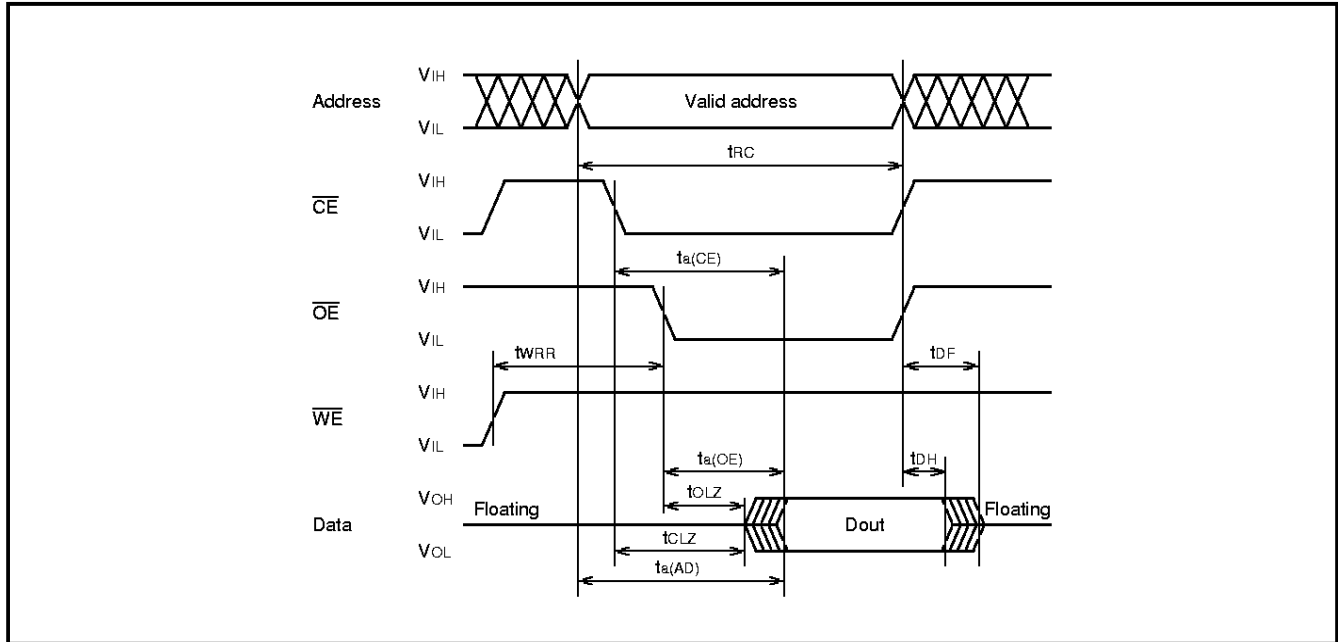


Fig. 8 Read timing

Read/Write mode

The microcomputer enters the read/write mode by applying V_{PP}H to the VPP pin. In this mode, the user must first input a software command to choose the operation (e. g., read, program, or erase) to be performed on the flash memory (this is called the first cycle), and then input the information necessary for execution of the command (e.g. address and data) and control signals (this is called the second cycle). When this is done, the M37753FFCFP and the M37753FFCHP execute the specified operation.

Table 3 shows the software commands and the input/output information in the first and the second cycles. The input address is latched internally at the falling edge of the \overline{WE} input; software commands and other input data are latched internally at the rising edge of the \overline{WE} input.

The following explains each software command. Refer to Figures 9 to 11 for details about the signal input/output timings.

Table 3. Software command (Parallel input/output mode)

Symbol	First cycle		Second cycle	
	Address input	Data input	Address input	Data I/O
Read	X	00 ₁₆	Read address	Read data (Output)
Program	X	40 ₁₆	Program address	Program data (Input)
Program verify	X	C0 ₁₆	X	Verify data (Output)
Erase	X	20 ₁₆	X	20 ₁₆ (Input)
Erase verify	Verify address	A0 ₁₆	X	Verify data (Output)
Reset	X	FF ₁₆	X	FF ₁₆ (Input)
Device identification	X	90 ₁₆	ADI	DDI (Output)

Note: ADI = Device identification address : manufacturer's code 00000₁₆, device code 00001₁₆
 DDI = Device identification data : manufacturer's code 1C₁₆, device code D0₁₆
 X can be V_{IL} or V_{IH}.

Read command

The microcomputer enters the read mode by inputting command code "0016" in the first cycle. The command code is latched into the internal command latch at the rising edge of the WE input. When the address of a memory location to be read is input in the second cycle, with control signals input at the timing shown in Figure 9, the M37753FFCFP and the M37753FFCHP output the contents of the specified address from the data I/O pins to the external.

The read mode is retained until any other command is latched into the command latch. Consequently, once the M37753FFCFP and the M37753FFCHP enter the read mode, the user can read out the successive memory contents simply by changing the input address and executing the second cycle only. Any command other than the read command must be input beginning from its command code over again each time the user execute it. The contents of the command latch immediately after power-on is 0016.

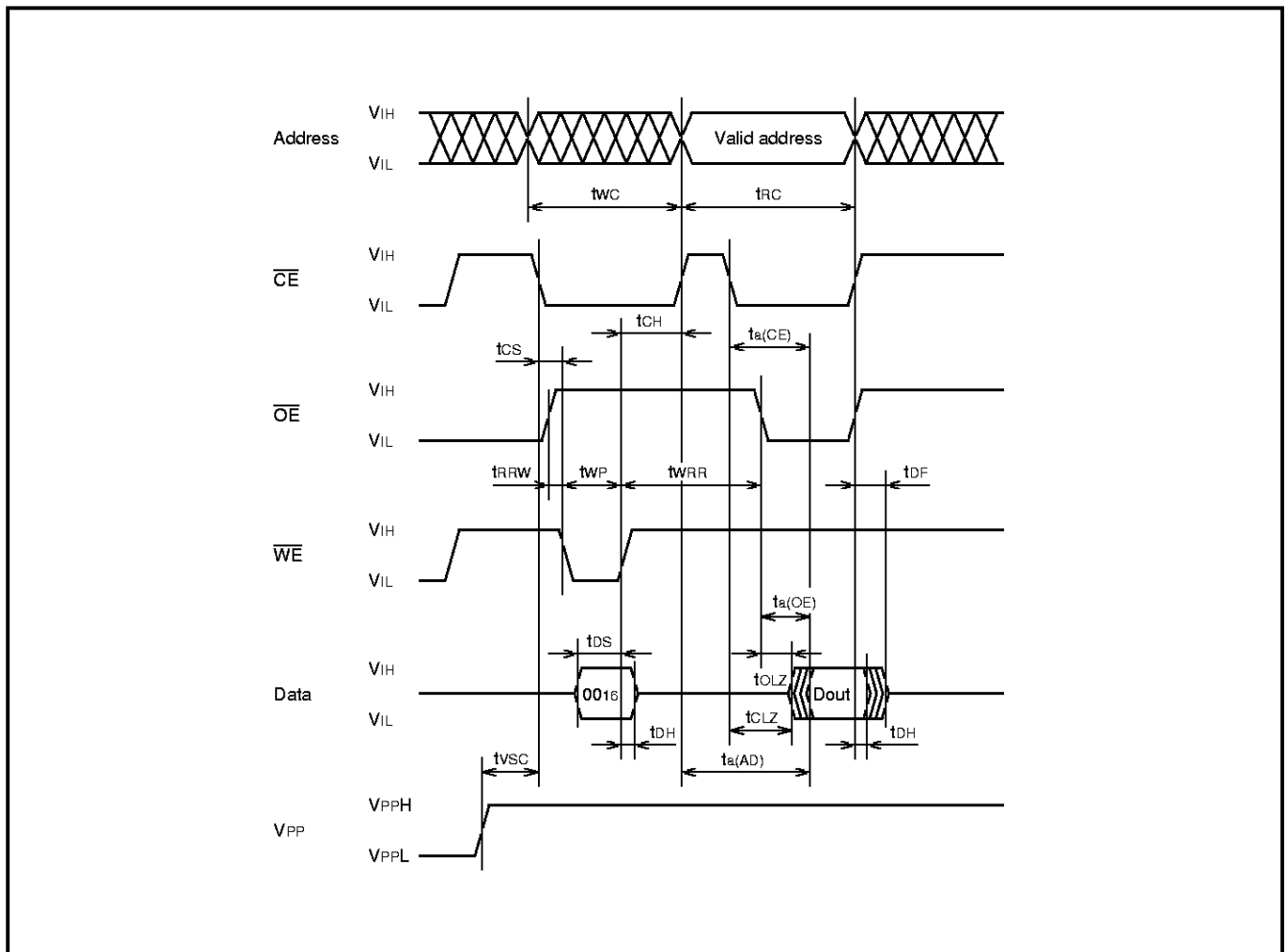


Fig. 9 Timings during reading

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

Program command

The microcomputer enters the program mode by inputting command code "4016" in the first cycle. The command code is latched into the internal command latch at the rising edge of the \overline{WE} input. When the address which indicates a program location and data are input in the second cycle, the M37753FFCFP and the M37753FFCHP internally latch the address at the falling edge of the \overline{WE} input and the data at the rising edge of the \overline{WE} input. The M37753FFCFP and the M37753FFCHP start programming at the rising edge of the \overline{WE} input in the second cycle and finishes programming within 10 μ s as measured by its internal timer. Programming is performed in units of bytes.

Note: A programming operation is not completed by executing the program command once. Always be sure to execute a program verify command after executing the program command. When the failure is found in this verification, the user must repeatedly execute the program command until the pass. Refer to Figure 12 for the programming flowchart.

Program verify command

The microcomputer enters the program verify mode by inputting command code "C016" in the first cycle. This command is used to verify the programmed data after executing the program command. The command code is latched into the internal command latch at the rising edge of the \overline{WE} input. When control signals are input in the second cycle at the timing shown in Figure 10, the M37753FFCFP and the M37753FFCHP output the programmed address's contents to the external. Since the address is internally latched when the program command is executed, there is no need to input it in the second cycle.

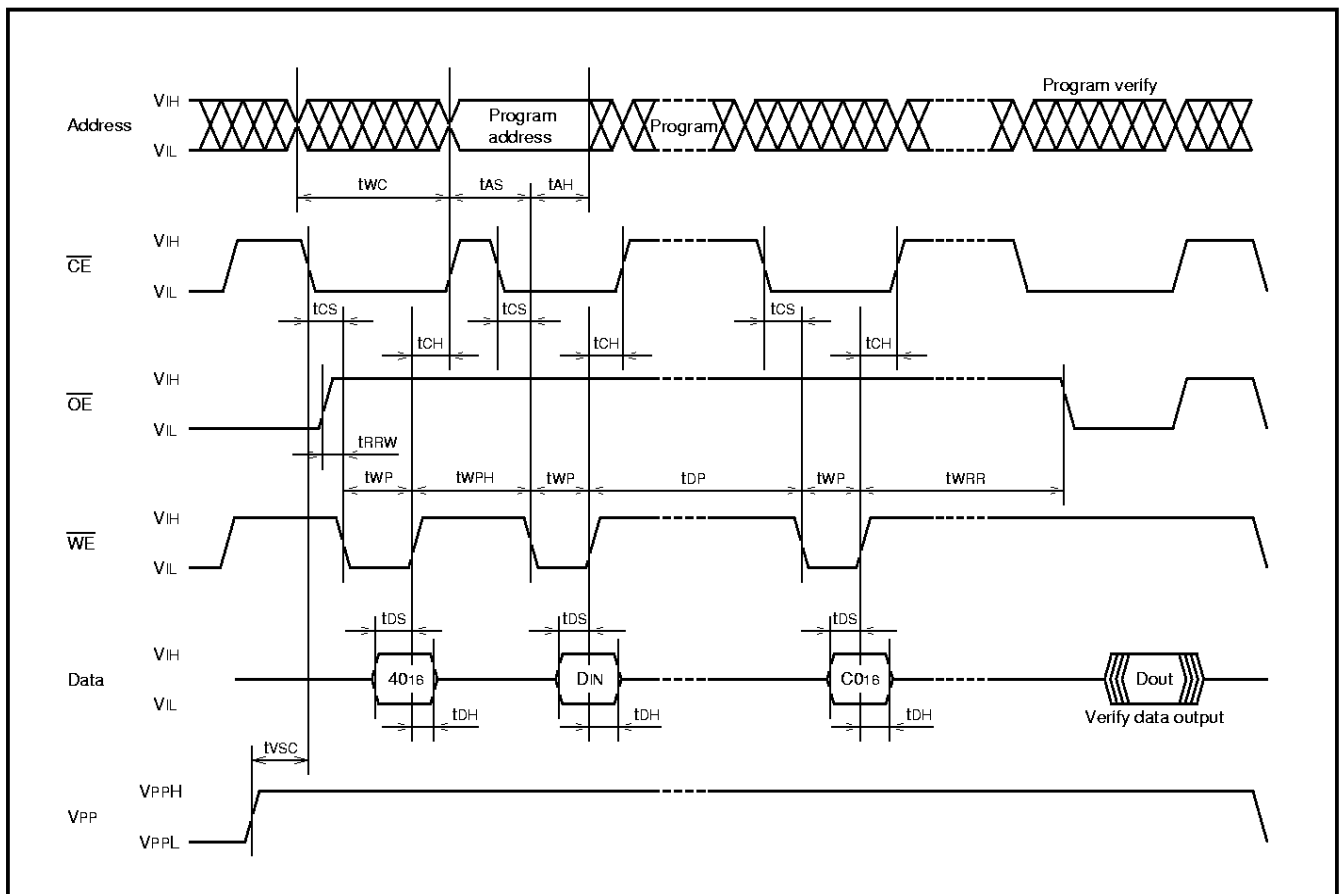


Fig. 10 Input/output timings during programming (Verify data is output at the same timing as for read.)

Erase command

The erase command is executed by inputting command code 20₁₆ in the first cycle and command code 20₁₆ again in the second cycle. The command code is latched into the internal command latch at the rising edges of the \overline{WE} input in the first cycle and in the second cycle, respectively. The erase operation is initiated at the rising edge of the \overline{WE} input in the second cycle, and the memory contents are collectively erased within 9.5 ms as measured by the internal timer. Note that data 00₁₆ must be written to all memory locations before executing the erase command.

Note: An erase operation is not completed by executing the erase command once. Always be sure to execute an erase verify command after executing the erase command. When the failure is found in this verification, the user must repeatedly execute the erase command until the pass. Refer to Figure 12 for the erase flowchart.

Erase verify command

The user must verify the contents of all addresses after completing the erase command. The microcomputer enters the erase verify mode by inputting the verify address and command code A0₁₆ in the first cycle. The address is internally latched at the falling edge of the \overline{WE} input, and the command code is internally latched at the rising edge of the \overline{WE} input. When control signals are input in the second cycle at the timing shown in Figure 11, the M37753FFCFP and the M37753FFCHP output the contents of the specified address to the external.

Note: If any memory location where the contents have not been erased is found in the erase verify operation, execute the operation of "erase → erase verify" over again. In this case, however, the user does not need to write data 00₁₆ to memory locations before erasing.

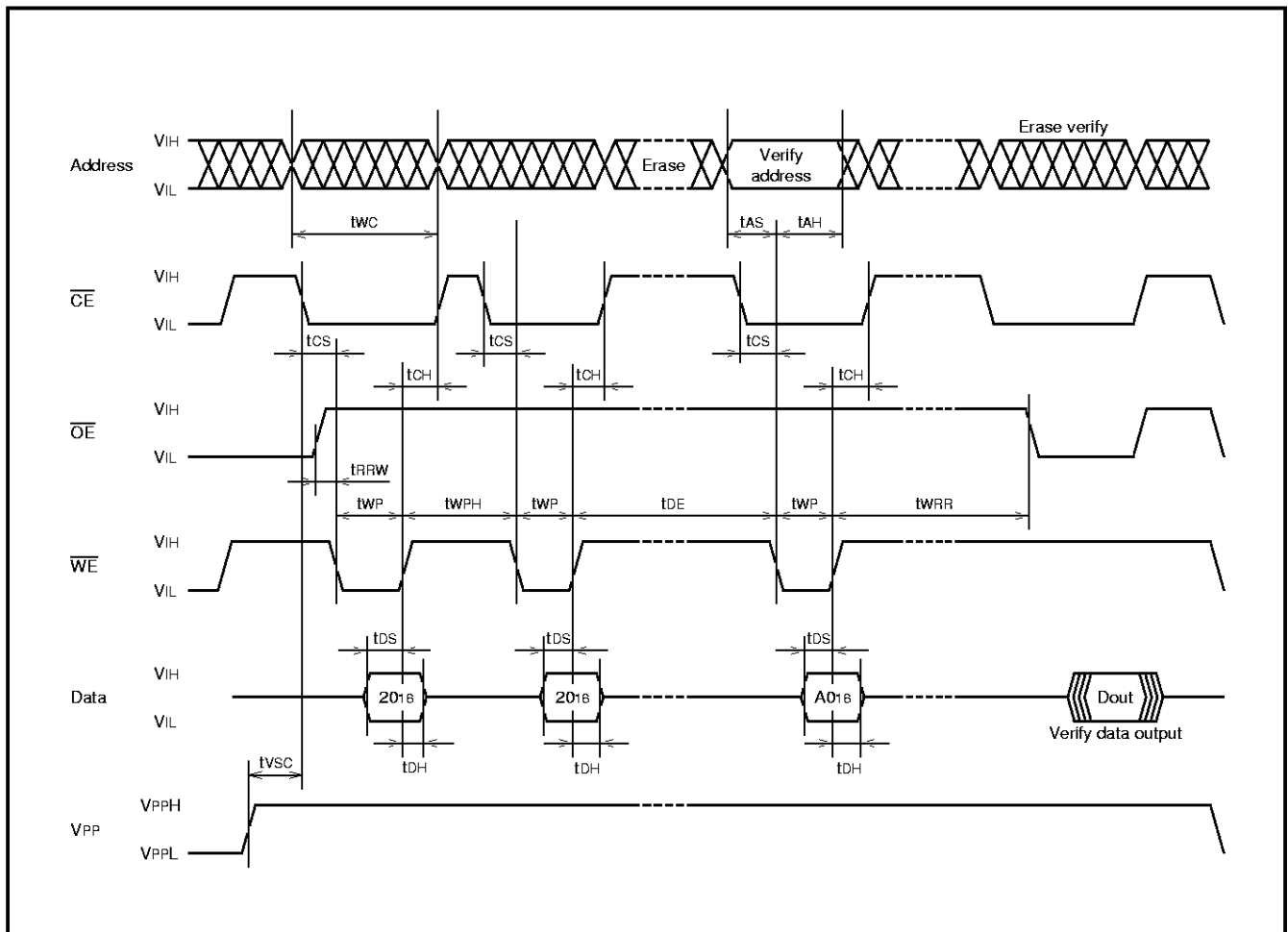


Fig. 11 Input/output timings during erasing (Verify data is output at the same timing as for read.)

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

Reset command

The reset command provides a means of stopping execution of the erase or program command safely. If the user inputs command code FF₁₆ in the second cycle after inputting the erase or program command in the first cycle and again input command code FF₁₆ in the third cycle, the erase or program command is disabled (i.e., reset), and the M37753FFCFP and the M37753FFCHP are placed in the read mode. If the reset command is executed, the contents of the memory does not change.

Device identification code command

By inputting command code 90₁₆ in the first cycle, the user can read out the device identification code. The command code is latched into the internal command latch at the rising edge of the \overline{WE} input. At this time, the user can read out manufacture's code 1C₁₆ (i.e., MITSUBISHI) by inputting 0000₁₆ to the address input pins in the second cycle; the user can read out device code D0₁₆ (i.e., 1M-bit flash memory) by inputting 0001₁₆.

These command and data codes are input/output at the same timing as for read.

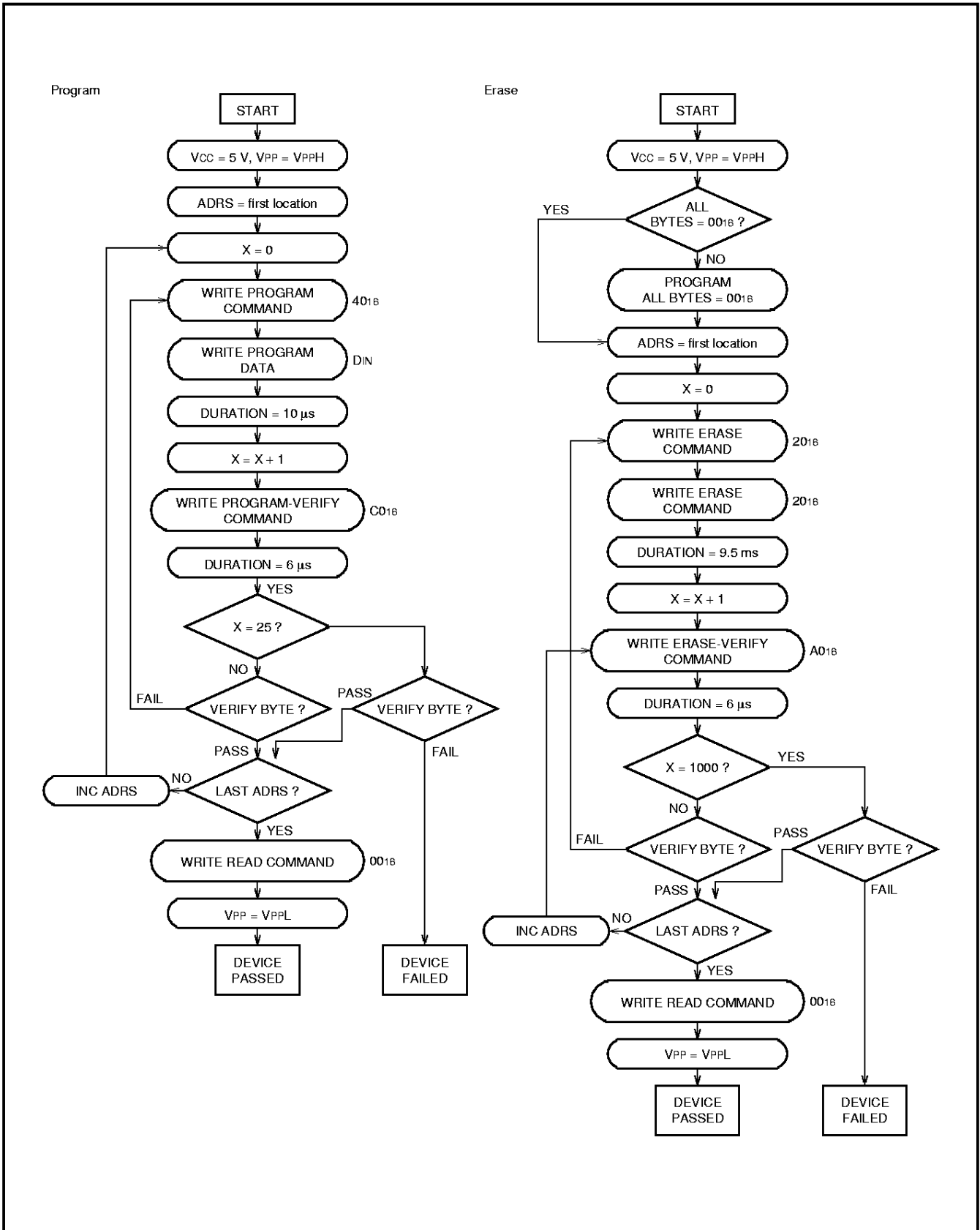


Fig. 12 Programming/Erasing algorithm flow chart

PRELIMINARY
Notice: This is not a final specification.
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SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

DC ELECTRICAL CHARACTERISTICS ($T_a = 25\text{ }^\circ\text{C}$, $V_{CC} = 5\text{ V} \pm 10\%$, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
ISB1	VCC supply current (at standby)	$V_{CC} = 5.5\text{ V}$, $\overline{CE} = V_{IH}$			1	mA
ISB2		$V_{CC} = 5.5\text{ V}$, $\overline{CE} = V_{CC} \pm 0.2\text{ V}$			100	μA
ICC1	VCC supply current (at read)	$V_{CC} = 5.5\text{ V}$, $\overline{CE} = V_{IL}$, $t_{RC} = 150\text{ ns}$, $I_{OUT} = 0\text{ mA}$			30	mA
ICC2	VCC supply current (at program)	$V_{PP} = V_{PPH}$			30	mA
ICC3	VCC supply current (at erase)	$V_{PP} = V_{PPH}$			30	mA
IPP1	VPP supply current (at read)	$0 \leq V_{PP} \leq V_{CC}$			10	μA
		$V_{CC} < V_{PP} \leq V_{CC} + 1.0\text{ V}$			100	μA
		$V_{PP} = V_{PPH}$			100	μA
IPP2	VPP supply current (at program)	$V_{PP} = V_{PPH}$			30	mA
IPP3	VPP supply current (at erase)	$V_{PP} = V_{PPH}$			30	mA
VPLL	VPP supply voltage (read only)		V_{CC}		$V_{CC} + 1.0$	V
VPPH	VPP supply voltage (read/write)		11.4	12.0	12.6	V

Note: V_{IH} , V_{IL} , V_{OH} , V_{OL} , I_{IH} , and I_{IL} for the control input, address input, and data input/output pins conform to the standards for microcomputer modes (e.g., memory expansion and microprocessor modes).

AC ELECTRICAL CHARACTERISTICS ($T_a = 25\text{ }^\circ\text{C}$, $V_{CC} = 5\text{ V} \pm 10\%$, unless otherwise noted)

Read-only mode

Symbol	Parameter	Limits		Unit
		Min.	Max.	
t_{RC}	Read cycle time	150		ns
$t_{a(AD)}$	Address access time		150	ns
$t_{a(CE)}$	\overline{CE} access time		150	ns
$t_{a(OE)}$	\overline{OE} access time		55	ns
t_{CLZ}	Output enable time (after \overline{CE})	0		ns
t_{OLZ}	Output enable time (after \overline{OE})	0		ns
t_{DF}	Output floating time (after \overline{OE})		35	ns
t_{DH}	Output valid time (after \overline{CE} , \overline{OE} , address)	0		ns
t_{WRR}	Write recovery time (before read)	6		μs

Read/Write mode

Symbol	Parameter	Limits		Unit
		Min.	Max.	
t_{WC}	Write cycle time	150		ns
t_{AS}	Address set up time	0		ns
t_{AH}	Address hold time	60		ns
t_{DS}	Data setup time	50		ns
t_{DH}	Data hold time	10		ns
t_{WRR}	Write recovery time (before read)	6		μs
t_{RRW}	Read recovery time (before write)	0		μs
t_{CS}	\overline{CE} setup time	20		ns
t_{CH}	\overline{CE} hold time	0		ns
t_{WP}	Write pulse width	60		ns
t_{WPH}	Write pulse waiting time	20		ns
t_{DP}	Program time	10		μs
t_{DE}	Erase time	9.5		ms
t_{VSC}	VPP setup time	1		μs

Note: The read timing in the read/write mode is the same timing as in the read-only mode.

PRELIMINARY
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M37753FFCFP
M37753FFCHP

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

Flash memory mode 2 (serial I/O mode)

The M37753FFCFP and the M37753FFCHP have a function to serially input/output the software commands, addresses, and data required for operation on the internal flash memory (e. g., read, program, and erase) using only a few pins. This is called the serial I/O (input/output) mode. This mode can be selected by driving the SDA (serial data input/output), SCLK (serial clock input), and \overline{OE}

pins high after connecting wires as shown in Figures 13, 14 and powering on the VCC pin and then applying VPPH to the VPP pin. In the serial I/O mode, the user can use seven types of software commands: bank (0, 1) select, read, program, program verify, auto erase, and error check. Serial input/output is accomplished synchronously with the clock, beginning from the LSB (LSB first).

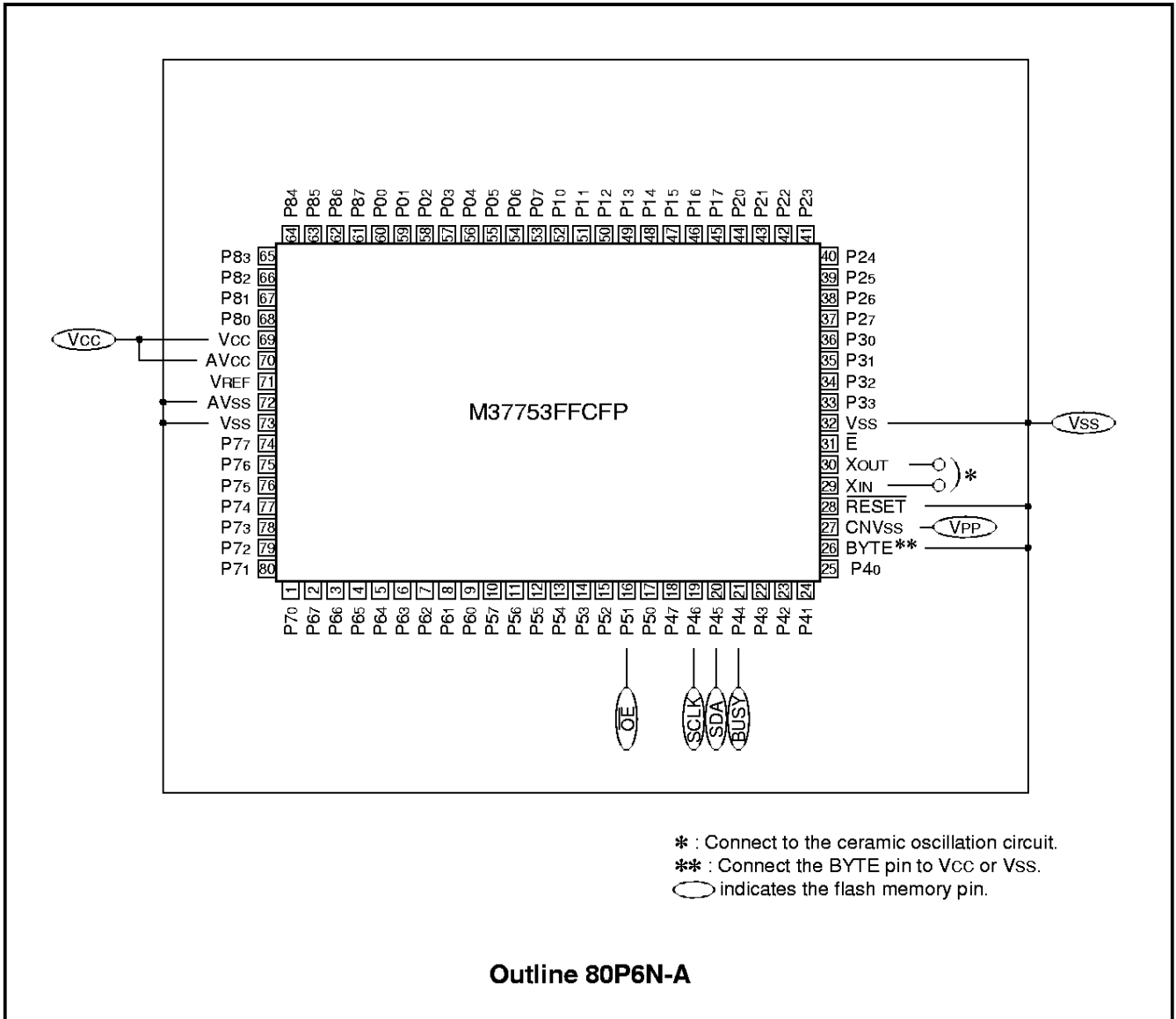


Fig. 13 Pin connection of M37753FFCFP when operating in serial I/O mode

PRELIMINARY
 Notice: This is not a final specification.
 Some parametric limits are subject to change.

M37753FFCFP
M37753FFCHP

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

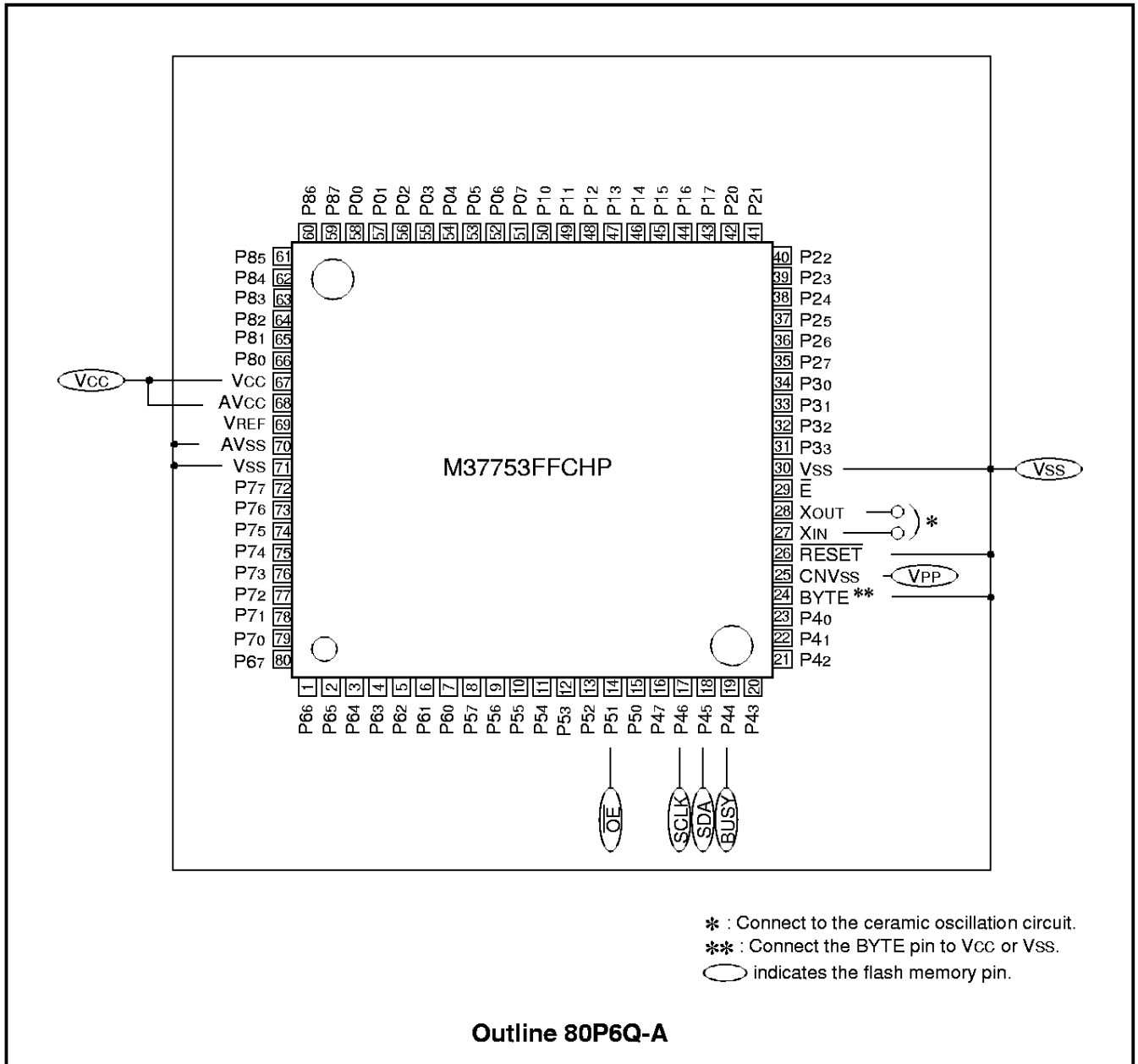


Fig. 14 Pin connection of M37753FFCHP when operating in serial I/O mode

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

Functional outline (Serial I/O mode)

In the serial I/O mode, data is transferred synchronously with the clock using serial input/output. The input data is read from the SDA pin into the internal circuit synchronously with the rising edge of the serial clock pulse; the output data is output from the SDA pin synchronously with the falling edge of the serial clock pulse. Data is

transferred in units of eight bits.

In the first transfer, the user inputs the command code. This is followed by address input and data input/output according to the contents of the command. Table 4 shows the software commands used in the serial I/O mode. The following explains each software command.

Table 4. Software command (Serial I/O mode)

Command	Number of transfers	First command code input	Second	Third	Fourth
Bank 0 select		E0 ₁₆	_____	_____	_____
Bank 1 select		E1 ₁₆	_____	_____	_____
Read		00 ₁₆	Read address L (Input)	Read address H (Input)	Read data (Output)
Program		40 ₁₆	Program address L (Input)	Program address H (Input)	Program data (Input)
Program verify		C0 ₁₆	Verify data (Output)	_____	_____
Auto erase		30 ₁₆	30 ₁₆ (Input)	_____	_____
Error check		80 ₁₆	Error code (Output)	_____	_____

Bank select command

This is the command which specifies the bank of the flash memory, which is to be read/programmed, before executing the read command or the program command (and the program verify command). There are the bank 0 select command (command code "E0₁₆"), which selects bank 0 (addresses 00000₁₆ to 0FFFF₁₆), and the bank 1 select command (command code "E1₁₆"), which selects bank 1 (addresses 10000₁₆ to 1FFFF₁₆).

When any bank select command is input once, specified bank is

valid until the next bank select command is input. Accordingly, when the read command or the program command (and the program verify command) is executed to plural bytes in the same bank, if any bank select command is input first, it is unnecessary to input the bank select command again for the following bytes. When selecting the serial I/O mode (before bank command input), bank 0 is selected.

Note: Bank select command does not affect the auto erase command, that is to say, when executing the auto erase command, all flash memory is erased collectively regardless of specified bank.

And in the same way, the bank select command does not affect the error check command.

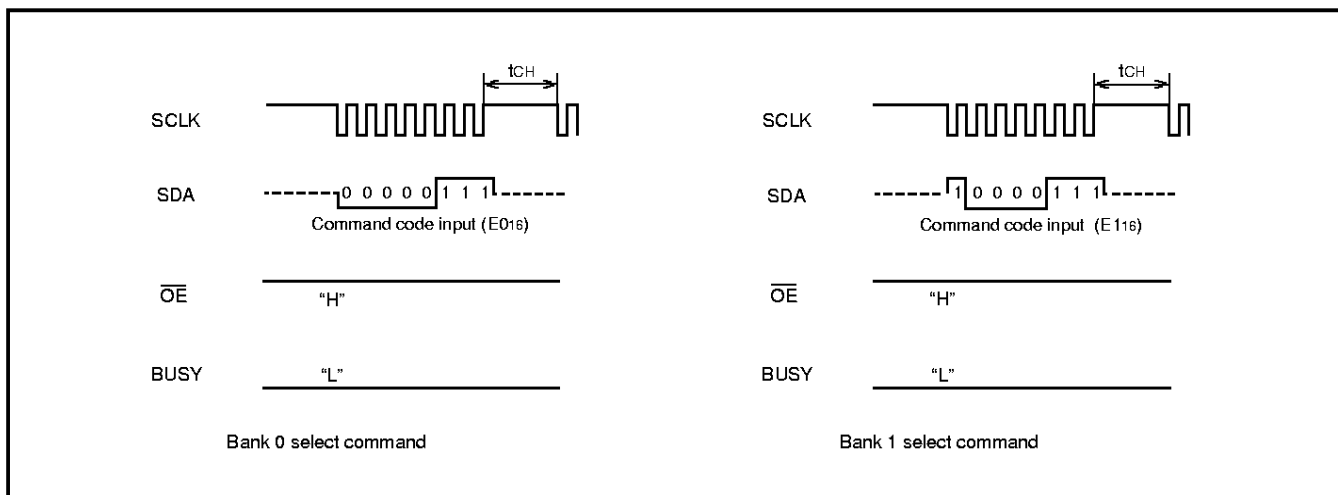


Fig. 15 Timings during bank select

Read command

Input command code 00₁₆ in the first transfer. Proceed and input the low-order 8 bits and the high-order 8 bits of the address and pull the \overline{OE} pin low. When this is done, the M37753FFCFP and the M37753FFCHP read out the contents of the specified address, and

then latch it into the internal data latch. When the \overline{OE} pin is released back high and serial clock is input to the SCLK pin, the read data that has been latched into the data latch is serially output from the SDA pin.

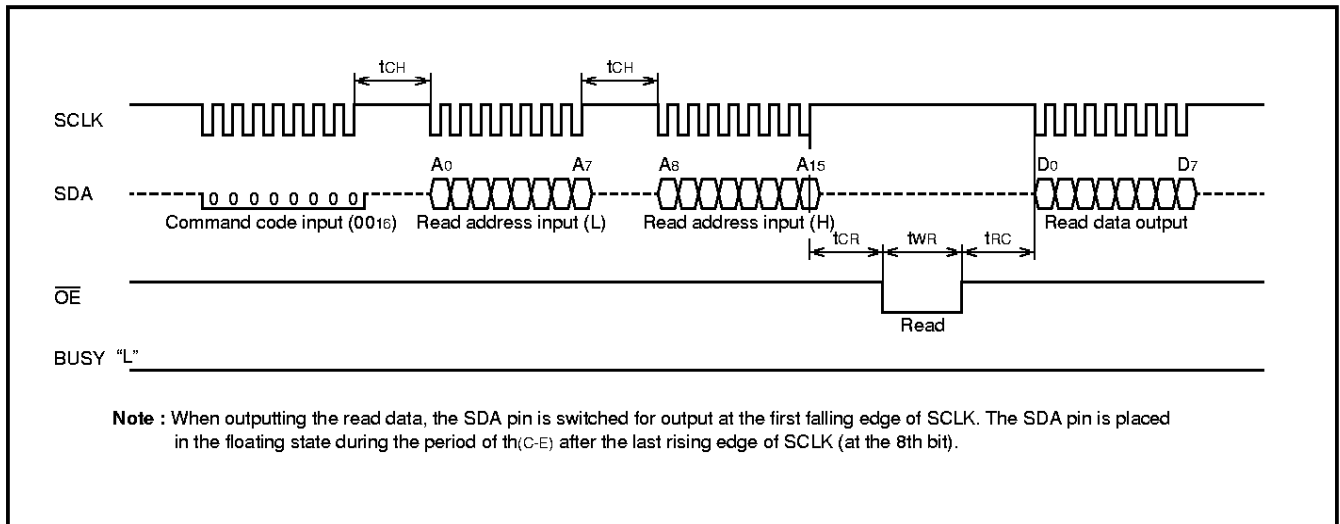


Fig. 16 Timings during reading

Program command

Input command code 40₁₆ in the first transfer. Proceed and input the low-order 8 bits and the high-order 8 bits of the address and then program data. Programming is initiated at the last rising edge of the serial clock during program data transfer. The BUSY pin is driven high during program operation. Programming is completed within 10 μs as measured by the built-in timer, and the BUSY pin is pulled low.

Note : A programming operation is not completed by executing the program command once. Always be sure to execute a program verify command after executing the program command. In the case of failure in the verification, the user must repeatedly execute the program command until the pass in the verification. Refer to Figure 12 for the programming flowchart.

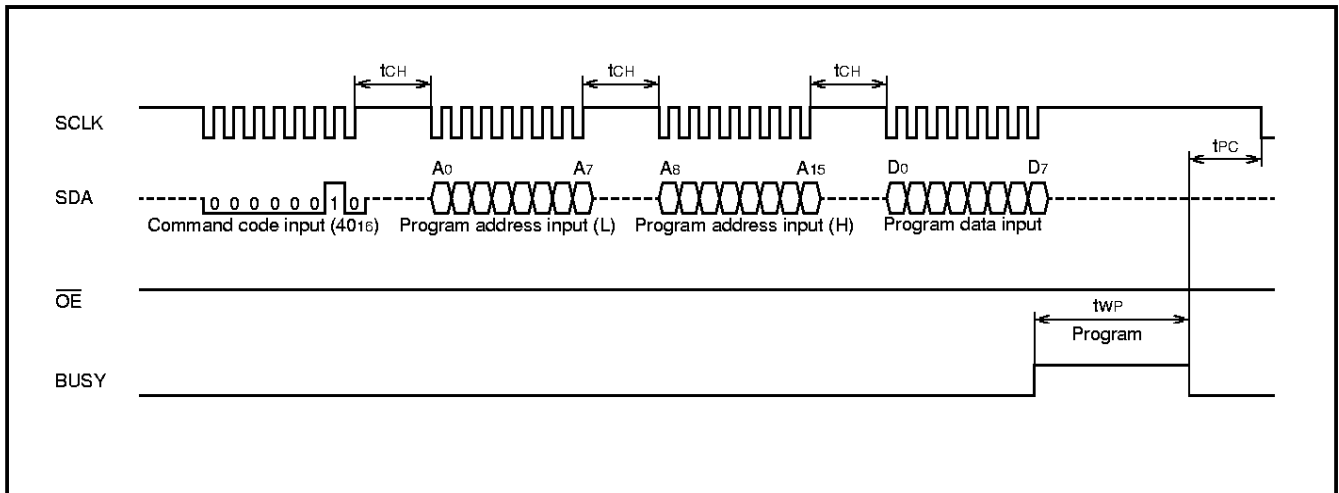
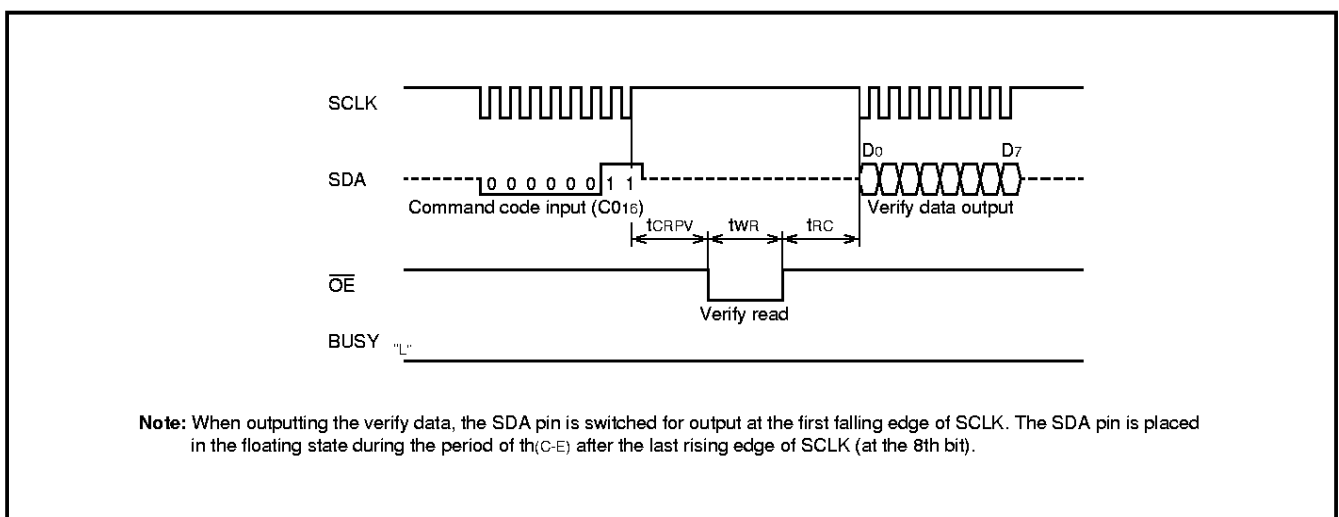


Fig. 17 Timings during programming

Program verify command

Input command code C0₁₆ in the first transfer. Proceed and drive the OE pin low. When this is done, the M37753FFCFP and the M37753FFCHP verify-read the programmed address's contents,

and then latch it into the internal data latch. When the OE pin is released back high and serial clock is input to the SCLK pin, the verify data that has been latched into the data latch is serially output from the SDA pin.



Note: When outputting the verify data, the SDA pin is switched for output at the first falling edge of SCLK. The SDA pin is placed in the floating state during the period of $t_{(C-E)}$ after the last rising edge of SCLK (at the 8th bit).

Fig. 18 Timings during program verify

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

Auto erase command

Input command code 30₁₆ in the first transfer and command code 30₁₆ again in the second transfer. When this is done, the M37753FFCFP and the M37753FFCHP execute an auto erase command. Auto erase is initiated at the last rising edge of the serial clock. The BUSY pin is driven high during the auto erase operation. Auto

erase is completed when all memory contents are erased, and the BUSY pin is pulled low.

Note: In the auto erase operation, the M37753FFCFP and the M37753FFCHP automatically repeat the erase and verify operations internally. Therefore, erase is completed by executing the command once.

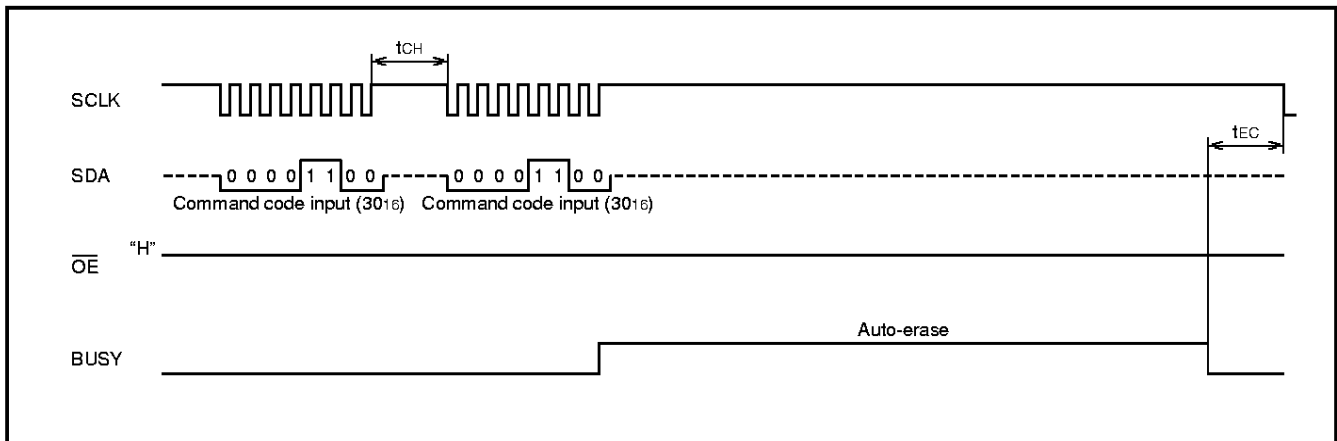


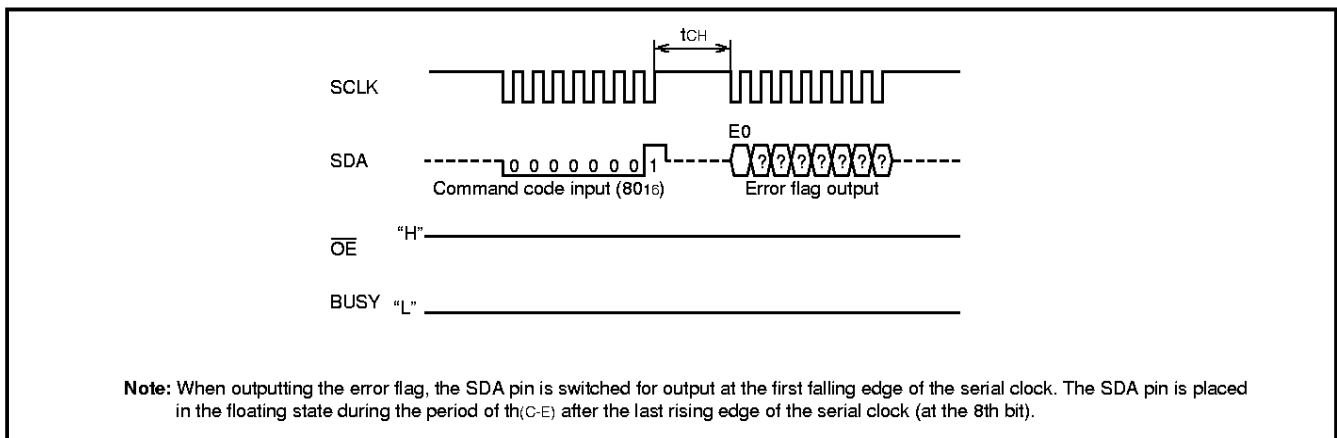
Fig. 19 Timings at auto-erasing

Error check command

Input command code 80₁₆ in the first transfer, and the M37753FFCFP and the M37753FFCHP output error information from the SDA pin, beginning at the next falling edge of the serial clock. If the E0 of the 8-bit error information is 1, it indicates that a command error has occurred. A command error means that some invalid commands other than commands shown in Table 4 has been input.

When a command error occurs, the serial communication circuit sets the corresponding flag and stops functioning to avoid an erroneous programming or erase. When being placed in this state, the serial communication circuit does not accept the subsequent serial clock and data (even including an error check command). Therefore, if the

user wants to execute an error check command, temporarily drop the VPP pin input to the VPPL level to terminate the serial input/output mode. Then, place the M37753FFCFP and the M37753FFCHP into the serial I/O mode back again. The serial communication circuit is reset by this operation and is ready to accept commands. The error flag alone is not cleared by this operation, so the user can examine the serial communication circuit's error conditions before reset. This examination is done by the first execution of an error check command after the reset. The error flag is cleared when the user has executed the error check command. Because the error flag is undefined immediately after power-on, always be sure to execute the error check command.



Note: When outputting the error flag, the SDA pin is switched for output at the first falling edge of the serial clock. The SDA pin is placed in the floating state during the period of $t_{H(C-E)}$ after the last rising edge of the serial clock (at the 8th bit).

Fig. 20 Timings at error checking

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

DC ELECTRICAL CHARACTERISTICS (Ta = 25 °C, VCC = 5 V ± 10 %, VPP = 12 V ± 5 %, unless otherwise noted)

ICC, IPP-relevant standards during read, program, and erase are the same as in the parallel input/output mode. VIH, VIL, VOH, VOL, IIH, and IIL for the SCLK, SDA, BUSY, OE pins conform to the microcomputer modes.

AC ELECTRICAL CHARACTERISTICS

(Ta = 25 °C, VCC = 5 V ± 10 %, VPP = 12 V ± 5 %, f(XIN) = 40 MHz, unless otherwise noted)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tCH	Serial transmission interval	400 ^(Note 1)		ns
tCR	Read waiting time after transmission	400 ^(Note 1)		ns
tWR	Read pulse width	320 ^(Note 2)		ns
tRC	Transfer waiting time after read	400 ^(Note 1)		ns
tCRPV	Waiting time before program verify	6		µs
tWP	Programming time		10	µs
tPC	Transfer waiting time after programming	400 ^(Note 1)		ns
tEC	Transfer waiting time after erase	400 ^(Note 1)		ns
tc(CK)	SCLK input cycle time	250		ns
tw(CKH)	SCLK high-level pulse width	100		ns
tw(CKL)	SCLK low-level pulse width	100		ns
tr(CK)	SCLK rise time	20		ns
tf(CK)	SCLK fall time	20		ns
td(C-Q)	SDA output delay time	0	90	ns
th(C-Q)	SDA output hold time	0		ns
th(C-E)	SDA output hold time (only the 8th bit)	120 ^(Note 3)	200 ^(Note 4)	ns
tsu(D-C)	SDA input set up time	30		ns
th(C-D)	SDA input hold time	90		ns

Notes 1: When f(XIN) = 25 MHz or less, calculate the minimum value according to formula 1.

$$\text{Formula 1 : } \frac{1 \times 10}{f(XIN)} \times 10^9$$

2: When f(XIN) = 25 MHz or less, calculate the minimum value according to formula 2.

$$\text{Formula 2 : } \frac{1 \times 8}{f(XIN)} \times 10^9$$

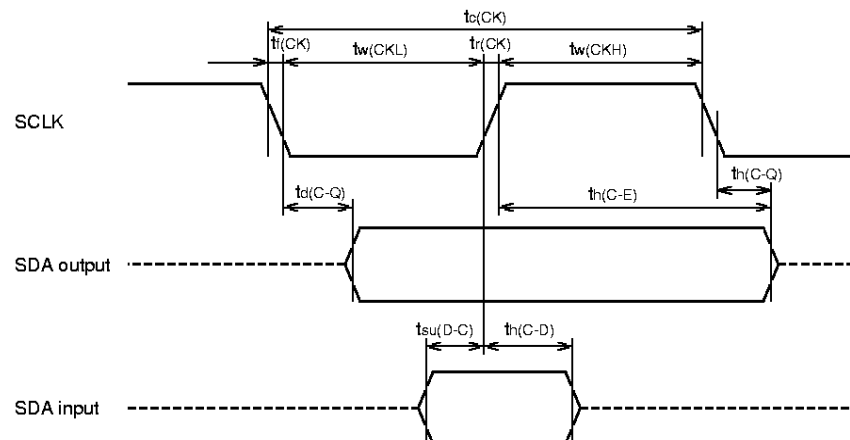
3: When f(XIN) = 25 MHz or less, calculate the minimum value according to formula 3.

$$\text{Formula 3 : } \frac{1 \times 3}{f(XIN)} \times 10^9$$

4: When f(XIN) = 25 MHz or less, calculate the minimum value according to formula 4

$$\text{Formula 4 : } \frac{1 \times 5}{f(XIN)} \times 10^9$$

AC waveforms



Test conditions for AC characteristics

- Output timing voltage : VOL = 0.8 V, VOH = 2.0 V
- Input timing voltage : VIL = 0.2 VCC, VIH = 0.8 VCC

Flash memory mode 3 (CPU reprogramming mode)

The M37753FFCFP and the M37753FFCHP have the CPU reprogramming mode where a built-in flash memory is handled by the central processing unit (CPU). 112 Kbytes (addresses 001000₁₆ to 00EFFF₁₆ and addresses 011000₁₆ to 01EFFF₁₆) of the 120-Kbyte flash memory shown in Figure 1 can be reprogrammed (erase and program). Remaining 8 Kbytes of the flash memory (addresses 00F000₁₆ to 010FFF₁₆) cannot be reprogrammed, but can be read. (It is possible to reprogram this remaining 8 Kbytes in the parallel I/O mode and the serial I/O mode). This area of 8 Kbytes can be used as an area where the control program of CPU reprogramming mode is stored.

In CPU reprogramming mode, the flash memory is handled by writing and reading to/from the flash memory control register (see Figure 21) and the flash command register (see Figure 22).

The CNVSS pin is used as the VPP power supply pin in CPU reprogramming mode. It is necessary to apply the power-supply voltage of VPPH from the external to this pin.

Functional outline (Parallel input/output mode)

Figure 21 shows the flash memory control register bit configuration.

Figure 22 shows the flash command register bit configuration.

Bit 0 of the flash memory control register is the CPU reprogramming mode select bit. When this bit is set to "1" and VPPH is applied to the CNVSS/VPP pin, the CPU reprogramming mode is selected. Whether the CPU reprogramming mode is realized or not is judged by reading the CPU reprogramming mode monitor flag (bit 3 of the flash memory control register).

Bit 1 is a busy flag which becomes "1" during auto erase, erase, and program execution.

Whether these operations have been completed or not is judged by checking this flag after each command of auto erase, erase, and the program is executed.

Bits 4, 5 of the flash memory control register are the erase/program area select bits. These bits specify an area where auto erase, erase, and program is operated. When the auto erase and the erase commands are executed after an area is specified by these bits, only the specified area is erased. Only for the specified area, programming is enabled; for the other areas, programming is disabled.

Figure 23 shows the processor mode register 0 bit configuration in the CPU reprogramming mode. Set bit 1 to "0" (single-chip or memory expansion mode) in the CPU reprogramming mode. Set bit 2 (internal memory access bus cycle select bit) to "0."

Be sure to set data length select flag m to "1" (8-bit length) beforehand because writing and reading of data are operated in unit of byte.

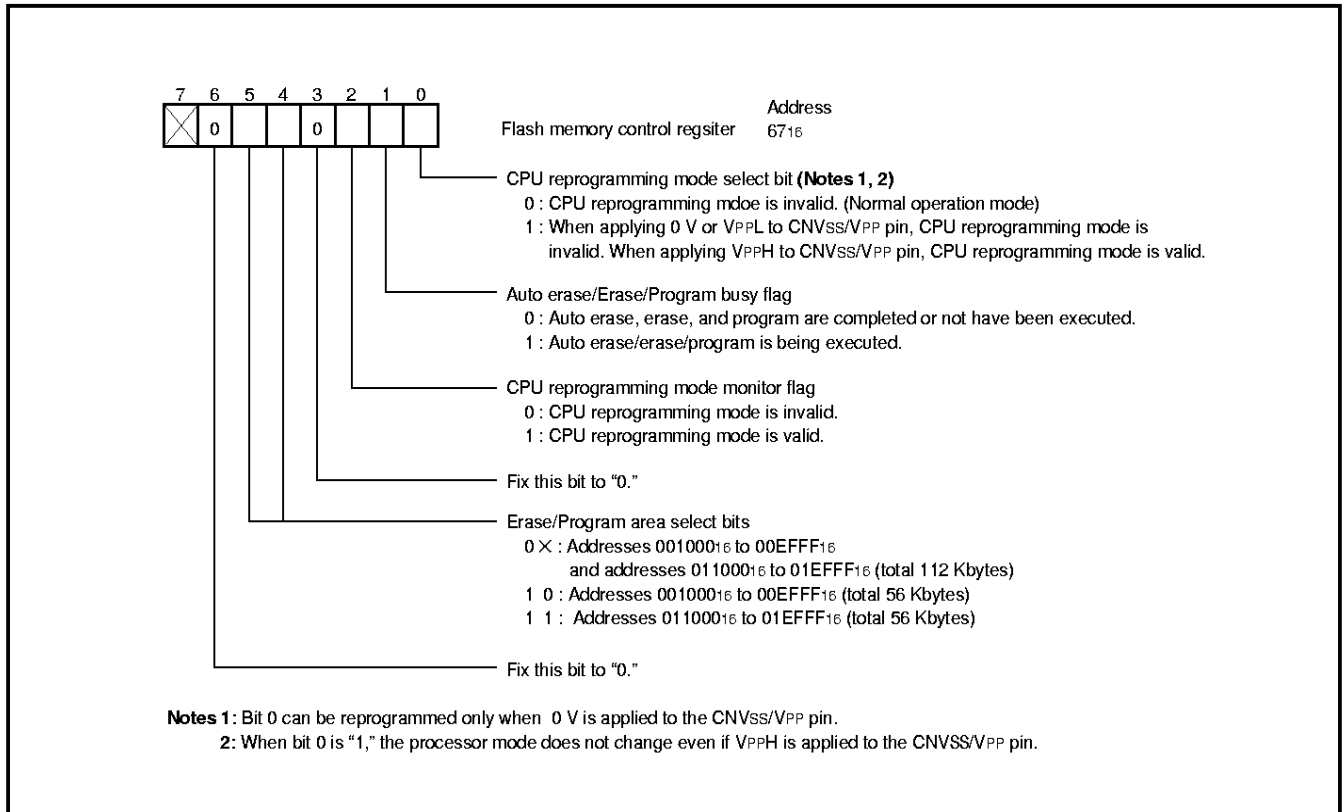


Fig. 21 Flash memory control register bit configuration

CPU reprogramming mode operation procedure

The operation procedure in CPU reprogramming mode is described below.

< Beginning procedure >

- ① Apply 0 V to the CNVss/VPP pin for reset release.
- ② Set the processor mode register 0 (see Figure 23).
- ③ After CPU reprogramming mode control program is transferred to internal RAM, jump to this control program on RAM. (The following operations are controlled by this control program).
- ④ Set "1" (8-bit length) to data length select flag m.
- ⑤ Set "1" to the CPU reprogramming mode select bit.
- ⑥ Apply VPPH to the CNVss/VPP pin.
- ⑦ Read the CPU reprogramming mode monitor flag to confirm whether the CPU reprogramming mode is valid.
- ⑧ The operation of the flash memory is executed by software-command-writing to the flash command register .

Note: The following are necessary other than this:

- Control for data which is input from the external (serial I/O etc.) and to be programmed to the flash memory
- Initial setting for ports etc.
- Writing to the watchdog timer

< Release procedure >

- ① Apply 0V to the CNVss/VPP pin.
- ② Set the CPU reprogramming mode select bit to "0."

Each software command is explained as follows.

Read command

When "0016" is written to the flash command register, the M37753FFCFP and the M37753FFCHP enter the read mode. The contents of the corresponding address can be read by reading the flash memory (For instance, with the LDA instruction etc.) under this condition.

The read mode is maintained until another command code is written to the flash command register. Accordingly, after setting the read mode once, the contents of the flash memory can continuously be read.

After reset and after the reset command is executed, the read mode is set.

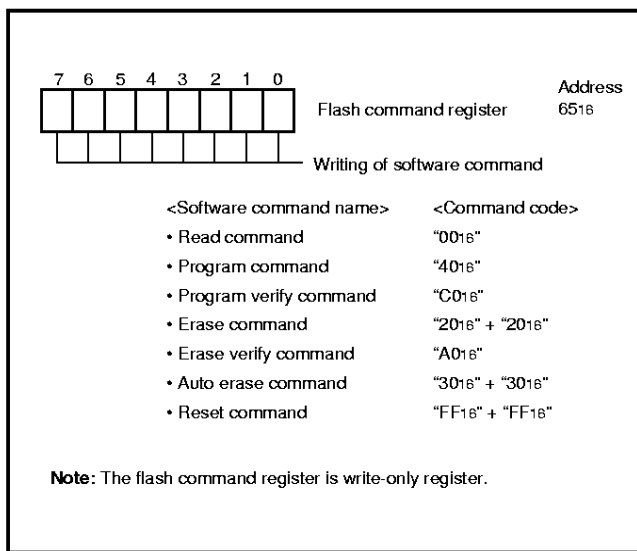


Fig. 22 Flash command register bit configuration

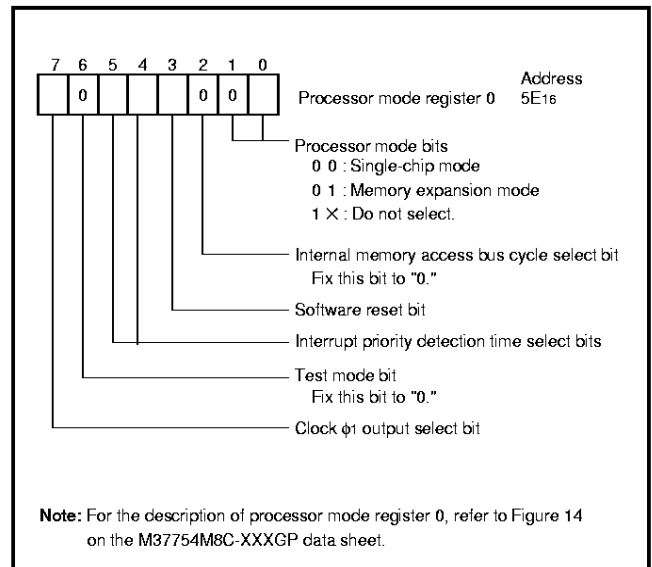


Fig. 23 Processor mode register 0 bit configuration in CPU rewriting mode

PRELIMINARY
 Notice: This is not a final specification.
 Some parametric limits are subject to change.

Program command

When "40₁₆" is written to the flash command register, the M37753FFCFP and the M37753FFCHP enter the program mode.

Subsequently to this, if the instruction (for instance, STA or LDM instruction) for writing byte data in the address to be programmed is executed, the control circuit of the flash memory executes the program. The auto erase/erase/program busy flag of the flash memory control register is set to "1" when the program starts, and becomes "0" when the program is completed. Accordingly, after the write instruction is executed, CPU can recognize the completion of the program by polling this bit.

The programmed area must be specified beforehand by the erase/program area select bits.

During programming, watchdog timer stops with "FFF₁₆" set.

Note: A programming operation is not completed by executing the program command once. Always be sure to execute a program verify command after executing the program command. When the failure is found in this verification, the user must repeatedly execute the program command until the pass. Refer to Figure 24 for the flow chart of the programming.

Program verify command

When "C0₁₆" is written to the flash command register, the M37753FFCFP and the M37753FFCHP enter the program verify mode. Subsequently to this, if the instruction (for instance, LDA instruction) for reading byte data from the address to be verified (i.e., previously programmed address), the contents which has been written to the address actually is read.

CPU compares this read data with data which has been written by the previous program command. In consequence of the comparison, if not agreeing, the operation of "program → program verify" must be executed again.

Erase command

When writing "20₁₆" twice continuously to the flash command register, the flash memory control circuit performs erase to the area specified beforehand by the erase/program area select bits.

Auto erase/erase/program busy flag of the flash memory control register becomes "1" when erase begins, and it becomes "0" when erase completes. Accordingly, CPU can recognize the completion of erase by polling this bit.

Data "00₁₆" must be written to all areas to be erased by the program and the program verify commands before the erase command is executed.

During programming, watchdog timer stops with "FFF₁₆" set.

Note: The erasing operation is not completed by executing the erase command once. Always be sure to execute an erase verify command after executing the erase command. When the failure is found in this verification, the user must repeatedly execute the erase command until the pass. Refer to Figure 24 for the erasing flowchart.

Erase verify command

When "A0₁₆" is written to the flash command register, the M37753FFCFP and the M37753FFCHP enter the erase verify mode. Subsequently to this, if the instruction (for instance, LDA instruction) for reading byte data from the address to be verified, the contents of the address is read.

CPU must erase and verify to all erased areas in a unit of address. If the address of which data is not "FF₁₆" (i.e., data is not erased) is found, it is necessary to discontinue erasure verification there, and execute the operation of "erase → erase verify" again.

Note: By executing the operation of "erase → erase verify" again when the memory not erased is found. It is unnecessary to write data "00₁₆" before erasing in this case.

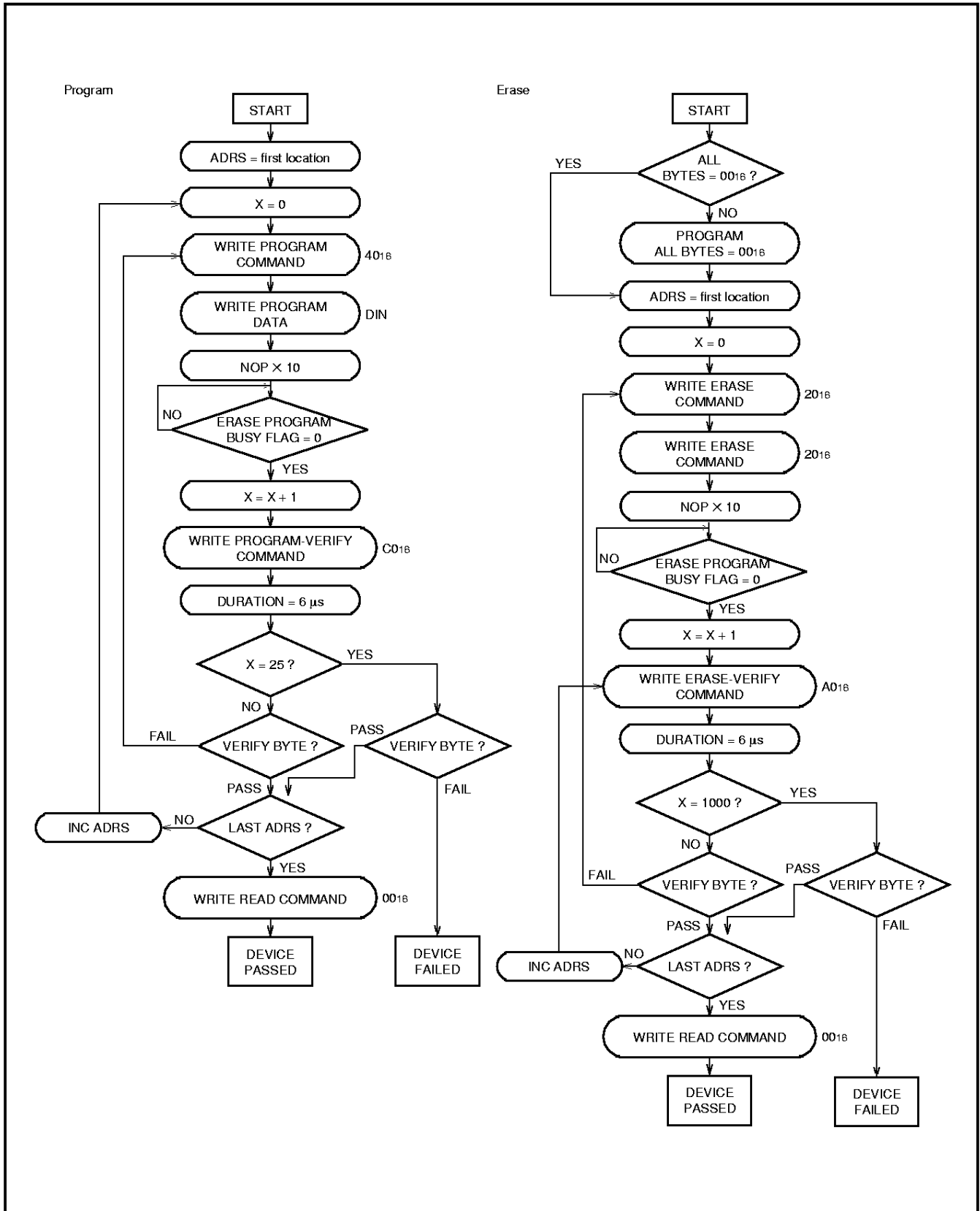


Fig. 24 Flowchart when program/erase/auto erase is executed (1)

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

Auto erase command

When writing "3016" twice continuously to the flash command register, the flash memory control circuit executes the auto erase sequence described below for the area specified beforehand by the erase/program area select bits.

- (1) Data "0016" is written to the area to be erased in the flash memory.
- (2) The erasure is executed.
- (3) The contents of the erased flash memory is erase-verified one by one. When the address which is not erased is found, verification is interrupted, and after the erase command is executed again, erase-verification is operated again.
- (4) When the erasure of all areas specified to be erased, is confirmed by erase-verify-operation, the auto erase command is ended.

The auto erase/erase/program busy flag of the flash memory control register becomes "1" when auto erase starts, and becomes "0" when auto erase completes. Accordingly, CPU can recognize the completion of auto erase by polling this bit.

During auto erase, watchdog timer stops with "FF16" set.

Note: When the flash memory is erased by using the auto erase command, it is unnecessary to execute the erase and erase verify commands. Figure 25 shows the flowchart when auto erase is executed.

DC electric characteristics

Note: The characteristic of the flash memory part are the same as the standard of the parallel I/O mode.

AC electric characteristics

Note: The characteristics are the same as the standards of the microcomputer mode.

Reset command

The reset command is a command to discontinue the program, erase, or the auto erase command on the way. When "FF16" is written to the command register two times continuously after "4016," "2016," or "3016" is written to the flash command register, the program, erase, or auto erase command becomes invalid (reset), and the M37753FFCFP and the M37753FFCHP enters the reset mode. The contents of the memory does not change even if the reset command is executed.

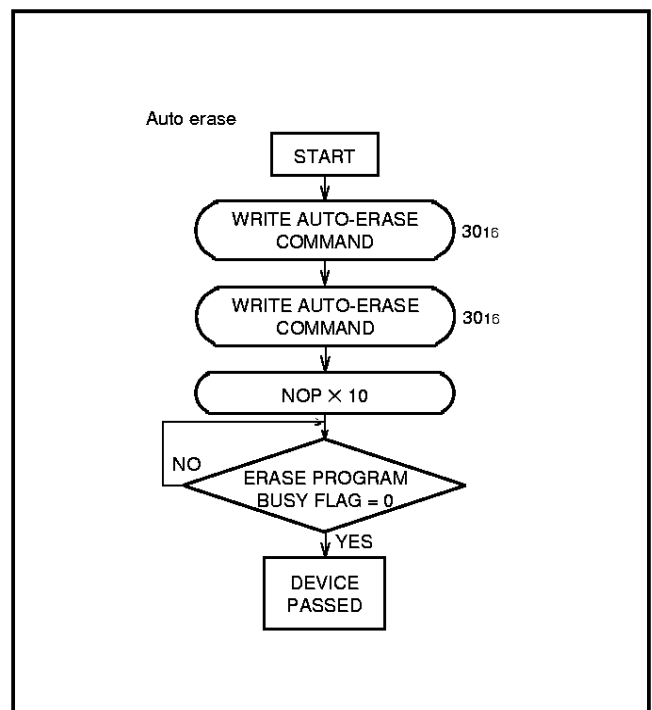


Fig. 25 Flowchart when program/erase/auto erase is executed (2)

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Ratings	Unit
VCC	Power source voltage	-0.3 to 7	V
AVCC	Analog power source voltage	-0.3 to 7	V
VI	Input voltage RESET, CNVSS, BYTE	-0.3 to 12 (Note)	V
VI	Input voltage P00-P07, P10-P17, P20-P27, P30-P33, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87, VREF, XIN	-0.3 to VCC+0.3	V
VO	Output voltage P00-P07, P10-P17, P20-P27, P30-P33, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87, XOUT, E	-0.3 to VCC+0.3	V
Pd	Power dissipation	300	mW
Topr	Operating temperature	-20 to 85	°C
Tstg	Storage temperature	-40 to 150	°C

Note : For the CNVSS pin, this is 12.6V when programming to the flash memory.

RECOMMENDED OPERATING CONDITIONS (VCC = 5 V±10 %, Ta = -20 to 85 °C, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
VCC	Supply voltage	4.5	5.0	5.5	V
AVCC	Analog supply voltage		VCC		V
VSS	Supply voltage		0		V
AVSS	Analog supply voltage		0		V
VIH	High-level input voltage P00-P07, P30-P33, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87, XIN, RESET, CNVSS, BYTE	0.8 VCC		VCC	V
VIH	High-level input voltage P10-P17, P20-P27 (in single-chip mode)	0.8 VCC		VCC	V
VIH	High-level input voltage P10-P17, P20-P27 (in memory expansion mode and microprocessor mode)	0.5 VCC		VCC	V
VIL	Low-level input voltage P00-P07, P30-P33, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87, XIN, RESET, CNVSS, BYTE	0		0.2 VCC	V
VIL	Low-level input voltage P10-P17, P20-P27 (in single-chip mode)	0		0.2 VCC	V
VIL	Low-level input voltage P10-P17, P20-P27 (in memory expansion mode and microprocessor mode)	0		0.16 VCC	V
IOH(peak)	High-level peak output current P00-P07, P10-P17, P20-P27, P30-P33, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87			-10	mA
IOH(avg)	High-level average output current P00-P07, P10-P17, P20-P27, P30-P33, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87			-5	mA
IOL(peak)	Low-level peak output current P00-P07, P10-P17, P20-P27, P30-P33, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87			10	mA
IOL(peak)	Low-level peak output current P50-P55			20	mA
IOL(avg)	Low-level average output current P00-P07, P10-P17, P20-P27, P30-P33, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87			5	mA
IOL(avg)	Low-level average output current P50-P55			15	mA
f(XIN)	External clock frequency input (Note 3)				MHz
	Low-speed running			25	
	High-speed running			40	

Notes 1: Average output current is the average value of a 100 ms interval.

2: The sum of IOL(peak) for ports P0, P1, P2, P3, and P8 must be 80 mA or less, the sum of IOH(peak) for ports P0, P1, P2, P3, and P8 must be 80 mA or less, the sum of IOL(peak) for ports P4, P5, P6, and P7 must be 110 mA or less, the sum of IOH(peak) for ports P4, P5, P6, and P7 must be 80 mA or less.

3: When the clock source select bit is "1," f(XIN)'s maximum limit is 12.5 MHz at low-speed running and is 20 MHz at high-speed running.

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

ELECTRICAL CHARACTERISTICS (V_{CC} = 5 V, V_{SS} = 0 V, T_a = -20 to 85 °C, f(XIN) = 40 MHz (Note))

Symbol	Parameter	Test conditions	Limits			Unit	
			Min.	Typ.	Max.		
V _{OH}	High-level output voltage P00-P07, P10-P17, P20-P27, P30, P31, P33, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87	I _{OH} = -10 mA	3			V	
V _{OH}	High-level output voltage P00-P07, P10-P17, P20-P27, P30, P31, P33,	I _{OH} = -400 μA	4.7			V	
V _{OH}	High-level output voltage P32	I _{OH} = -10 mA I _{OH} = -400 μA	3.1 4.8			V	
V _{OH}	High-level output voltage \bar{E}	I _{OH} = -10 mA I _{OH} = -400 μA	3.4 4.8			V	
V _{OL}	Low-level output voltage P00-P07, P10-P17, P20-P27, P30, P31, P33, P40-P47, P56, P57, P60-P67, P70-P77, P80-P87	I _{OL} = 10 mA			2	V	
V _{OL}	Low-level output voltage P00-P07, P10-P17, P20-P27, P30, P31, P33	I _{OL} = 2 mA			0.45	V	
V _{OL}	Low-level output voltage P32	I _{OL} = 10 mA I _{OL} = 2 mA			1.9 0.43	V	
V _{OL}	Low-level output voltage \bar{E}	I _{OL} = 10 mA I _{OL} = 2 mA			1.6 0.4	V	
V _{OL}	Low-level output voltage P50-P56	I _{OL} = 20 mA I _{OL} = 2 mA			2 0.4	V	
V _{T+} - V _{T-}	Hysteresis HOLD, RDY, TA0IN-TA4IN, TB0IN-TB2IN, INT0-INT4, ADTRG, CTS0, CTS1, CLK0, CLK1, RxD0, RxD1		0.4		1	V	
V _{T+} - V _{T-}	Hysteresis RESET, HOLD, RDY		0.2		0.5	V	
V _{T+} - V _{T-}	Hysteresis XIN		0.1		0.3	V	
I _{IH}	High-level input current P00-P07, P10-P17, P20-P27, P30-P33, P40-P47, P50-P57, P60-P67, P70-P77, P80-P87, XIN, RESET, CNVSS, BYTE	V _I = 5 V			5	μA	
I _{IL}	Low-level input current P00-P07, P10-P17, P20-P27, P30-P33, P40-P47, P50-P53, P60-P67, P70-P77, P81-P87, XIN, RESET, CNVSS, BYTE	V _I = 0 V			-5	μA	
I _{IL}	Low-level input current P54-P57, P80	V _I = 0 V, No pull-up transistor V _I = 0 V, Pull-up transistor used			-5 -1.0	μA mA	
VRAM	RAM hold voltage	When clock is stopped.	2			V	
I _{CC}	Power supply current (target value)	Output-only pin is open and other pins are V _{SS} during reset.	f(XIN) = 40 MHz, square waveform (Note)		25	50	mA
			T _a = 25 °C when clock is stopped.			1	μA
			T _a = 85 °C when clock is stopped.			20	μA

Note: f(XIN) = 20 MHz when the clock source select bit = "1."

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

A-D CONVERTER CHARACTERISTICS

(VCC = AVCC = 5 V ± 10 %, VSS = AVSS = 0 V, Ta = -20 to 85 °C, the clock source select bit = 0, unless otherwise noted)

Symbol	Parameter	Test conditions		Limits			Unit	
				Min.	Typ.	Max.		
—	Resolution	VREF = VCC		A-D converter selected			10	Bits
				Comparator selected			$\frac{1}{256} V_{REF}$	V
—	Absolute accuracy	VREF = VCC	250 kHz ≤ φAD ≤ 12.5 MHz	10-bit mode			± 3	LSB
				8-bit mode			± 2	LSB
				Comparator			± 40	mV
				250 kHz ≤ φAD ≤ 20 MHz (Note 1)	8-bit mode			± 3
				Comparator			± 60	mV
RLADDER	Ladder resistance	VREF = VCC			5		20	kΩ
tCONV	Conversion time	High-speed running (f(XIN) ≤ 40 MHz) (Note 2)	φAD = f(XIN)/4 selected	10-bit mode	5.9			μs
				8-bit mode	4.9			
			φAD = f(XIN)/2 selected	Comparator	1.4			
				8-bit mode	2.45			
			Low-speed running (f(XIN) ≤ 25 MHz) (Note 2)	Comparator	0.7			
				10-bit mode	4.72			
		8-bit mode	3.92					
		Comparator	1.12					
VREF	Reference voltage			2.7			VCC	V
VIA	Analog input voltage			0			VREF	V

Notes 1: This is valid when the high-speed running is selected.

2: When the clock source select bit = 1, f(XIN) is 20 MHz or less at the high-speed running, and f(XIN) is 12.5 MHz or less at the low-speed running.

D-A CONVERTER CHARACTERISTICS

(VCC = 5 V, VSS = AVSS = 0 V, VREF = 5 V, Ta = -20 to 85 °C, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
—	Resolution				8	Bits
—	Absolute accuracy				± 1.0	%
tsu	Set time				3	μs
RO	Output resistance		1	2.5	4	kΩ
IVREF	Reference power supply input current	(Note)			3.2	mA

Note: The test conditions are as follows:

- One D-A converter is used.
- The D-A register value of the unused D-A converter is "0016."
- The reference power supply input current of the ladder resistance of the A-D converter is excluded.

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

PERIPHERAL DEVICE INPUT/OUTPUT TIMING (VCC = 5 V±10 %, VCC = 0 V, Ta = -20 to 85 °C, unless otherwise noted)

- * If the values depends on external clock frequency f(XIN), formulas of the limits are shown below. Also, the values at f(XIN) = 40 MHz in high-speed running and at f(XIN) = 25 MHz in low-speed running are shown in (). At this time, the clock source select bit is "0." When the clock source select bit is "1", regard f(XIN) in tables as 2·f(XIN).
- * The rise and fall time of input signal must be 100 ns or less respectively, unless otherwise noted.

Timer A input (Count input in event counter mode)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tc(TA)	TAiIN input cycle time	80		ns
tw(TAH)	TAiIN input high-level pulse width	40		ns
tw(TAL)	TAiIN input low-level pulse width	40		ns

Timer A input (Gating input in timer mode)

Symbol	Parameter		Limits		Unit
			Min.	Max.	
tc(TA)	TAiIN input cycle time	f(XIN) ≤ 40 MHz	$\frac{16 \times 10^9}{f(XIN)}$ (400)		ns
		(XIN) ≤ 25 MHz	$\frac{8 \times 10^9}{f(XIN)}$ (320)		ns
tw(TAH)	TAiIN input high-level pulse width	f(XIN) ≤ 40 MHz	$\frac{8 \times 10^9}{f(XIN)}$ (200)		ns
		f(XIN) ≤ 25 MHz	$\frac{4 \times 10^9}{f(XIN)}$ (160)		ns
tw(TAL)	TAiIN input low-level pulse width	f(XIN) ≤ 40 MHz	$\frac{8 \times 10^9}{f(XIN)}$ (200)		ns
		f(XIN) ≤ 25 MHz	$\frac{4 \times 10^9}{f(XIN)}$ (160)		ns

Note : The TAiIN input cycle time requires 4 or more cycles of count source. The TAiIN input high-level pulse width and the TAiIN input low-level pulse width respectively require 2 or more cycles of the count source. The limits in the table are the values when the count source is f(XIN)/4 in high-speed running (f(XIN) ≤ 40 MHz) and when the count source is f(XIN)/2 in low-speed running (f(XIN) ≤ 25 MHz). At this time, the clock source select bit is "0."

Timer A input (External trigger input in one-shot pulse mode)

Symbol	Parameter		Limits		Unit
			Min.	Max.	
tc(TA)	TAiIN input cycle time	f(XIN) ≤ 40 MHz	$\frac{8 \times 10^9}{f(XIN)}$ (200)		ns
		f(XIN) ≤ 25 MHz	$\frac{4 \times 10^9}{f(XIN)}$ (160)		ns
tw(TAH)	TAiIN input high-level pulse width		80		ns
tw(TAL)	TAiIN input low-level pulse width		80		ns

Timer A input (External trigger input in pulse width modulation mode)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tw(TAH)	TAiIN input high-level pulse width	80		ns
tw(TAL)	TAiIN input low-level pulse width	80		ns

Timer A input (Up-down input in event counter mode)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tc(UP)	TAiOUT input cycle time	2000		ns
tw(UPH)	TAiOUT input high-level pulse width	1000		ns
tw(UPL)	TAiOUT input low-level pulse width	1000		ns
tsu(UP-TiN)	TAiOUT input setup time	400		ns
th(TiN-UP)	TAiOUT input hold time	400		ns

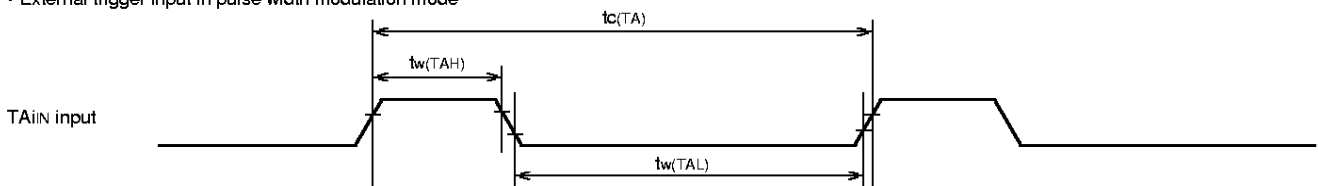
PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

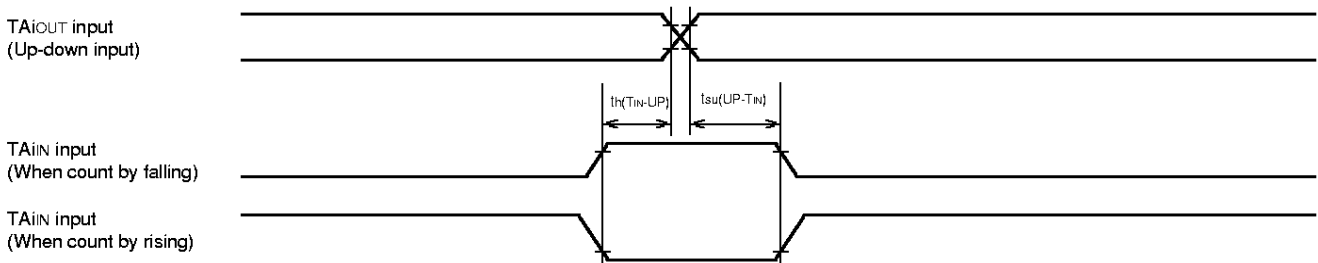
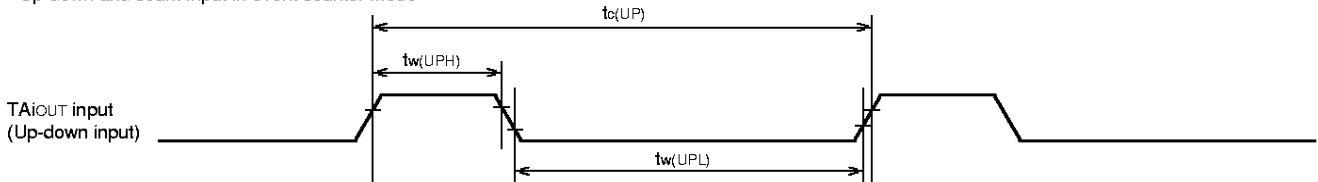
Timer A input (Two-phase pulse input in event counter mode)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_c(TA)$	TAiIN input cycle time	800		ns
$t_{su}(TA_{jIN}-TA_{jOUT})$	TAjIN input setup time	200		ns
$t_{su}(TA_{jOUT}-TA_{jIN})$	TAjOUT input setup time	200		ns

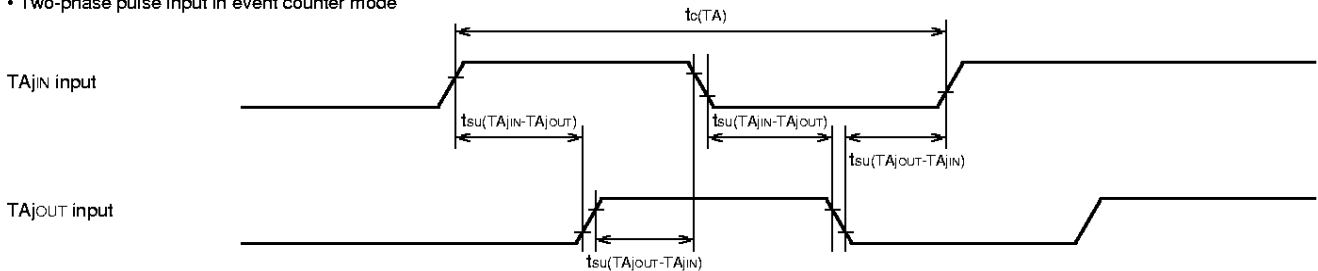
- Count input in event counter mode
- Gating input in timer mode
- External trigger input in one-shot pulse mode
- External trigger input in pulse width modulation mode



- Up-down and count input in event counter mode



- Two-phase pulse input in event counter mode



Test conditions

- $V_{CC} = 5V \pm 10\%$
- Input timing voltage : $V_{IL} = 1.0V$, $V_{IH} = 4.0V$

PRELIMINARY
Notice: This is not a final specification.
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SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

Timer B input (Count input in event counter mode)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tc(TB)	TBiIN input cycle time (one edge count)	80		ns
tw(TBH)	TBiIN input high-level pulse width (one edge count)	40		ns
tw(TBL)	TBiIN input low-level pulse width (one edge count)	40		ns
tc(TB)	TBiIN input cycle time (both edge count)	160		ns
tw(TBH)	TBiIN input high-level pulse width (both edge count)	80		ns
tw(TBL)	TBiIN input low-level pulse width (both edge count)	80		ns

Timer B input (Pulse period measurement mode)

Symbol	Parameter		Limits		Unit
			Min.	Max.	
tc(TB)	TBiIN input cycle time	f(XIN) ≤ 40 MHz	$\frac{16 \times 10^9}{f(XIN)}$ (400)		ns
		f(XIN) ≤ 25 MHz	$\frac{8 \times 10^9}{f(XIN)}$ (320)		ns
tw(TBH)	TBiIN input high-level pulse width	f(XIN) ≤ 40 MHz	$\frac{8 \times 10^9}{f(XIN)}$ (200)		ns
		f(XIN) ≤ 25 MHz	$\frac{4 \times 10^9}{f(XIN)}$ (160)		ns
tw(TBL)	TBiIN input low-level pulse width	f(XIN) ≤ 40 MHz	$\frac{8 \times 10^9}{f(XIN)}$ (200)		ns
		f(XIN) ≤ 25 MHz	$\frac{4 \times 10^9}{f(XIN)}$ (160)		ns

Note : The TBiIN input cycle time requires 4 or more cycles of count source. The TBiIN input high-level pulse width and the TBiIN input low-level pulse width respectively require 2 or more cycles of the count source. The limits in the table are the values when the count source is f(XIN)/4 in high-speed running (f(XIN) ≤ 40 MHz) and when the count source is f(XIN)/2 in low-speed running (f(XIN) ≤ 25 MHz). At this time, the clock source select bit is "0."

Timer B input (Pulse width measurement mode)

Symbol	Parameter		Limits		Unit
			Min.	Max.	
tc(TB)	TBiIN input cycle time	f(XIN) ≤ 40 MHz	$\frac{16 \times 10^9}{f(XIN)}$ (400)		ns
		f(XIN) ≤ 25 MHz	$\frac{8 \times 10^9}{f(XIN)}$ (320)		ns
tw(TBH)	TBiIN input high-level pulse width	f(XIN) ≤ 40 MHz	$\frac{8 \times 10^9}{f(XIN)}$ (200)		ns
		f(XIN) ≤ 25 MHz	$\frac{4 \times 10^9}{f(XIN)}$ (160)		ns
tw(TBL)	TBiIN input low-level pulse width	f(XIN) ≤ 40 MHz	$\frac{8 \times 10^9}{f(XIN)}$ (200)		ns
		f(XIN) ≤ 25 MHz	$\frac{4 \times 10^9}{f(XIN)}$ (160)		ns

Note : The TBiIN input cycle time requires 4 or more cycles of count source. The TBiIN input high-level pulse width and the TBiIN input low-level pulse width respectively require 2 or more cycles of the count source. The limits in the table are the values when the count source is f(XIN)/4 in high-speed running (f(XIN) ≤ 40 MHz) and when the count source is f(XIN)/2 in low-speed running (f(XIN) ≤ 25 MHz). At this time, the clock source select bit is "0."

A-D trigger input

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tc(AD)	ADTRG input cycle time (minimum allowable trigger)	1000		ns
tw(ADL)	ADTRG input low-level pulse width	125		ns

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

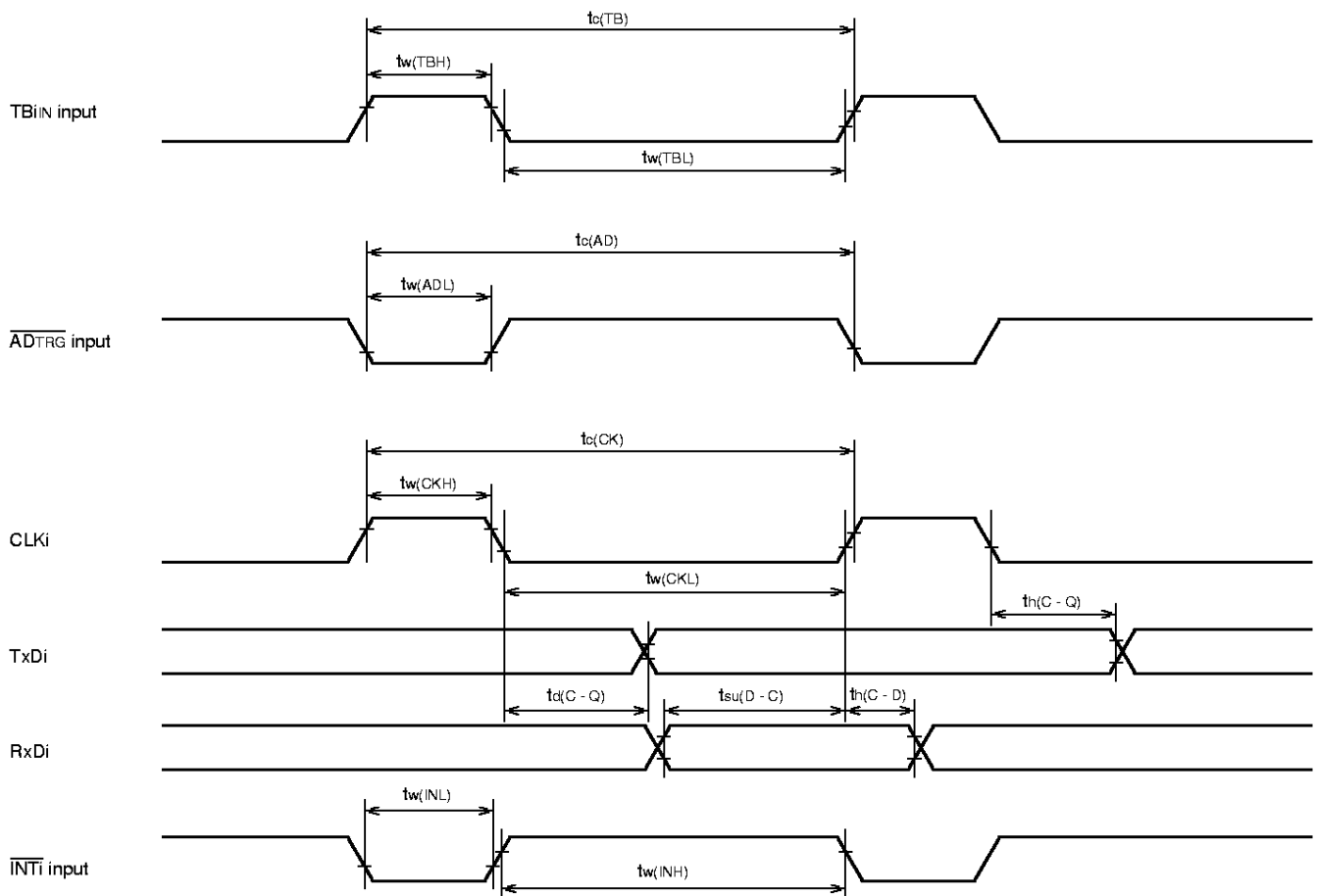
SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

Serial I/O

Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	200		ns
$t_w(CKH)$	CLKi input high-level pulse width	100		ns
$t_w(CKL)$	CLKi input low-level pulse width	100		ns
$t_d(C-Q)$	TxDi output delay time		80	ns
$t_h(C-Q)$	TxDi hold time	0		ns
$t_{su}(D-C)$	RxDi input setup time	20		ns
$t_h(C-D)$	RxDi input hold time	90		ns

External interrupt \overline{INT}_i input

Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_w(INH)$	\overline{INT}_i input high-level pulse width	250		ns
$t_w(INL)$	\overline{INT}_i input low-level pulse width	250		ns



Test conditions

- $V_{CC} = 5 V \pm 10\%$
- Input timing voltage : $V_{IL} = 1.0 V, V_{IH} = 4.0 V$
- Output timing voltage : $V_{OL} = 0.8 V, V_{OH} = 2.0 V, C_L = 100 pF$

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

READY, HOLD TIMING

Timing requirements ($V_{CC} = 5 V \pm 10\%$, $V_{SS} = 0 V$, $T_a = -20$ to $85\text{ }^\circ\text{C}$, $f(XIN) = 40$ MHz when the clock source select bit = "0"* , unless otherwise noted)

* The rise and fall time of input signal must be 100 ns or less respectively, unless otherwise noted.

Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_{su}(RDY-\phi1)$	RDY input setup time	42		ns
$t_{su}(HOLD-\phi1)$	HOLD input setup time	42		ns
$t_h(\phi1-RDY)$	RDY input hold time	0		ns
$t_h(\phi1-HOLD)$	HOLD input hold time	0		ns

*: $f(XIN) = 20$ MHz when the clock source select bit = "1".

Switching characteristics ($V_{CC} = 5 V \pm 10\%$, $V_{SS} = 0 V$, $T_a = -20$ to $85\text{ }^\circ\text{C}$, $f(XIN) = 40$ MHz when the clock source select bit = "0"* , unless otherwise noted)

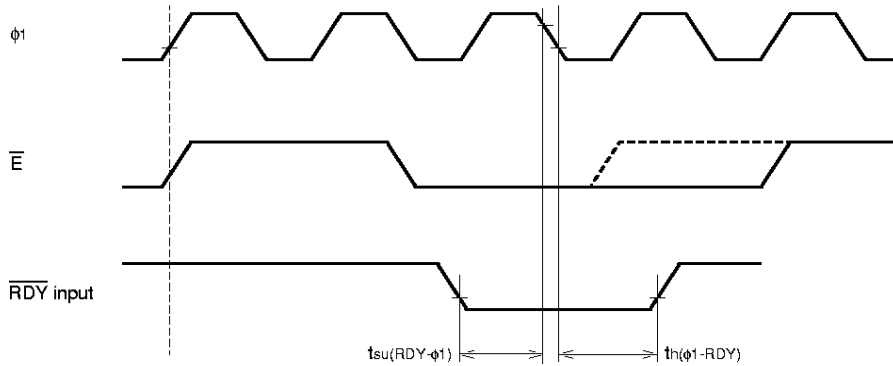
Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_d(\phi1-HLDA)$	HLDA output delay time		50	ns
$t_{pxz}(HLDA-R/WZ)$	Floating start delay time (at hold state)		50	ns
$t_{pxz}(HLDA-BHEZ)$	Floating start delay time (at hold state)		50	ns
$t_{pxz}(HLDA-AZ)$	Floating start delay time (at hold state)		50	ns
$t_{pxz}(HLDA-A/DZ)$	Floating start delay time (at hold state)		50	ns
$t_{pzx}(HLDA-R/WZ)$	Floating release delay time (at hold state)	0		ns
$t_{pzx}(HLDA-BHEZ)$	Floating release delay time (at hold state)	0		ns
$t_{pzx}(HLDA-AZ)$	Floating release delay time (at hold state)	0		ns
$t_{pzx}(HLDA-A/DZ)$	Floating release delay time (at hold state)	0		ns

*: $f(XIN) = 20$ MHz when the clock source select bit = "1".

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

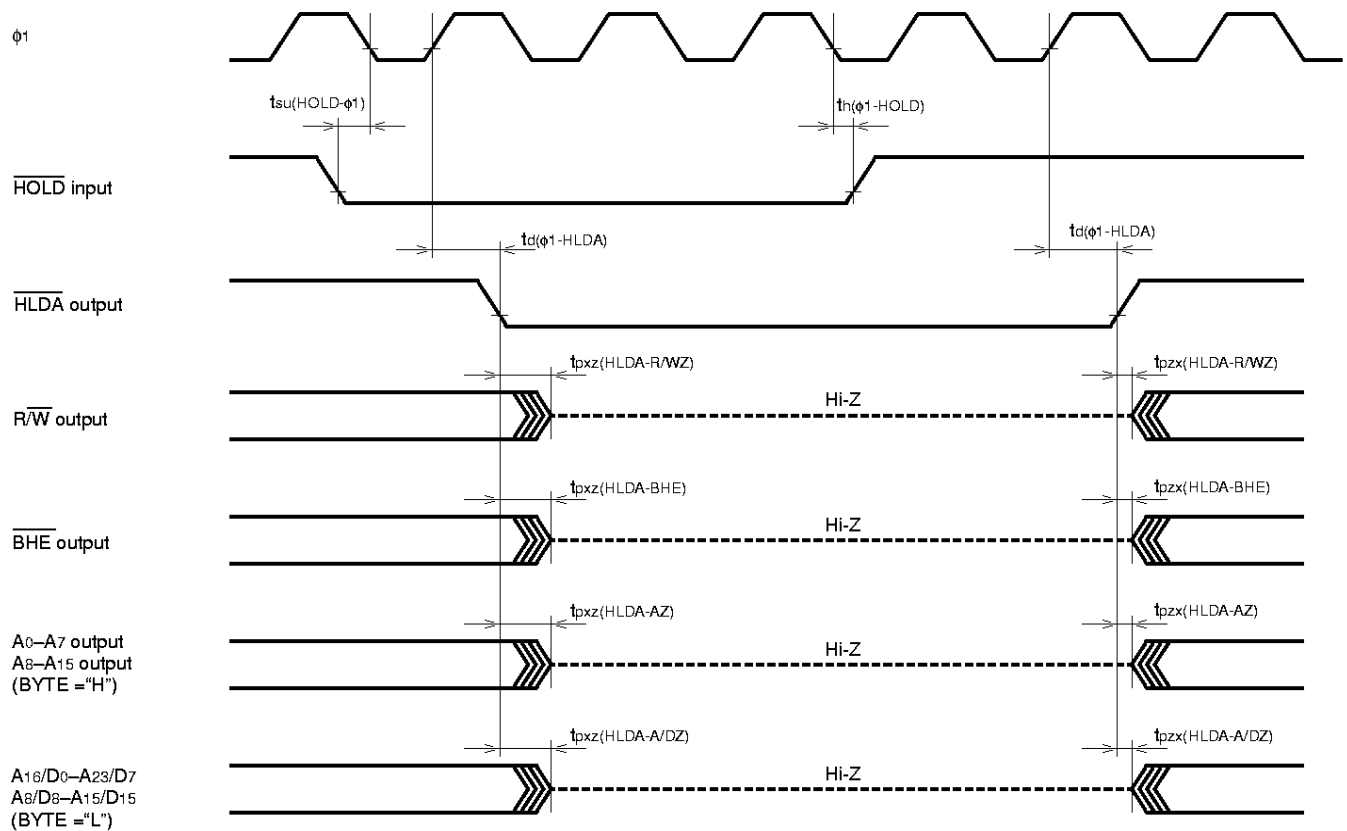
SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

$\overline{\text{RDY}}$ input (when 3- ϕ access in high-speed running)



* $\overline{\text{RDY}}$ input is always sampled at the falling edge of ϕ_1 just before the $\overline{\text{E}}$ signal's rise regardless of the bus mode and the number of waits.

$\overline{\text{HOLD}}$ input



Test conditions

- $V_{CC} = 5 V \pm 10 \%$
- $\overline{\text{RDY}}$ input, $\overline{\text{HOLD}}$ input : $V_{IL} = 1.0 V$, $V_{IH} = 4.0 V$
- HLDA output : $V_{OL} = 0.8 V$, $V_{OH} = 2.0 V$, $C_L = 100 pF$

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

Timing requirements ($V_{CC} = 5 V \pm 10 \%$, $V_{SS} = 0 V$, $T_a = -20$ to $85 \text{ }^\circ\text{C}$, $f(XIN) = 40 \text{ MHz}$ when the clock source select bit = "0"*, unless otherwise noted)

* The rise and fall time of input signal must be 100 ns or less respectively, unless otherwise noted.

Single-chip mode

Symbol	Parameter	Limits		Unit
		Min.	Max.	
t_c	External clock input cycle time (Note 1)	25		ns
$t_{w(H)}$	External clock input high-level pulse width (Note 2)	$t_c/2 - 8$		ns
$t_{w(L)}$	External clock input low-level pulse width (Note 2)	$t_c/2 - 8$		ns
t_r	External clock rise time		8	ns
t_f	External clock fall time		8	ns
$t_{su}(PiD-E)$	Port Pi input setup time ($i = 0-8$)	60		ns
$t_{h}(E-PiD)$	Port Pi input hold time ($i = 0-8$)	0		ns

*: $f(XIN) = 20 \text{ MHz}$ when the clock source select bit = "1"

Notes 1: When the clock source select bit = "1", t_c 's minimum limit is 50 ns.

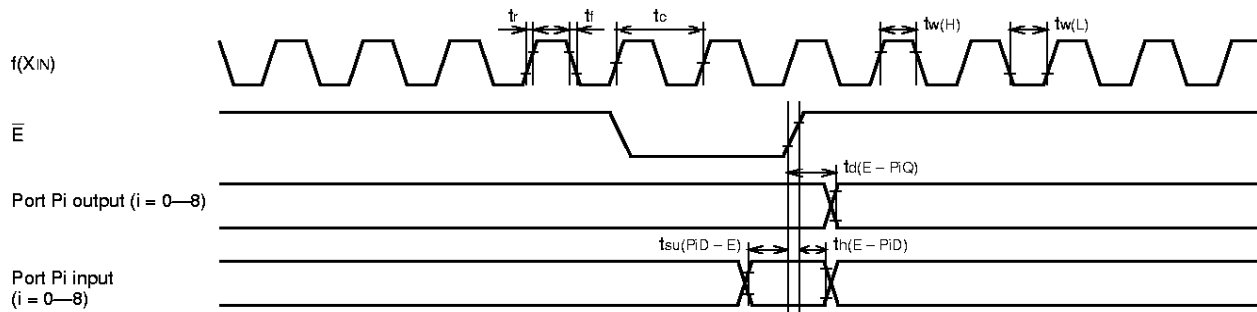
2: When the clock source select bit = "1", set $t_{w(H)}/t_c$ and $t_{w(L)}/t_c$ ratios to 45 to 55 %.

Switching characteristics ($V_{CC} = 5 V \pm 10 \%$, $V_{SS} = 0 V$, $T_a = -20$ to $85 \text{ }^\circ\text{C}$, $f(XIN) = 40 \text{ MHz}$ when the clock source select bit = "0"*, unless otherwise noted)

(Single-chip mode)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
$t_{d}(E-PiQ)$	Port Pi data output delay time ($i = 0-8$)		60	ns

*: $f(XIN) = 20 \text{ MHz}$ when the clock source select bit = "1"



Test conditions

- $V_{CC} = 5 V \pm 10 \%$
- Input timing voltage : $V_{IL} = 1.0 V$, $V_{IH} = 4.0 V$
- Output timing voltage : $V_{OL} = 0.8 V$, $V_{OH} = 2.0 V$, $C_L = 100 \text{ pF}$

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

Timing requirements ($V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V$, $T_a = -20$ to $85\text{ }^\circ\text{C}$, $f(XIN) = 25\text{ MHz}$ when the clock source select bit = "0"[※], unless otherwise noted)

* The rise and fall time of input signal must be 100 ns or less respectively, unless otherwise noted.

Memory expansion and Microprocessor mode : Low-speed running

Symbol	Parameter	Limits		Unit
		Min.	Max.	
t_c	External clock input cycle time (Note 1)	40		ns
$t_w(H)$	External clock input high-level pulse width (Note 2)	$t_c/2 - 8$		ns
$t_w(L)$	External clock input low-level pulse width (Note 2)	$t_c/2 - 8$		ns
t_r	External clock rise time		8	ns
t_f	External clock fall time		8	ns
$t_{su}(D-E)$	Data input setup time	30		ns
$t_{su}(PiD-E)$	Port Pi input setup time ($i = 4-8$)	60		ns
$t_h(E-D)$	Data input hold time	0		ns
$t_h(E-PiD)$	Port Pi input hold time ($i = 4-8$)	0		ns
$t_{su}(An/A-D)$	Data setup time with address stabilized (Note 3)		55 (2- ϕ access)	ns
			135 (3- ϕ access)	
			215 (4- ϕ access)	

*: $f(XIN) = 12.5\text{ MHz}$ when the clock source select bit = "1"

Notes 1: When the clock source select bit = "1", t_c 's minimum limit is 80 ns.

2: When the clock source select bit = "1", set $t_w(H)/t_c$ and $t_w(L)/t_c$ ratios to 45 to 55 %.

3: Since the values depend on external clock input frequency $f(XIN)$, calculate them using the bus timing data formula on the page after the next page.

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

Switching characteristics ($V_{CC} = 5 V \pm 10\%$, $V_{SS} = 0 V$, $T_a = -20$ to $85\text{ }^\circ\text{C}$, $f(XIN) = 25\text{ MHz}$ when the clock source select bit = "0"* , unless otherwise noted)

Memory expansion and Microprocessor mode : Low-speed running

Symbol	Parameter	2- ϕ access		3- ϕ access		4- ϕ access		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_w(\phi H), t_w(\phi L)$	ϕ high-level pulse width, ϕ low-level pulse width (Note)	20		20		20		ns
$t_d(E-\phi 1)$	$\phi 1$ output delay time	-12	7	-12	7	-12	7	ns
$t_w(EL)$	\bar{E} low-level pulse width (Note)	55		135		135		ns
$t_d(A_n-E)$	Address output delay time (Note)	12		12		92		ns
$t_d(E-DQ)$	Data output delay time		35		35		35	ns
$t_{pxz}(E-DZ)$	Floating start delay time		5		5		5	ns
$t_d(A-E)$	Address output delay time (Note)	12		12		92		ns
$t_d(A-ALE)$	Address output delay time (Note)	5		5		52		ns
$t_d(E-ALE)$	ALE output delay time (Note)	20		20		20		ns
$t_d(ALE-E)$	ALE output delay time	4		4		4		ns
$t_w(ALE)$	ALE pulse width (Note)	22		22		62		ns
$t_d(BHE-E)$	\bar{BHE} output delay time (Note)	15		15		95		ns
$t_d(R/\bar{W}-E)$	R/\bar{W} output delay time (Note)	15		15		95		ns
$t_h(E-A_n)$	Address hold time (Note)	10		10		10		ns
$t_h(ALE-A)$	Address hold time	9		9		25 (Note)		ns
$t_h(E-DQ)$	Data hold time (Note)	18		18		18		ns
$t_{pzz}(E-DZ)$	Floating release delay time (Note)	18		18		18		ns
$t_h(E-BHE)$	\bar{BHE} hold time (Note)	10		10		10		ns
$t_h(E-R/\bar{W})$	R/\bar{W} hold time (Note)	10		10		10		ns
$t_d(E-PiQ)$	Port Pi data output delay time ($i = 4-8$)		60		60		60	ns

*: $f(XIN) = 12.5\text{ MHz}$ when the clock source select bit = "1"

Note: Since the values depend on external clock input frequency $f(XIN)$, calculate them using the bus timing data formula on the next page.

The value of $t_h(ALE-A)$ depends on $f(XIN)$ only when 4- ϕ access is performed.

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

Bus timing data formulas

Memory expansion and Microprocessor mode : Low-speed running ($V_{CC} = 5 V \pm 10 \%$, $V_{SS} = 0 V$, $T_a = -20$ to $85 \text{ }^\circ\text{C}$, $f(XIN) \leq 25 \text{ MHz}$ when the clock source select bit = "0"* , unless otherwise noted)

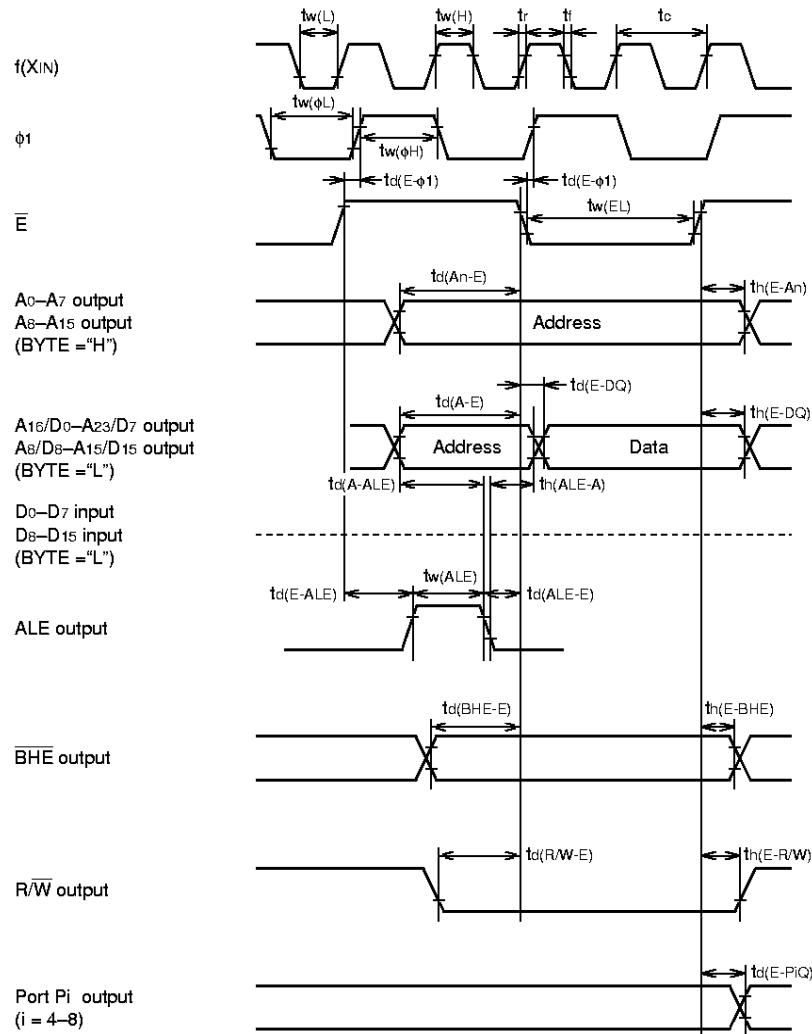
Symbol	Parameter	2- ϕ access	3- ϕ access	4- ϕ access	Unit
$t_{su}(A_n/A-D)$	Data setup time with address stabilized	$\frac{3 \times 10^9}{f(XIN)} - 65$	$\frac{5 \times 10^9}{f(XIN)} - 65$	$\frac{7 \times 10^9}{f(XIN)} - 65$	ns
$t_w(\phi H), t_w(\phi L)$	ϕ high-level pulse width, ϕ low-level pulse width	$\frac{1 \times 10^9}{f(XIN)} - 20$	←	←	ns
$t_w(EL)$	\bar{E} low-level pulse width	$\frac{2 \times 10^9}{f(XIN)} - 25$	$\frac{4 \times 10^9}{f(XIN)} - 25$	←	ns
$t_d(A_n-E)$	Address output delay time	$\frac{1 \times 10^9}{f(XIN)} - 28$	←	$\frac{3 \times 10^9}{f(XIN)} - 28$	ns
$t_d(A-E)$	Address output delay time	$\frac{1 \times 10^9}{f(XIN)} - 28$	←	$\frac{3 \times 10^9}{f(XIN)} - 28$	ns
$t_d(A-ALE)$	Address output delay time	$\frac{1 \times 10^9}{f(XIN)} - 35$	←	$\frac{2 \times 10^9}{f(XIN)} - 28$	ns
$t_d(E-ALE)$	ALE output delay time	$\frac{1 \times 10^9}{f(XIN)} - 20$	←	←	ns
$t_w(ALE)$	ALE pulse width	$\frac{1 \times 10^9}{f(XIN)} - 18$	←	$\frac{2 \times 10^9}{f(XIN)} - 18$	ns
$t_d(BHE-E)$	\bar{BHE} output delay time	$\frac{1 \times 10^9}{f(XIN)} - 25$	←	$\frac{3 \times 10^9}{f(XIN)} - 25$	ns
$t_d(R/W-E)$	$\bar{R/W}$ output delay time	$\frac{1 \times 10^9}{f(XIN)} - 25$	←	$\frac{3 \times 10^9}{f(XIN)} - 25$	ns
$t_h(E-A_n)$	Address hold time	$\frac{1 \times 10^9}{f(XIN)} - 30$	←	←	ns
$t_h(ALE-A)$	Address hold time	—	—	$\frac{1 \times 10^9}{f(XIN)} - 15$	ns
$t_h(E-DQ)$	Data hold time	$\frac{1 \times 10^9}{f(XIN)} - 22$	←	←	ns
$t_{pzx}(E-DZ)$	Floating release delay time	$\frac{1 \times 10^9}{f(XIN)} - 22$	←	←	ns
$t_d(E-BHE)$	\bar{BHE} hold time	$\frac{1 \times 10^9}{f(XIN)} - 30$	←	←	ns
$t_d(E-R/W)$	$\bar{R/W}$ hold time	$\frac{1 \times 10^9}{f(XIN)} - 30$	←	←	ns

*: $f(XIN) \leq 12.5 \text{ MHz}$ when the clock source select bit = "1"

Note: When the clock source select bit is "1", regard $f(XIN)$ in tables as $2 \cdot f(XIN)$.

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

(when 2- ϕ access in low-speed running <Write>)



Test conditions (except Port Pi, f(XIN))

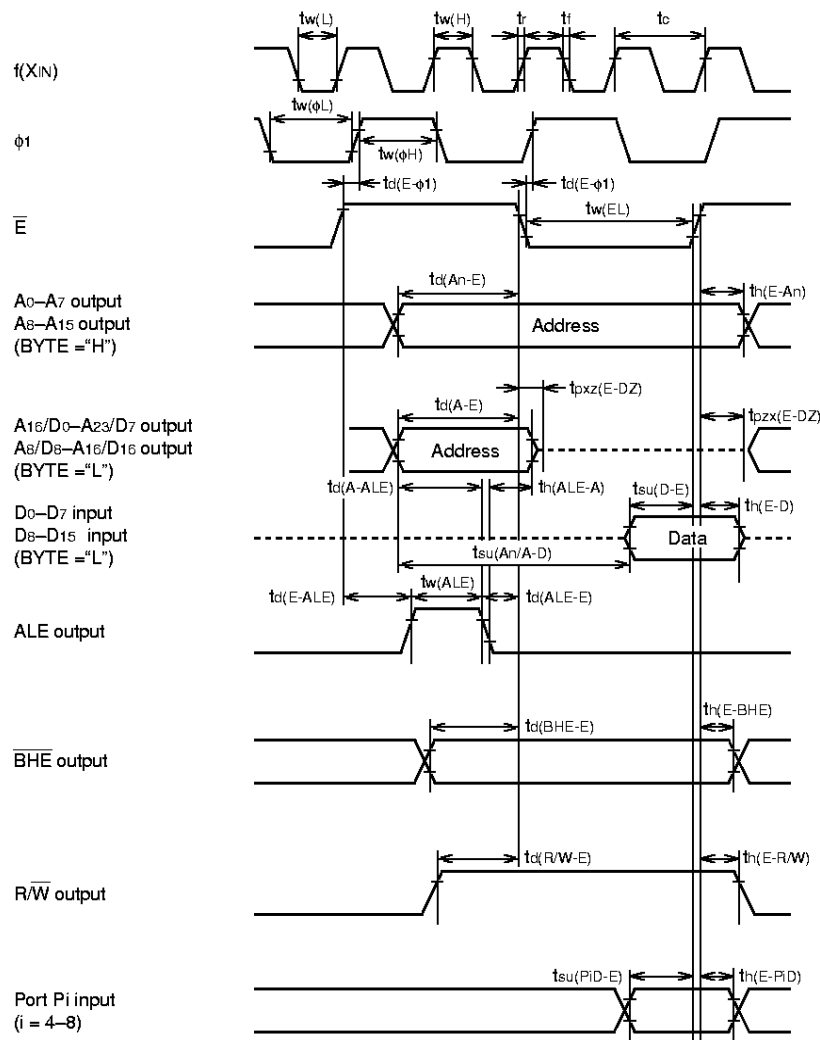
- $V_{CC} = 5V \pm 10\%$
- Output timing voltage : $V_{OL} = 0.8V$, $V_{OH} = 2.0V$, $C_L = 100pF$
- Data input : $V_{IL} = 0.8V$, $V_{IH} = 2.5V$

Test conditions (Port Pi, f(XIN))

- $V_{CC} = 5V \pm 10\%$
- Input timing voltage : $V_{IL} = 1.0V$, $V_{IH} = 4.0V$
- Output timing voltage : $V_{OL} = 0.8V$, $V_{OH} = 2.0V$, $C_L = 100pF$

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

(when 2- ϕ access in low-speed running <Read>)



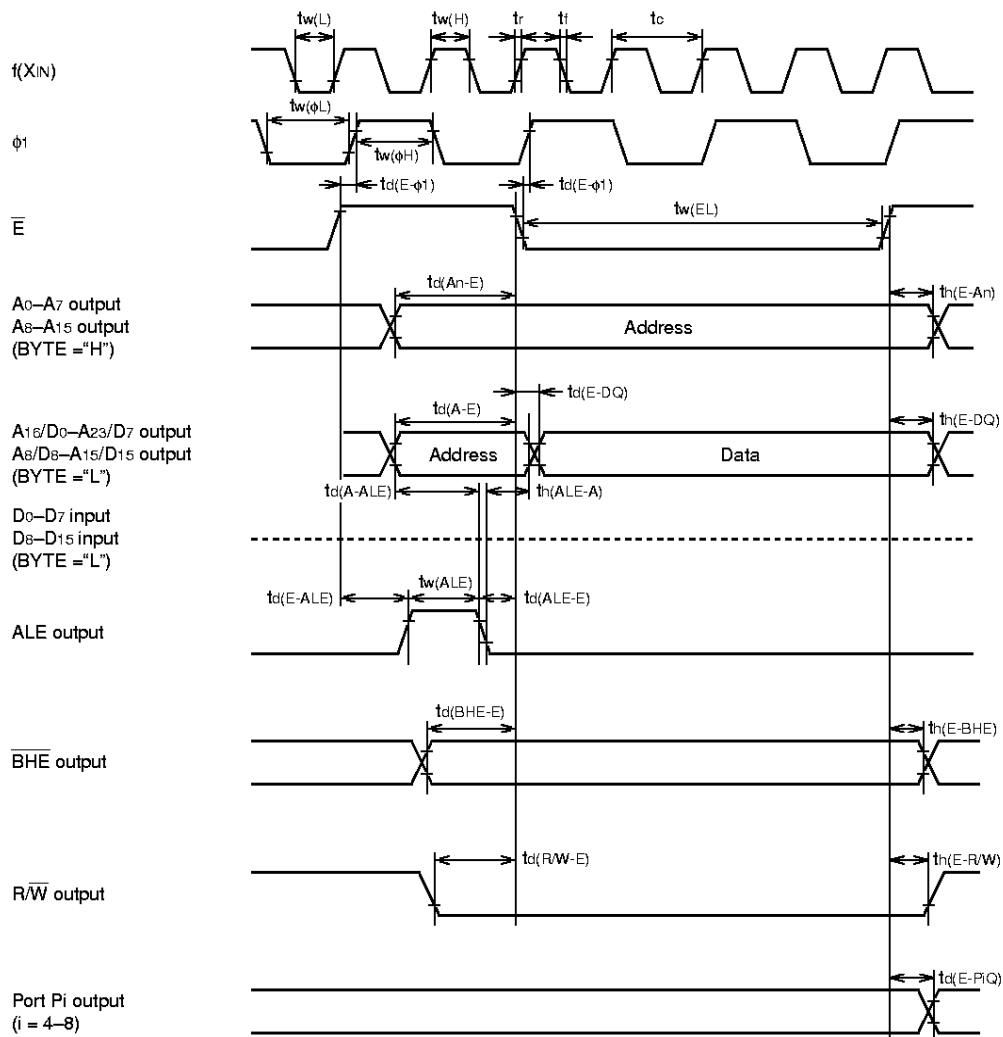
Test conditions (except Port Pi, $f(XIN)$)

- $V_{CC} = 5V \pm 10\%$
- Output timing voltage : $V_{OL} = 0.8V$, $V_{OH} = 2.0V$, $C_L = 100pF$
- Data input : $V_{IL} = 0.8V$, $V_{IH} = 2.5V$

Test conditions (Port Pi, $f(XIN)$)

- $V_{CC} = 5V \pm 10\%$
- Input timing voltage : $V_{IL} = 1.0V$, $V_{IH} = 4.0V$
- Output timing voltage : $V_{OL} = 0.8V$, $V_{OH} = 2.0V$, $C_L = 100pF$

(when 3- ϕ access in low-speed running <Write>)



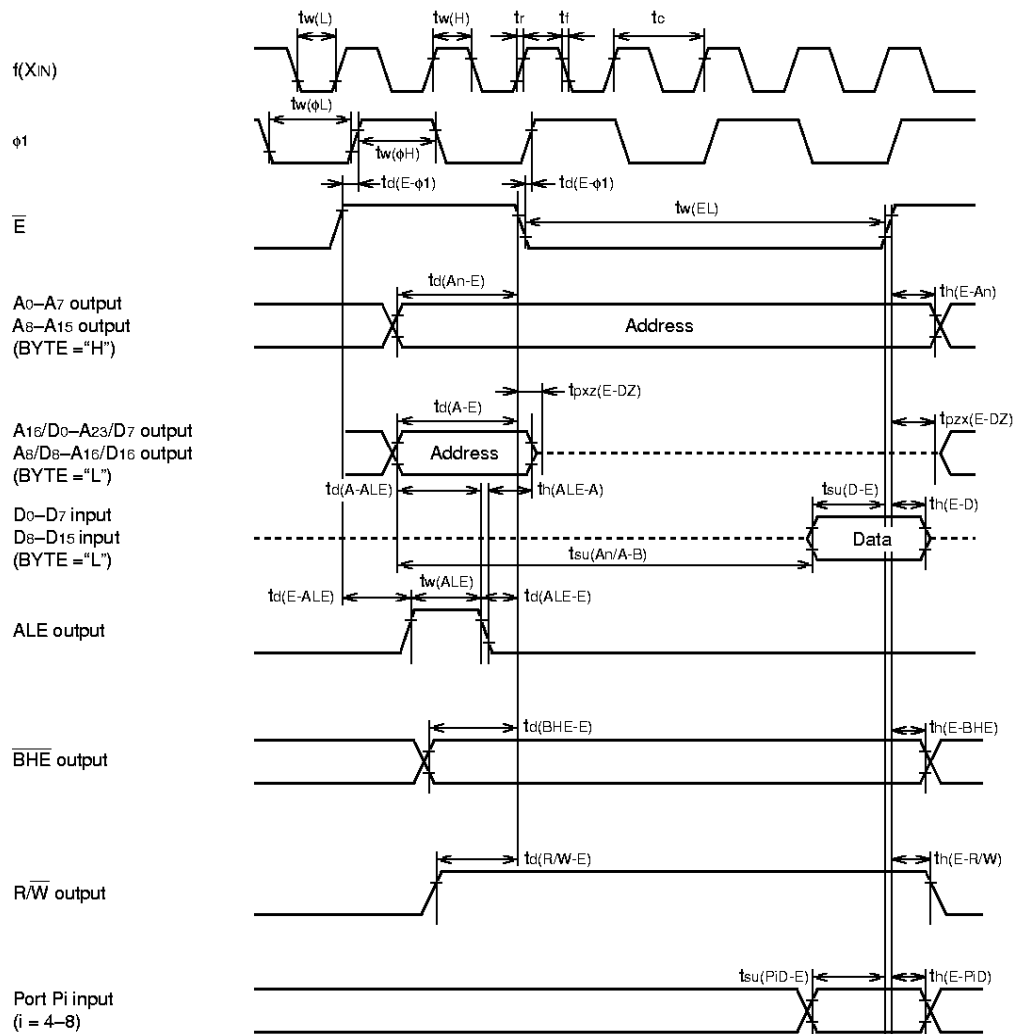
Test conditions (except Port Pi, $f(XIN)$)

- $V_{CC} = 5 V \pm 10 \%$
- Output timing voltage : $V_{OL} = 0.8 V$, $V_{OH} = 2.0 V$, $C_L = 100 pF$
- Data input : $V_{IL} = 0.8 V$, $V_{IH} = 2.5 V$

Test conditions (Port Pi, $f(XIN)$)

- $V_{CC} = 5 V \pm 10 \%$
- Input timing voltage : $V_{IL} = 1.0 V$, $V_{IH} = 4.0 V$
- Output timing voltage : $V_{OL} = 0.8 V$, $V_{OH} = 2.0 V$, $C_L = 100 pF$

(when 3- ϕ access in low-speed running <Read>)



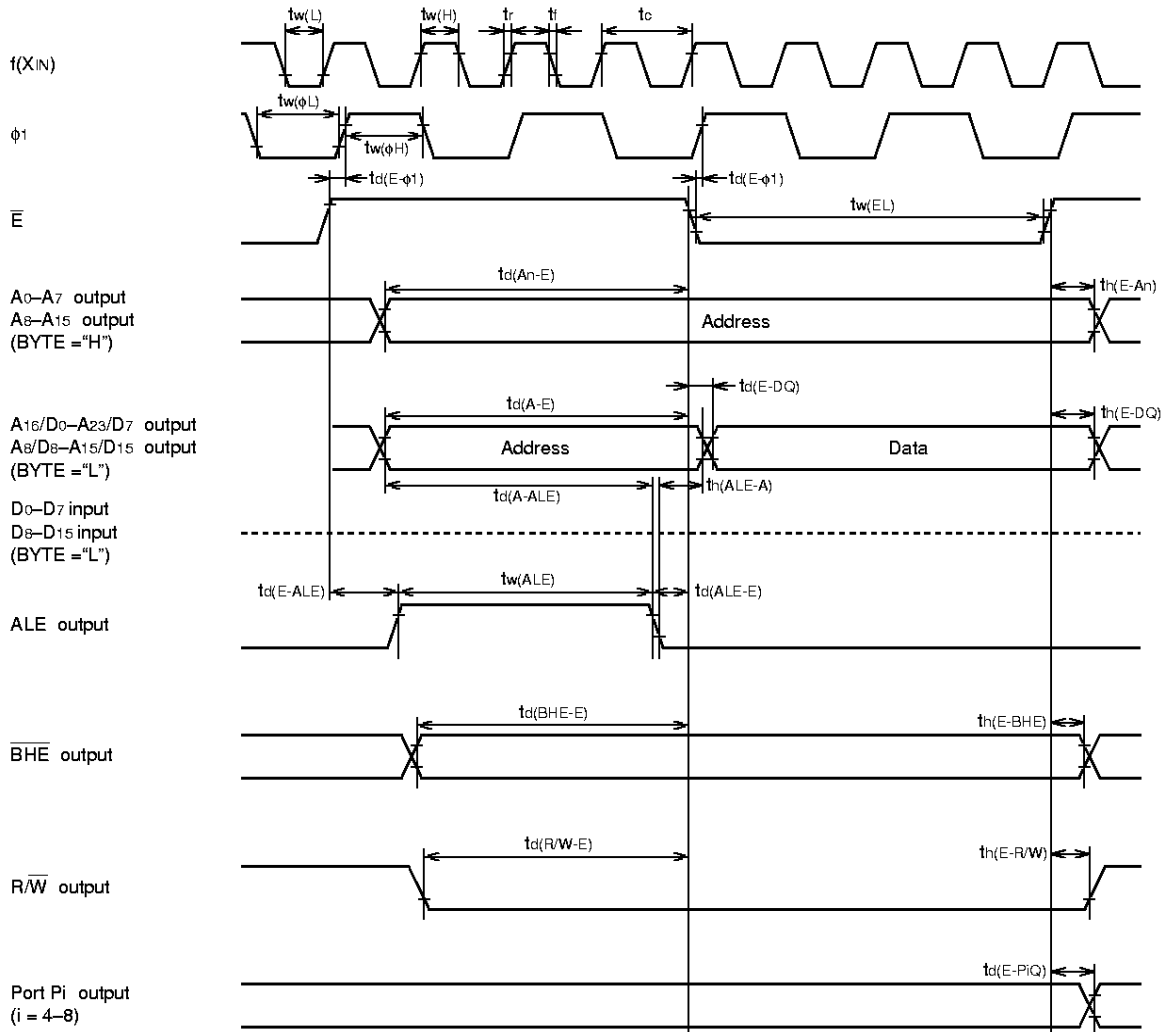
Test conditions (except Port Pi, $f(X_{iN})$)

- $V_{CC} = 5 V \pm 10 \%$
- Output timing voltage : $V_{OL} = 0.8 V$, $V_{OH} = 2.0 V$, $C_L = 100 pF$
- Data input : $V_{IL} = 0.8 V$, $V_{IH} = 2.5 V$

Test conditions (Port Pi, $f(X_{iN})$)

- $V_{CC} = 5 V \pm 10 \%$
- Input timing voltage : $V_{IL} = 1.0 V$, $V_{IH} = 4.0 V$
- Output timing voltage : $V_{OL} = 0.8 V$, $V_{OH} = 2.0 V$, $C_L = 100 pF$

(when 4- ϕ access in low-speed running <Write>)



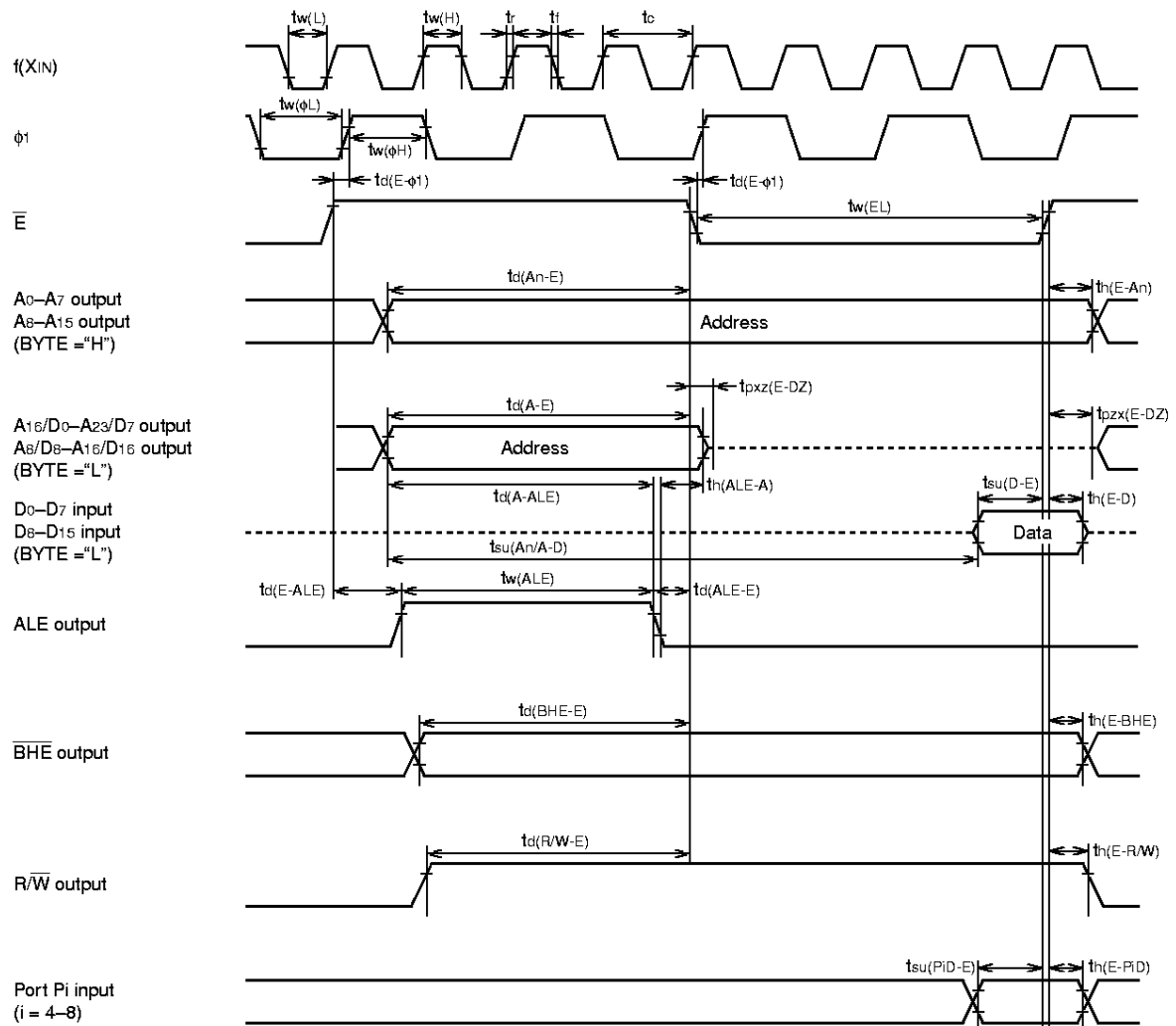
Test conditions (except Port Pi, $f(XIN)$)

- $V_{CC} = 5V \pm 10\%$
- Output timing voltage : $V_{OL} = 0.8V$, $V_{OH} = 2.0V$, $C_L = 100pF$
- Data input : $V_{IL} = 0.8V$, $V_{IH} = 2.5V$

Test conditions (Port Pi, $f(XIN)$)

- $V_{CC} = 5V \pm 10\%$
- Input timing voltage : $V_{IL} = 1.0V$, $V_{IH} = 4.0V$
- Output timing voltage : $V_{OL} = 0.8V$, $V_{OH} = 2.0V$, $C_L = 100pF$

(when 4- ϕ access in low-speed running <Read>)



Test conditions (except Port Pi, $f(X_{IN})$)

- $V_{CC} = 5 V \pm 10 \%$
- Output timing voltage : $V_{OL} = 0.8 V$, $V_{OH} = 2.0 V$, $C_L = 100 pF$
- Data input : $V_{IL} = 0.8 V$, $V_{IH} = 2.5 V$

Test conditions (Port Pi, $f(X_{IN})$)

- $V_{CC} = 5 V \pm 10 \%$
- Input timing voltage : $V_{IL} = 1.0 V$, $V_{IH} = 4.0 V$
- Output timing voltage : $V_{OL} = 0.8 V$, $V_{OH} = 2.0 V$, $C_L = 100 pF$

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

Timing requirements ($V_{CC} = 5 V \pm 10\%$, $V_{SS} = 0 V$, $T_a = -20$ to $85\text{ }^\circ\text{C}$, $f(XIN) = 40\text{ MHz}$ when the clock source select bit = "0"* , unless otherwise noted)

* The rise and fall time of input signal must be 100 ns or less respectively, unless otherwise noted.

Memory expansion and Microprocessor mode : High-speed running

Symbol	Parameter	Limits		Unit
		Min.	Max.	
t_c	External clock input cycle time (Note 1)	25		ns
$t_{w(H)}$	External clock input high-level pulse width (Note 2)	$t_c/2 - 8$		ns
$t_{w(L)}$	External clock input low-level pulse width (Note 2)	$t_c/2 - 8$		ns
t_r	External clock rise time		8	ns
t_f	External clock fall time		8	ns
$t_{su(D-E)}$	Input setup time	30		ns
$t_{su(PiD-E)}$	Port Pi input setup time (i = 4—8)	60		ns
$t_{h(E-D)}$	Data input hold time	0		ns
$t_{h(E-PiD)}$	Port Pi input hold time (i = 4—8)	0		ns
$t_{su(A_n/A-D)}$	Data setup time with address stabilized (Note 3)		50 (3- ϕ access)	ns
			100 (4- ϕ access)	
			150 (5- ϕ access)	

*: $f(XIN) = 20\text{ MHz}$ when the clock source select bit = "1"

Notes 1: When the clock source select bit = "1", t_c 's minimum limit is 50 ns.

2: When the clock source select bit = "1", set $t_{w(H)}/t_c$ and $t_{w(L)}/t_c$ ratios to 45 to 55 %.

3: Since the values depend on external clock input frequency $f(XIN)$, calculate them using the bus timing data formula on the page after the next page.

PRELIMINARY
Notice: This is not a final specification.
Some parametric limits are subject to change.

SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

Switching characteristics ($V_{CC} = 5 V \pm 10\%$, $V_{SS} = 0 V$, $T_a = -20$ to $85\text{ }^\circ\text{C}$, $f(XIN) = 40\text{ MHz}$ when the clock source select bit = "0"*[†], unless otherwise noted)

Memory expansion and Microprocessor mode : High-speed running

Symbol	Parameter	3- ϕ access		4- ϕ access		5- ϕ access		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_w(\phi H), t_w(\phi L)$	ϕ high-level pulse width, ϕ low-level pulse width (Note)	5		5		5		ns
$t_d(E-\phi 1)$	$\phi 1$ output delay time	-12	7	-12	7	-12	7	ns
$t_w(EL)$	\bar{E} low-level pulse width (Note)	50		75		125		ns
$t_d(A_n-E)$	Address output delay time (Note)	15		40		40		ns
$t_d(E-DQ)$	Data output delay time		35		35		35	ns
$t_{pxz}(E-DZ)$	Floating start delay time		5		5		5	ns
$t_d(A-E)$	Address output delay time (Note)	15		40		40		ns
$t_d(A-ALE)$	Address output delay time (Note)	5		30		30		ns
$t_d(E-ALE)$	ALE output delay time (Note)	10		10		10		ns
$t_d(ALE-E)$	ALE output delay time (Note)	4		4		4		ns
$t_w(ALE)$	ALE pulse width (Note)	10		35		35		ns
$t_d(BHE-E)$	\bar{BHE} output delay time (Note)	20		45		45		ns
$t_d(R/\bar{W}-E)$	R/\bar{W} output delay time (Note)	20		45		45		ns
$t_h(E-A_n)$	Address hold time (Note)	10		10		10		ns
$t_h(ALE-A)$	Address hold time (Note)	10		10		10		ns
$t_h(E-DQ)$	Data hold time (Note)	15		15		15		ns
$t_{PZX}(E-DZ)$	Floating release delay time (Note)	15		15		15		ns
$t_h(E-BHE)$	\bar{BHE} hold time (Note)	10		10		10		ns
$t_h(E-R/\bar{W})$	R/\bar{W} hold time (Note)	10		10		10		ns
$t_d(E-P_iQ)$	Port Pi data output delay time ($i = 4-8$)		60		60		60	ns

*: $f(XIN) = 20\text{ MHz}$ when the clock source select bit = "1"

Note: Since the values depend on external clock frequency $f(XIN)$, calculate them by using the bus timing data formulas on the next page.

PRELIMINARY
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SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

Bus timing data formulas

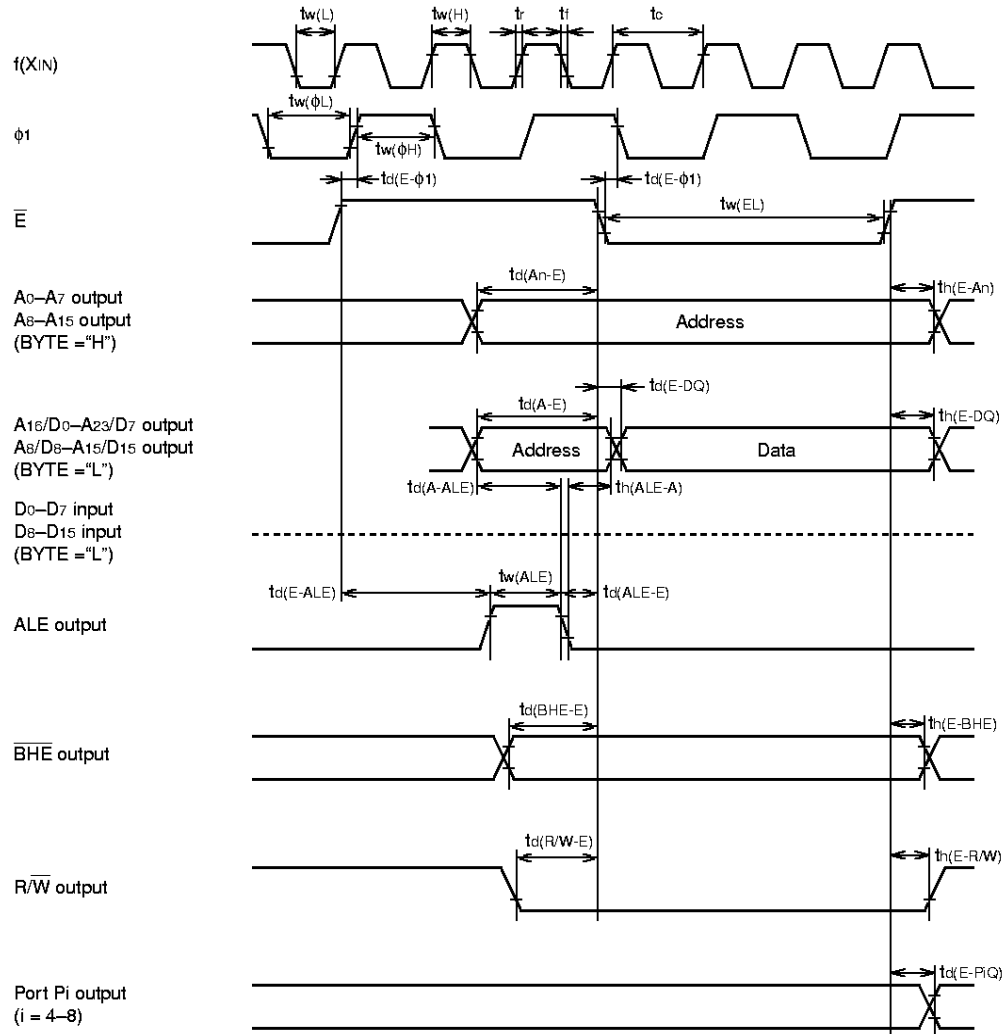
Memory expansion and Microprocessor mode : High-speed running ($V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V$, $T_a = -20$ to $85^\circ C$, $f(XIN) \leq 40$ MHz when the clock source select bit = "0"*, unless otherwise noted)

Symbol	Parameter	3- ϕ access	4- ϕ access	5- ϕ access	Unit
$t_{su}(A_n/A-D)$	Data setup time with address stabilized	$\frac{5 \times 10^9}{f(XIN)} - 75$	$\frac{7 \times 10^9}{f(XIN)} - 75$	$\frac{9 \times 10^9}{f(XIN)} - 75$	ns
$tw(\phi H), tw(\phi L)$	ϕ high-level pulse width, ϕ low-level pulse width	$\frac{1 \times 10^9}{f(XIN)} - 20$	←	←	ns
$tw(EL)$	\bar{E} low-level pulse width	$\frac{3 \times 10^9}{f(XIN)} - 25$	$\frac{4 \times 10^9}{f(XIN)} - 25$	$\frac{6 \times 10^9}{f(XIN)} - 25$	ns
$td(A_n-E)$	Address output delay time	$\frac{2 \times 10^9}{f(XIN)} - 35$	$\frac{3 \times 10^9}{f(XIN)} - 35$	←	ns
$td(A-E)$	Address output delay time	$\frac{2 \times 10^9}{f(XIN)} - 35$	$\frac{3 \times 10^9}{f(XIN)} - 35$	←	ns
$td(A-ALE)$	Address output delay time	$\frac{1 \times 10^9}{f(XIN)} - 20$	$\frac{2 \times 10^9}{f(XIN)} - 20$	←	ns
$td(E-ALE)$	ALE output delay time	$\frac{1 \times 10^9}{f(XIN)} - 15$	←	←	ns
$tw(ALE)$	ALE pulse width	$\frac{1 \times 10^9}{f(XIN)} - 15$	$\frac{2 \times 10^9}{f(XIN)} - 15$	←	ns
$td(BHE-E)$	\bar{BHE} output delay time	$\frac{2 \times 10^9}{f(XIN)} - 30$	$\frac{3 \times 10^9}{f(XIN)} - 30$	←	ns
$td(R/\bar{W}-E)$	R/\bar{W} output delay time	$\frac{2 \times 10^9}{f(XIN)} - 30$	$\frac{3 \times 10^9}{f(XIN)} - 30$	←	ns
$th(E-A_n)$	Address hold time	$\frac{1 \times 10^9}{f(XIN)} - 15$	←	←	ns
$th(ALE-A)$	Address hold time	$\frac{1 \times 10^9}{f(XIN)} - 15$	←	←	ns
$th(E-DQ)$	Data hold time	$\frac{1 \times 10^9}{f(XIN)} - 10$	←	←	ns
$tpzx(E-DZ)$	Floating release delay time	$\frac{1 \times 10^9}{f(XIN)} - 10$	←	←	ns
$td(E-BHE)$	\bar{BHE} hold time	$\frac{1 \times 10^9}{f(XIN)} - 15$	←	←	ns
$td(E-R/\bar{W})$	R/\bar{W} hold time	$\frac{1 \times 10^9}{f(XIN)} - 15$	←	←	ns

*: $f(XIN) \leq 20$ MHz when the clock source select bit = "1"

Note: When the clock source select bit is "1", regard $f(XIN)$ in tables as $2 \cdot f(XIN)$.

(when 3- ϕ access in high-speed running <Write>)



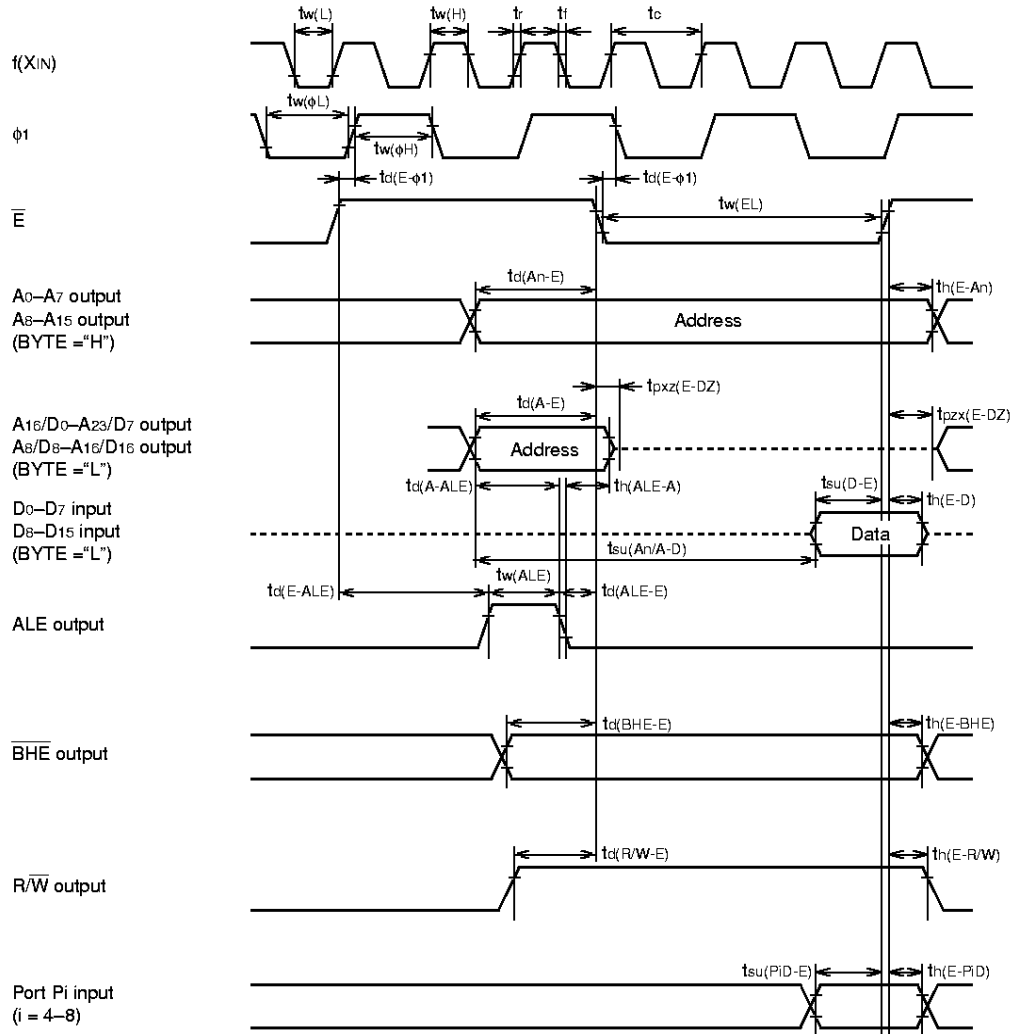
Test conditions (except Port Pi, f(XIN))

- $V_{CC} = 5 V \pm 10 \%$
- Output timing voltage : $V_{OL} = 0.8 V$, $V_{OH} = 2.0 V$, $C_L = 100 pF$
- Data input : $V_{IL} = 0.8 V$, $V_{IH} = 2.5 V$

Test conditions (Port Pi, f(XIN))

- $V_{CC} = 5 V \pm 10 \%$
- Input timing voltage : $V_{IL} = 1.0 V$, $V_{IH} = 4.0 V$
- Output timing voltage : $V_{OL} = 0.8 V$, $V_{OH} = 2.0 V$, $C_L = 100 pF$

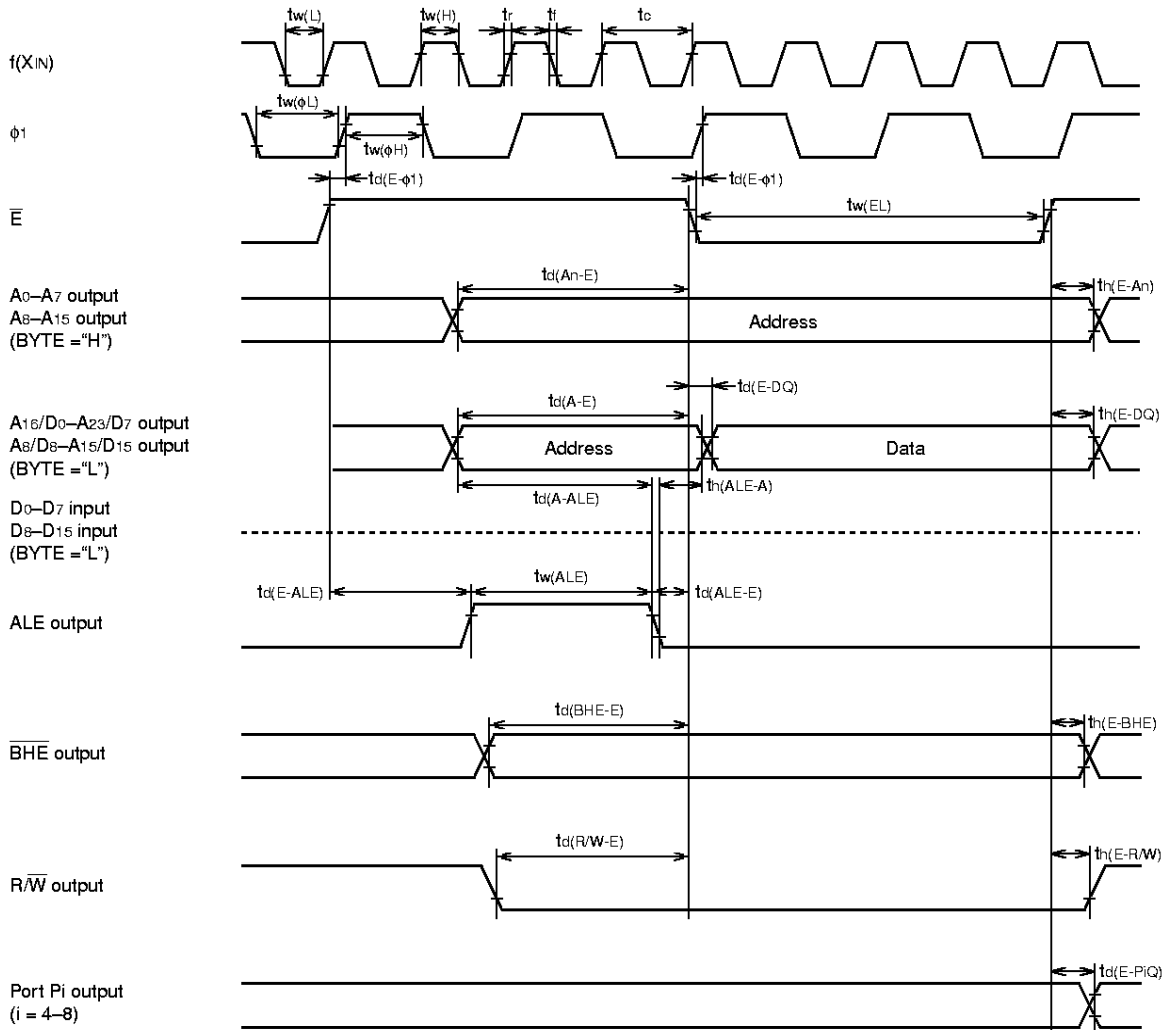
(when 3- ϕ access in high-speed running <Read>)



- Test conditions (except Port Pi, $f(XIN)$)
- $V_{CC} = 5 V \pm 10\%$
 - Output timing voltage : $V_{OL} = 0.8 V$, $V_{OH} = 2.0 V$, $C_L = 100 pF$
 - Data input : $V_{IL} = 0.8 V$, $V_{IH} = 2.5 V$

- Test conditions (Port Pi, $f(XIN)$)
- $V_{CC} = 5 V \pm 10\%$
 - Input timing voltage : $V_{IL} = 1.0 V$, $V_{IH} = 4.0 V$
 - Output timing voltage : $V_{OL} = 0.8 V$, $V_{OH} = 2.0 V$, $C_L = 100 pF$

(when 4- ϕ access in high-speed running <Write>)



Test conditions (except Port Pi, f(XIN))

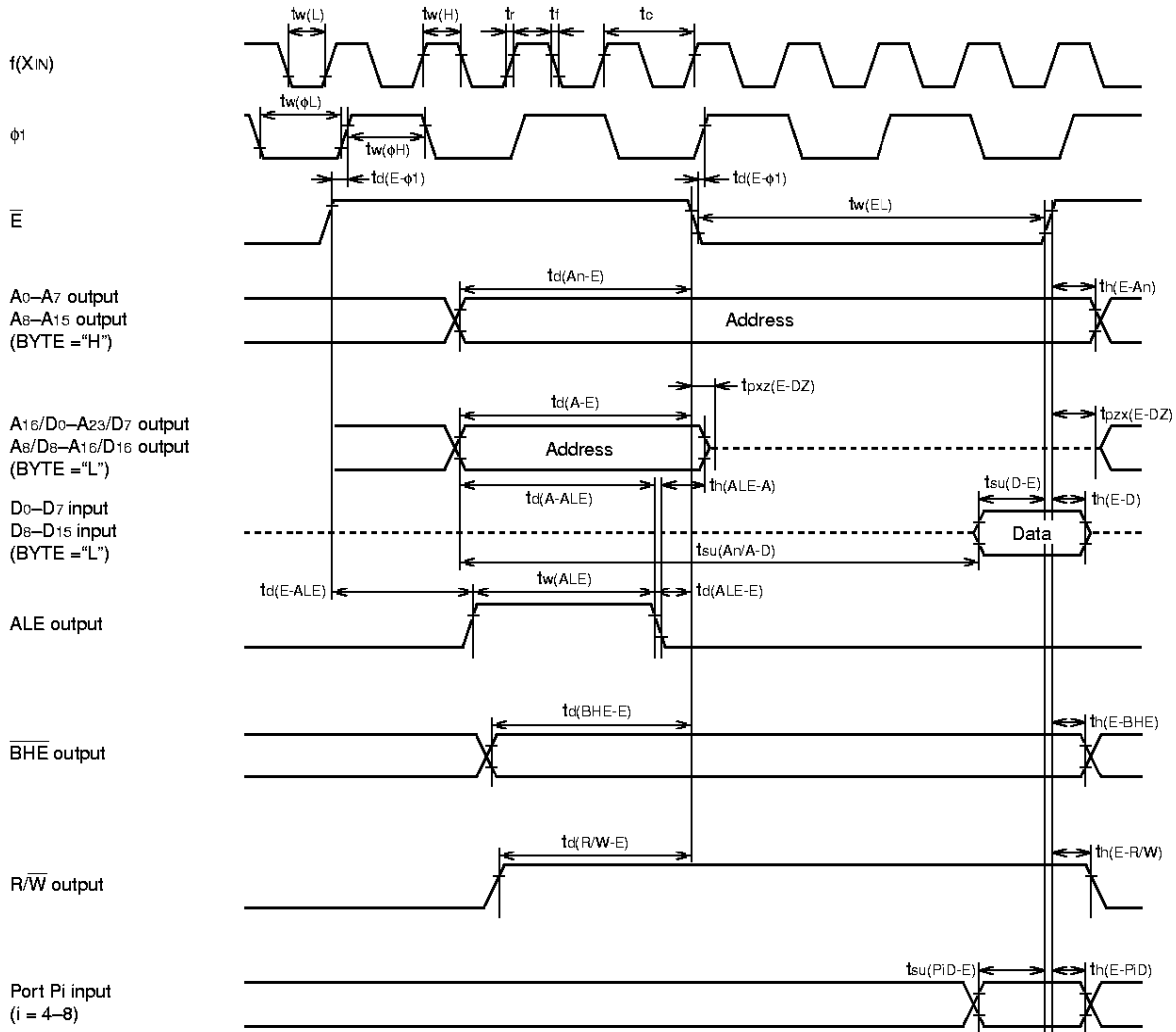
- $V_{CC} = 5 V \pm 10 \%$
- Output timing voltage : $V_{OL} = 0.8 V$, $V_{OH} = 2.0 V$, $C_L = 100 pF$
- Data input : $V_{IL} = 0.8 V$, $V_{IH} = 2.5 V$

Test conditions (Port Pi, f(XIN))

- $V_{CC} = 5 V \pm 10 \%$
- Input timing voltage : $V_{IL} = 1.0 V$, $V_{IH} = 4.0 V$
- Output timing voltage : $V_{OL} = 0.8 V$, $V_{OH} = 2.0 V$, $C_L = 100 pF$

PRELIMINARY
 Notice: This is not a final specification.
 Some parametric limits are subject to change.

(when 4- ϕ access in high-speed running <Read>)



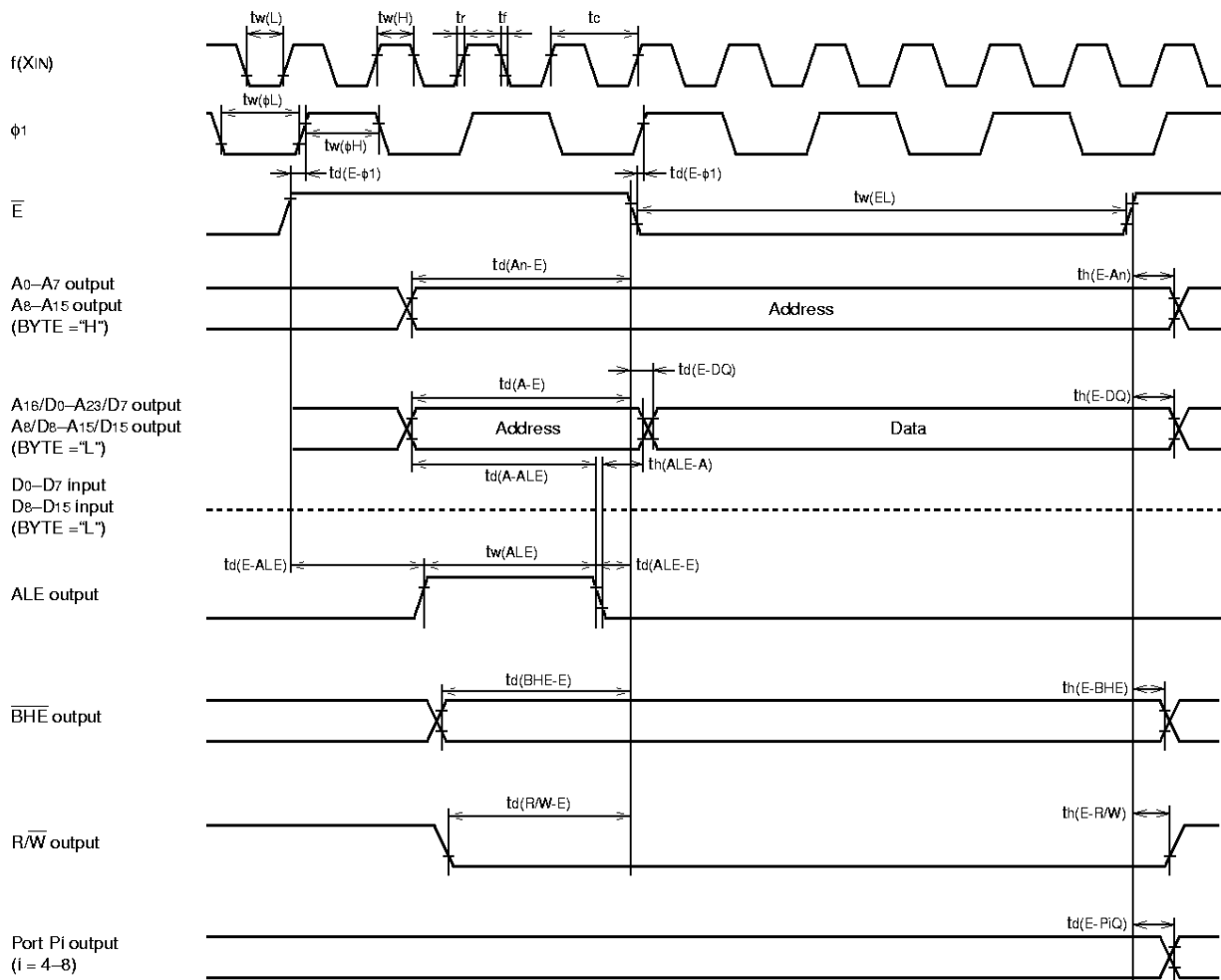
Test conditions (except Port Pi, f(XIN))

- $V_{CC} = 5 V \pm 10 \%$
- Output timing voltage : $V_{OL} = 0.8 V, V_{OH} = 2.0 V, C_L = 100 pF$
- Data input : $V_{IL} = 0.8 V, V_{IH} = 2.5 V$

Test conditions (Port Pi, f(XIN))

- $V_{CC} = 5 V \pm 10 \%$
- Input timing voltage : $V_{IL} = 1.0 V, V_{IH} = 4.0 V$
- Output timing voltage : $V_{OL} = 0.8 V, V_{OH} = 2.0 V, C_L = 100 pF$

(when 5- ϕ access in high-speed running <Write>)



Test conditions (except Port Pi, f(XIN))

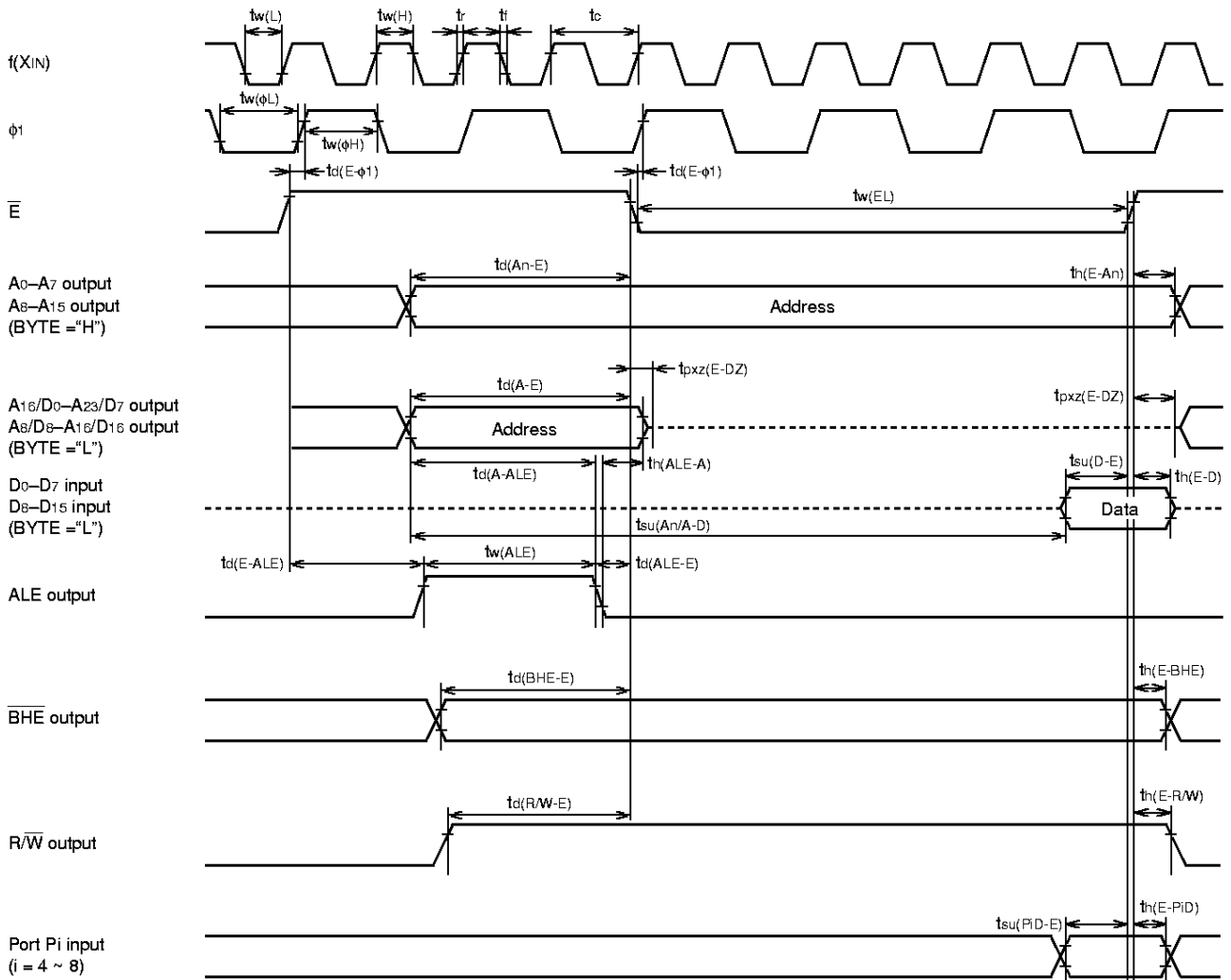
- VCC = 5 V \pm 10 %
- Output timing voltage : VOL = 0.8 V, VOH = 2.0 V, CL = 100 pF
- Data input : VIL = 0.8 V, VIH = 2.5 V

Test conditions (Port Pi, f(XIN))

- VCC = 5 V \pm 10 %
- Input timing voltage : VIL = 1.0 V, VIH = 4.0 V
- Output timing voltage : VOL = 0.8 V, VOH = 2.0 V, CL = 100 pF

PRELIMINARY
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(when 5-φ access in high-speed running <Read>)



Test conditions (except Port Pi, $f(XIN)$)

- $V_{CC} = 5 V \pm 10 \%$
- Output timing voltage : $V_{OL} = 0.8 V, V_{OH} = 2.0 V, C_L = 100 pF$
- Data input : $V_{IL} = 0.8 V, V_{IH} = 2.5 V$

Test conditions (Port Pi, $f(XIN)$)

- $V_{CC} = 5 V \pm 10 \%$
- Input timing voltage : $V_{IL} = 1.0 V, V_{IH} = 4.0 V$
- Output timing voltage : $V_{OL} = 0.8 V, V_{OH} = 2.0 V, C_L = 100 pF$

PRELIMINARY
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SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

<NOTE> External bus timing when internal memory area is accessed (2-φ access) in high-speed running

(VCC = 5 V ± 10 %, VSS = 0 V, Ta = -20 to 85 °C, f(XIN) ≤ 40 MHz when the clock source select bit = "0"*)

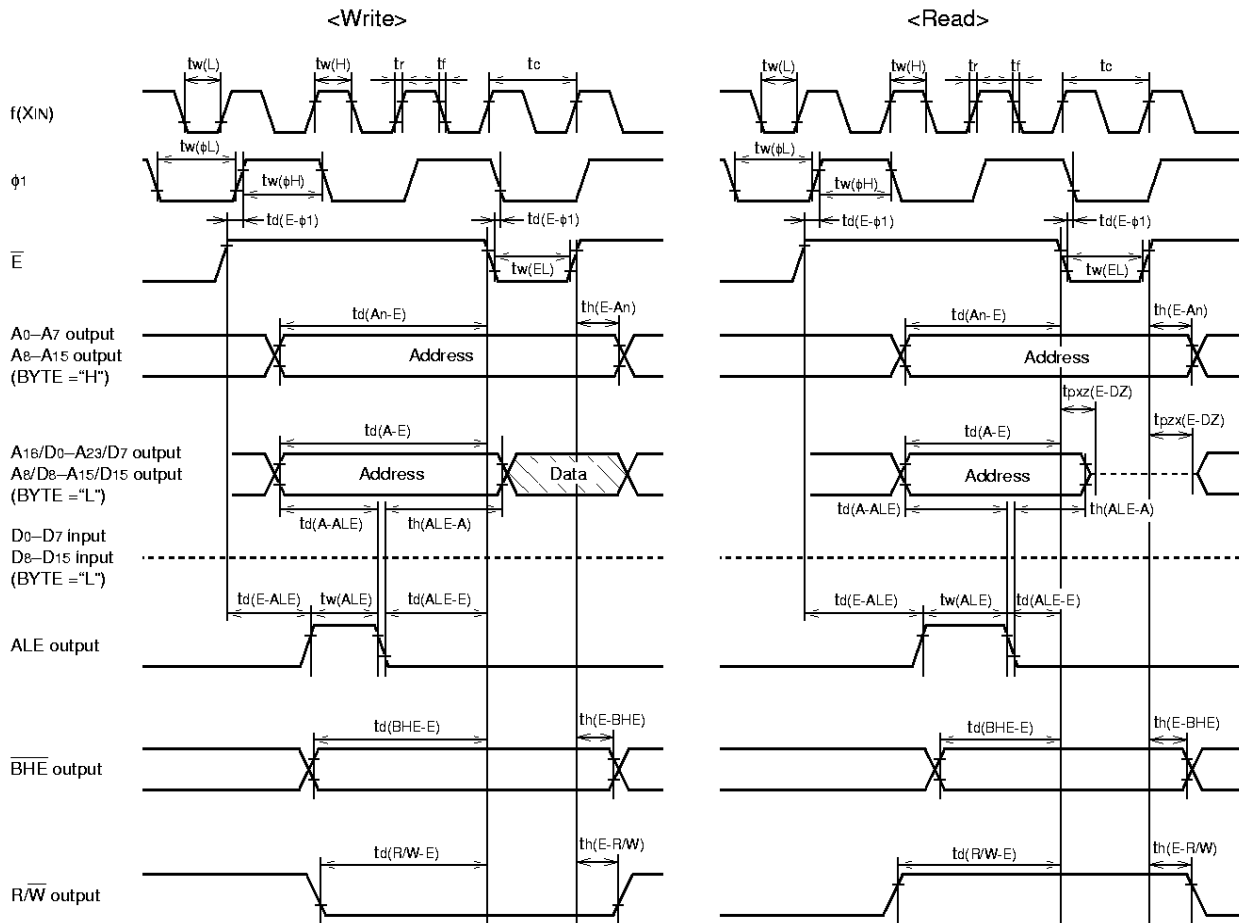
Symbol	Parameter	Limits		Bus timing data formula	Unit
		Min.	Max.		
tw(φH), tw(φL)	φ high-level pulse width, φ low-level pulse width	5		$\frac{1 \times 10^9}{f(XIN)} - 20$	ns
td(E-φ1)	φ1 output delay time	-12	7	————	ns
tw(EL)	\bar{E} low-level pulse width	5		$\frac{1 \times 10^9}{f(XIN)} - 20$	ns
td(A _n -E)	Address output delay time	15		$\frac{2 \times 10^9}{f(XIN)} - 35$	ns
tpxz(E-DZ)	Floating start delay time (BYTE="L")		5	————	ns
td(A-E)	Address output delay time	15		$\frac{2 \times 10^9}{f(XIN)} - 35$	ns
td(A-ALE)	Address output delay time	5		$\frac{1 \times 10^9}{f(XIN)} - 20$	ns
td(E-ALE)	ALE output delay time	10		$\frac{1 \times 10^9}{f(XIN)} - 15$	ns
td(ALE-E)	ALE output delay time	4		————	ns
tw(ALE)	ALE pulse width	10		$\frac{1 \times 10^9}{f(XIN)} - 15$	ns
td(BHE-E)	\bar{BHE} output delay time	20		$\frac{2 \times 10^9}{f(XIN)} - 30$	ns
td(R/W-E)	$\overline{R/W}$ output delay time	20		$\frac{2 \times 10^9}{f(XIN)} - 30$	ns
th(E-A _n)	Address hold time	10		$\frac{1 \times 10^9}{f(XIN)} - 15$	ns
th(ALE-A)	Address hold time (BYTE="L")	10		$\frac{1 \times 10^9}{f(XIN)} - 15$	ns
tpzx(E-DZ)	Floating release delay time (BYTE="L")	15		$\frac{1 \times 10^9}{f(XIN)} - 10$	ns
td(E-BHE)	\bar{BHE} hold time	10		$\frac{1 \times 10^9}{f(XIN)} - 15$	ns
td(E-R/W)	$\overline{R/W}$ hold time	10		$\frac{1 \times 10^9}{f(XIN)} - 15$	ns

*: f(XIN) ≤ 20 MHz when the clock source select bit = "1".

PRELIMINARY
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SHINGLE-CHIP 16-BIT CMOS MICROCOMPUTER FLASH MEMORY VERSION

(External bus timing on internal RAM access (2- ϕ access) in high-speed running)



* The value of write data is undefined.

* Contents of external data bus cannot be read into the internal.

Test conditions

- VCC = 5 V ± 10 %
- Output timing voltage : VOL = 0.8 V, VOH = 2.0 V, CL = 100 pF

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REVISION DESCRIPTION LIST

M37754FFCGP, M37754FFCHP DATA SHEET

Rev. No.	Revision Description	Rev. date
1.0	First Edition	971031